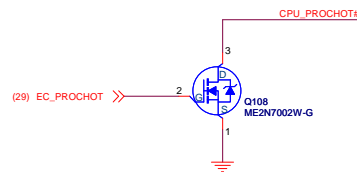
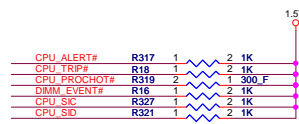
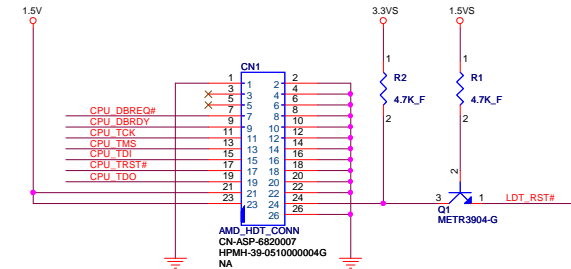


AMD Debug Termination

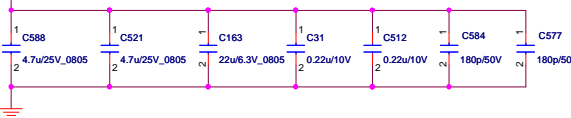
Signal Name	Type	Connection	Termination	Voltage
TEST6 TEST7 TEST8		Remain unconnected	-	
TEST9	I	Tie to VSS	-	VSS
TEST10		S1g2: Leave unconnected	-	
		S1g3: Pulled up to VLDT (0603 DNI)	-	
TEST12		Test point access required for scan function. Connection to scan header preferred but not required.	1 K Ω to VSS No pop	VSS
TEST14 TEST15 TEST16 TEST17		Test point access required, header is preferred	-	-
TEST18			1 K Ω to VSS No pop	VSS
TEST19			1 K Ω to VSS No pop	VSS
TEST20		Test point access required for scan function. Connection to scan header preferred but not required.	300 Ω ⁶	VSS
TEST21			300 Ω ⁶	VSS
TEST22			1 K Ω to VSS No pop	VSS
TEST23			300 Ω ⁶	VSS
TEST24	I	Test point access required for scan function. Connection to scan header preferred but not required.	300 Ω ⁶	VSS
TEST25_H			510 Ω ⁶	VSS
TEST25_L			510 Ω ⁶	VDDIO
TEST27 TEST28_H TEST28_L TEST29_H TEST29_L		Need test point on board	-	-



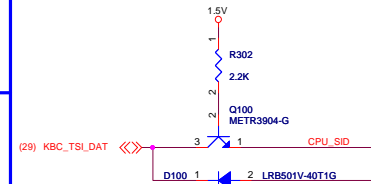
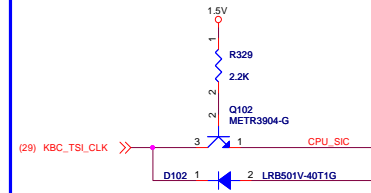
HDT Header



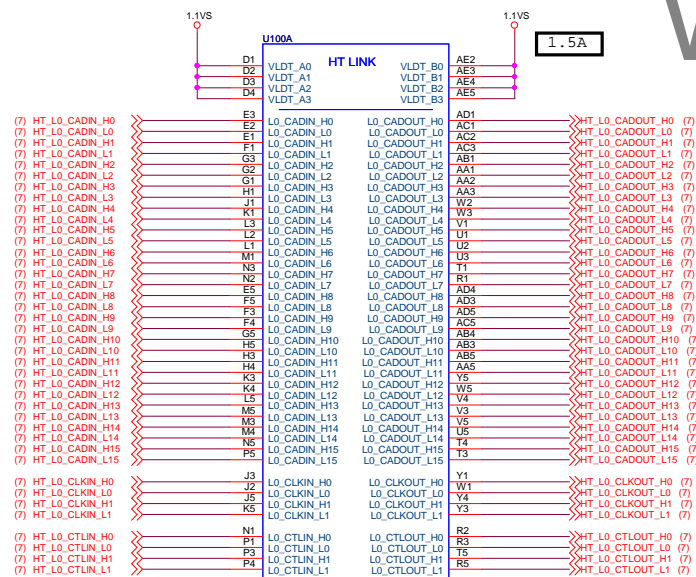
Place close to socket



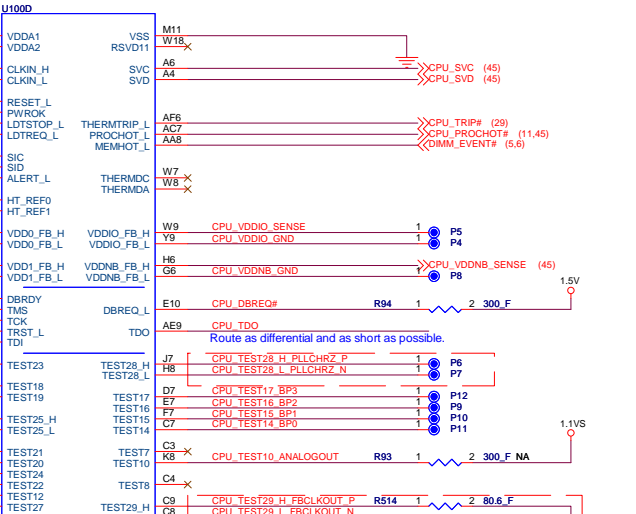
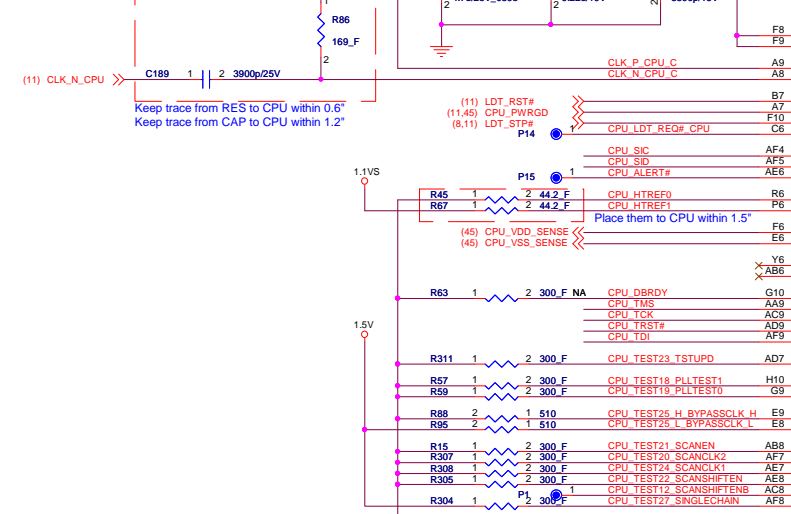
TSI Function



CPU HT/ MISC



www.aitech.ru



SVC	SVD	(CPU/VRM_PRO# = VCC/GND)	VCC/ GND	OPEN
0	0	1.1	1.1	
0	1	1.0	1.2	
1	0	0.9	1.0	
1	1	0.8	0.8	

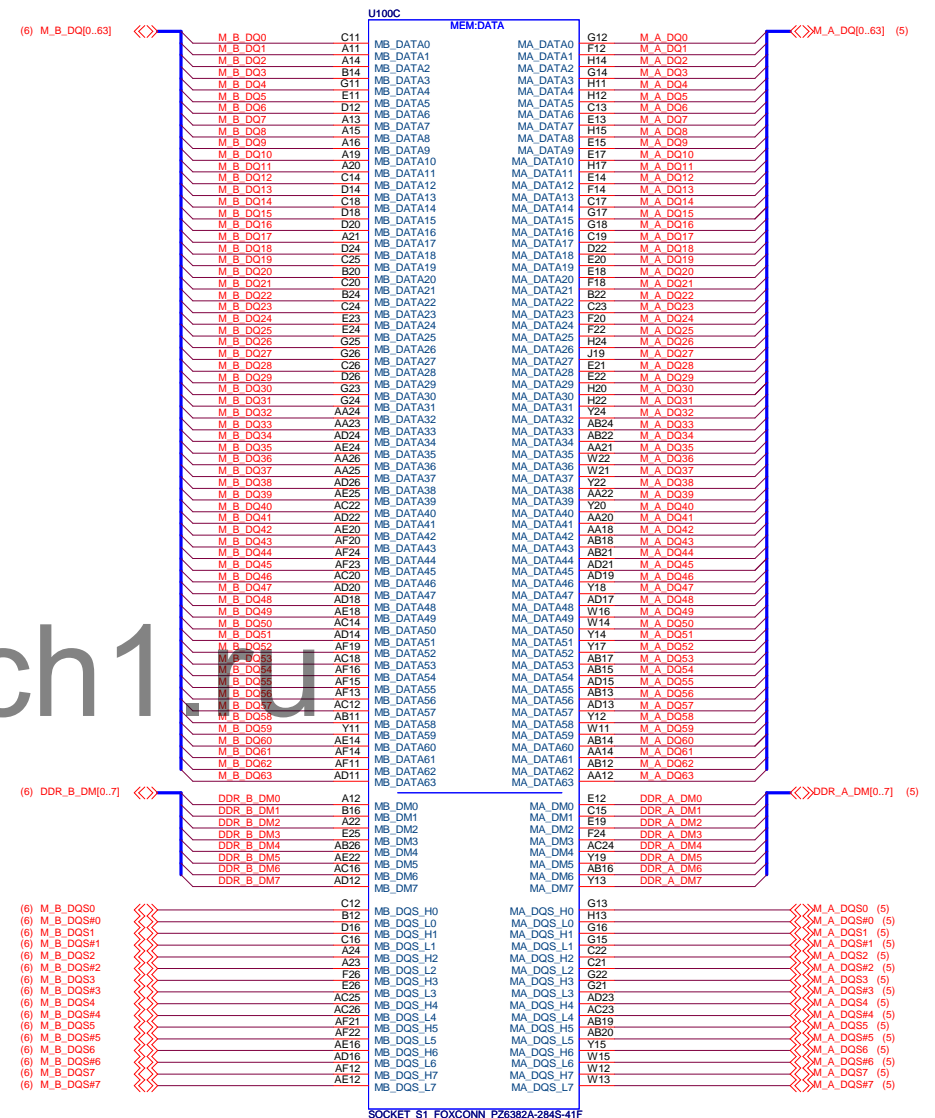
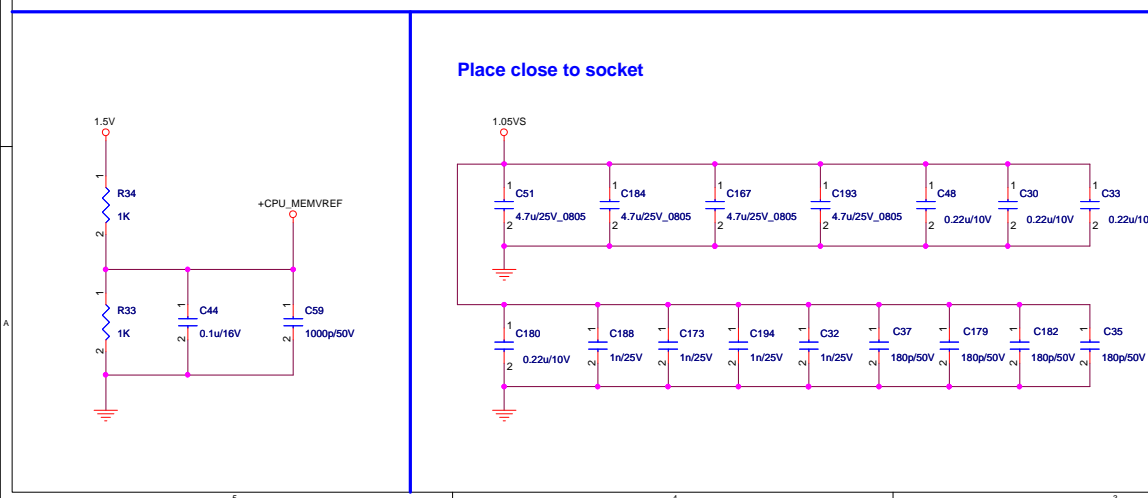
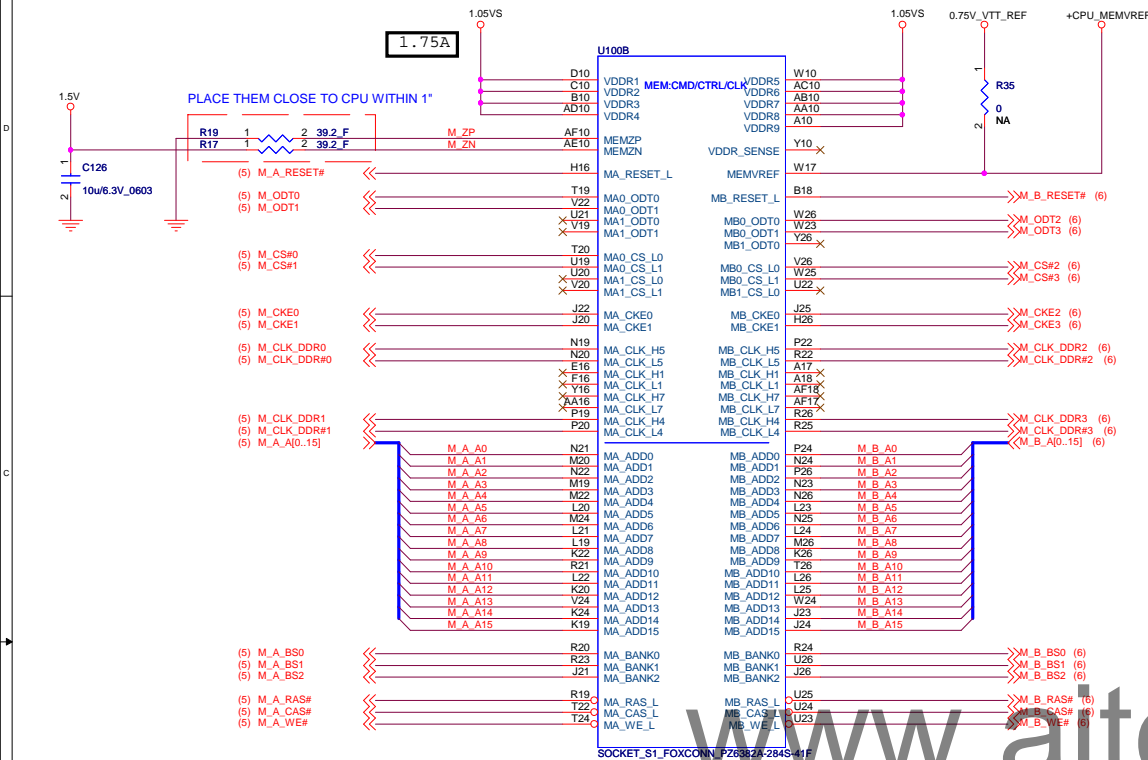
FLEX Computing

Project Name: H510UA1 Title: CPU - HT/ MISC I/F

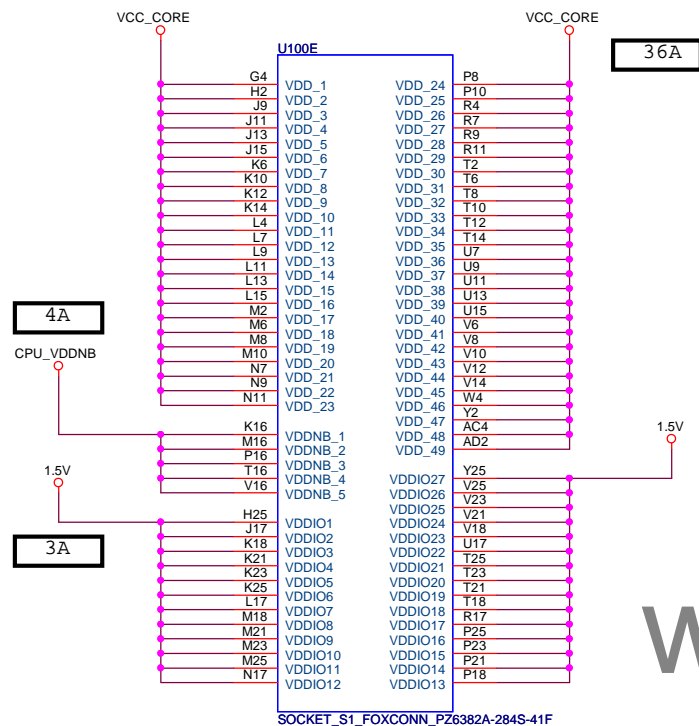
Size: Document Number: HPMH-40GAB6300-D Rev: D

Date: Thursday, December 30, 2010 Sheet: 2 of 51

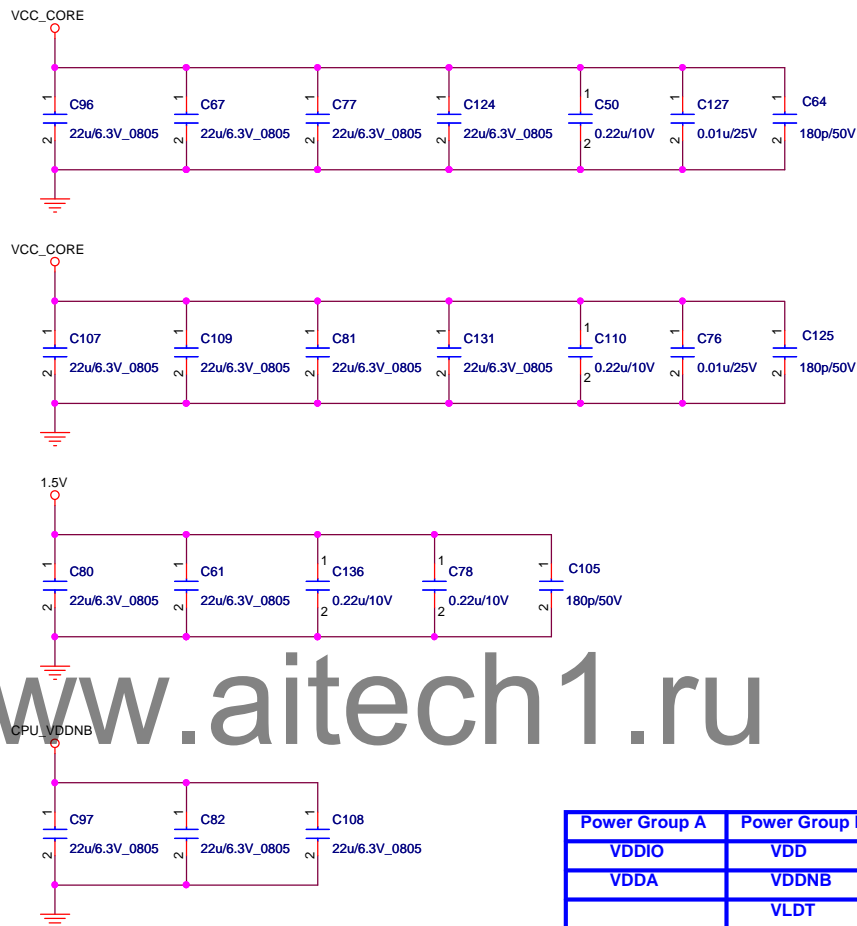
CPU Memory



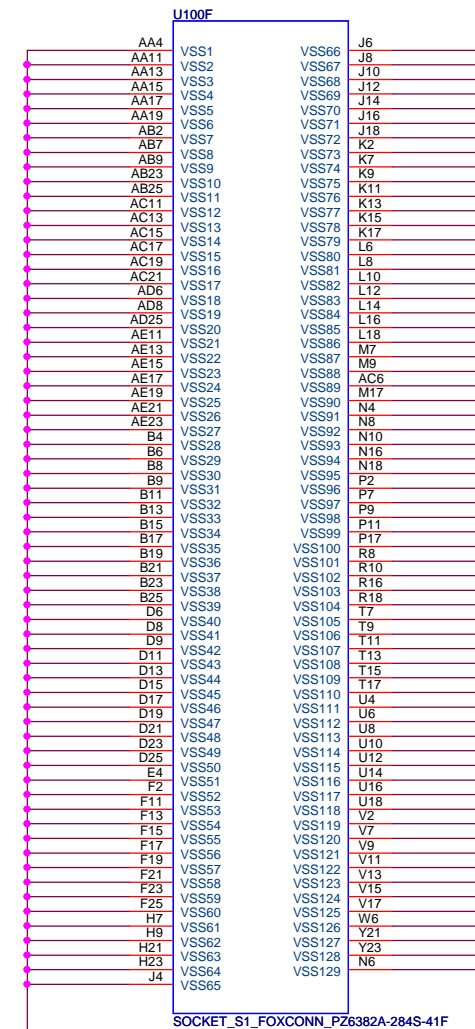
CPU PWR



BOTTOM SIDE DECOUPLING

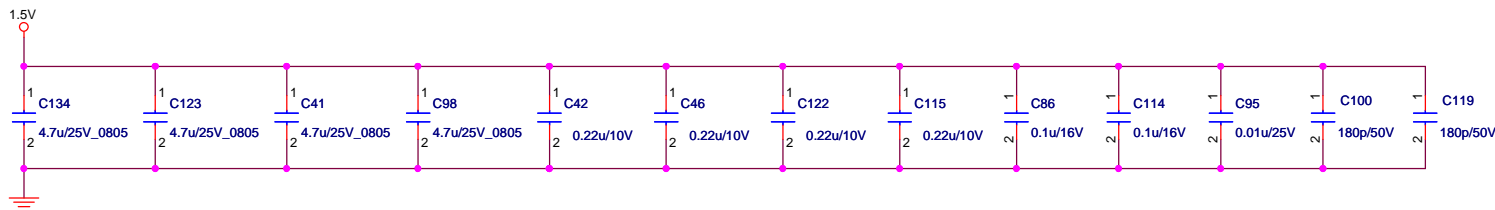


CPU GND



DECOUPLING BETWEEN PROCESSOR AND DIMMs

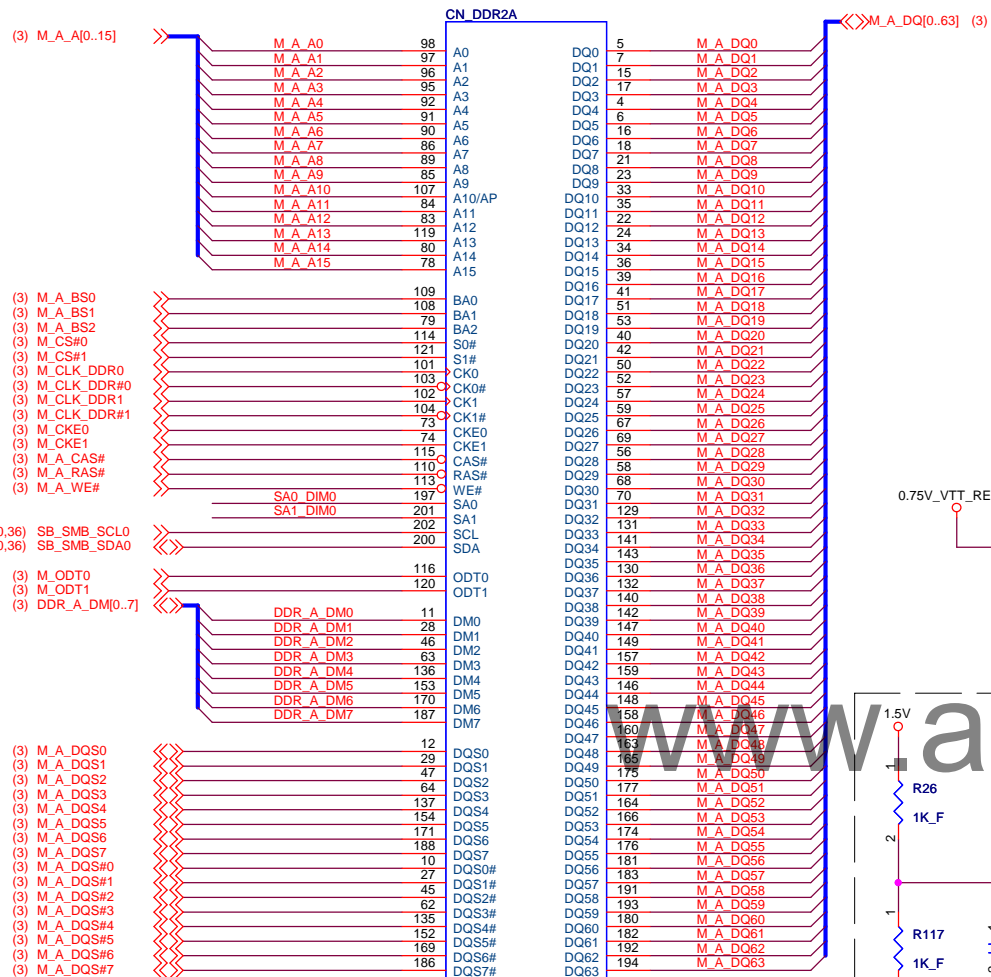
PLACE CLOSE TO PROCESSOR AS POSSIBLE



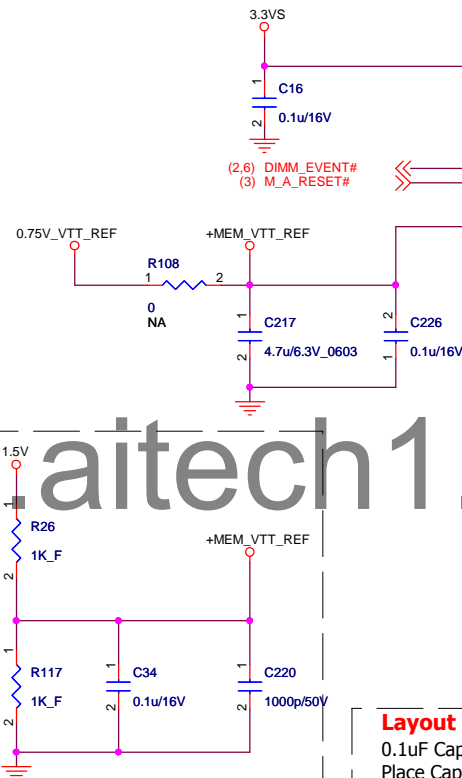
FLEXComputing

Project Name : H510UA1		Title : CPU - PWR/ GND	
Size :	Document Number :	HPMH-40GAB6300-D	
Date : Thursday, December 30, 2010		Rev : D	Sheet : 4 of 51

MEM CH-A

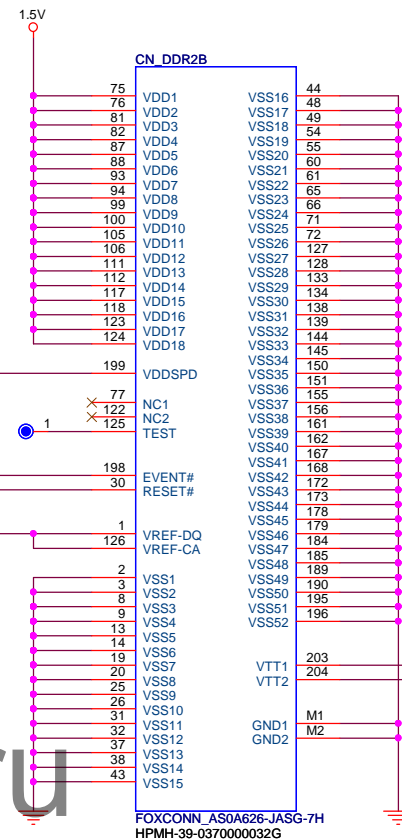


FOXCONN_AS0A626-JASG-7H
HPMH-39-0370000032G



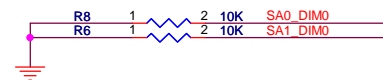
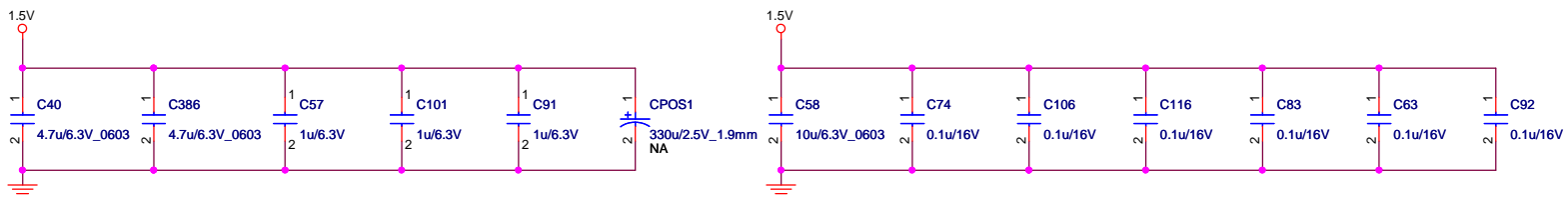
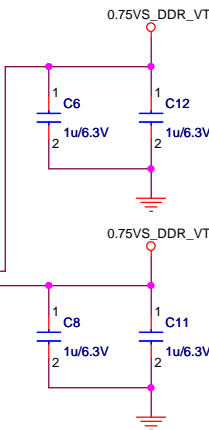
Layout

0.1uF Caps for CMD,CLK,CTRL return path
Place Caps on the same side as SO-DIMM
and close to VDD Pin .



Layout

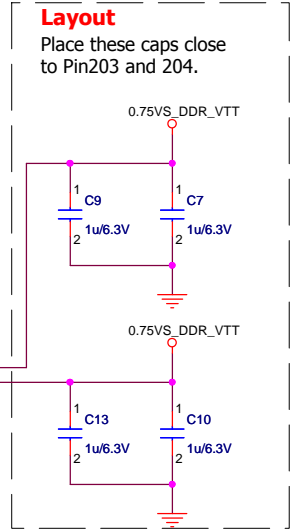
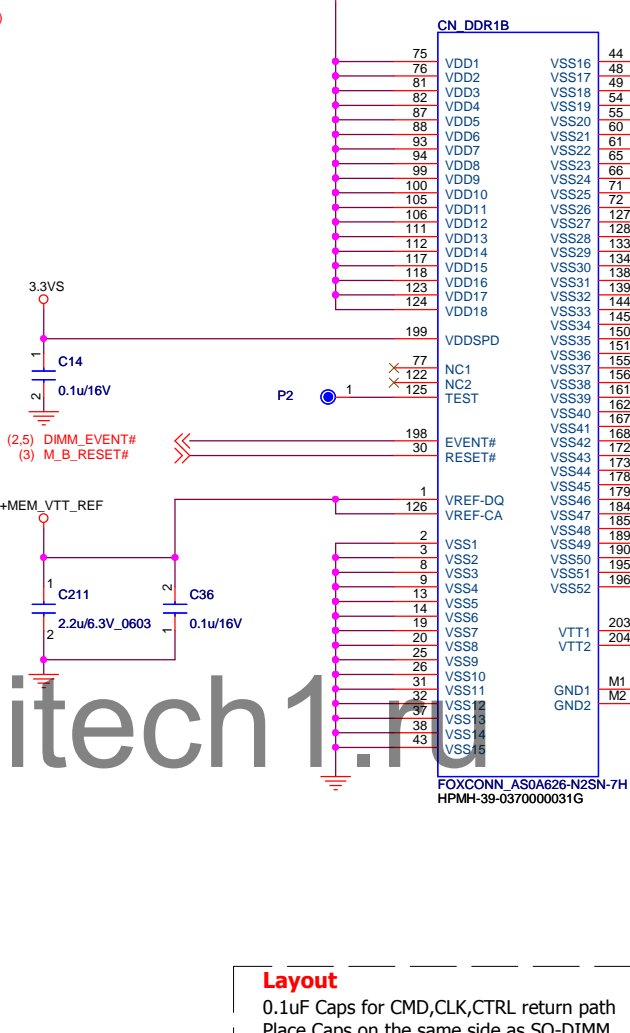
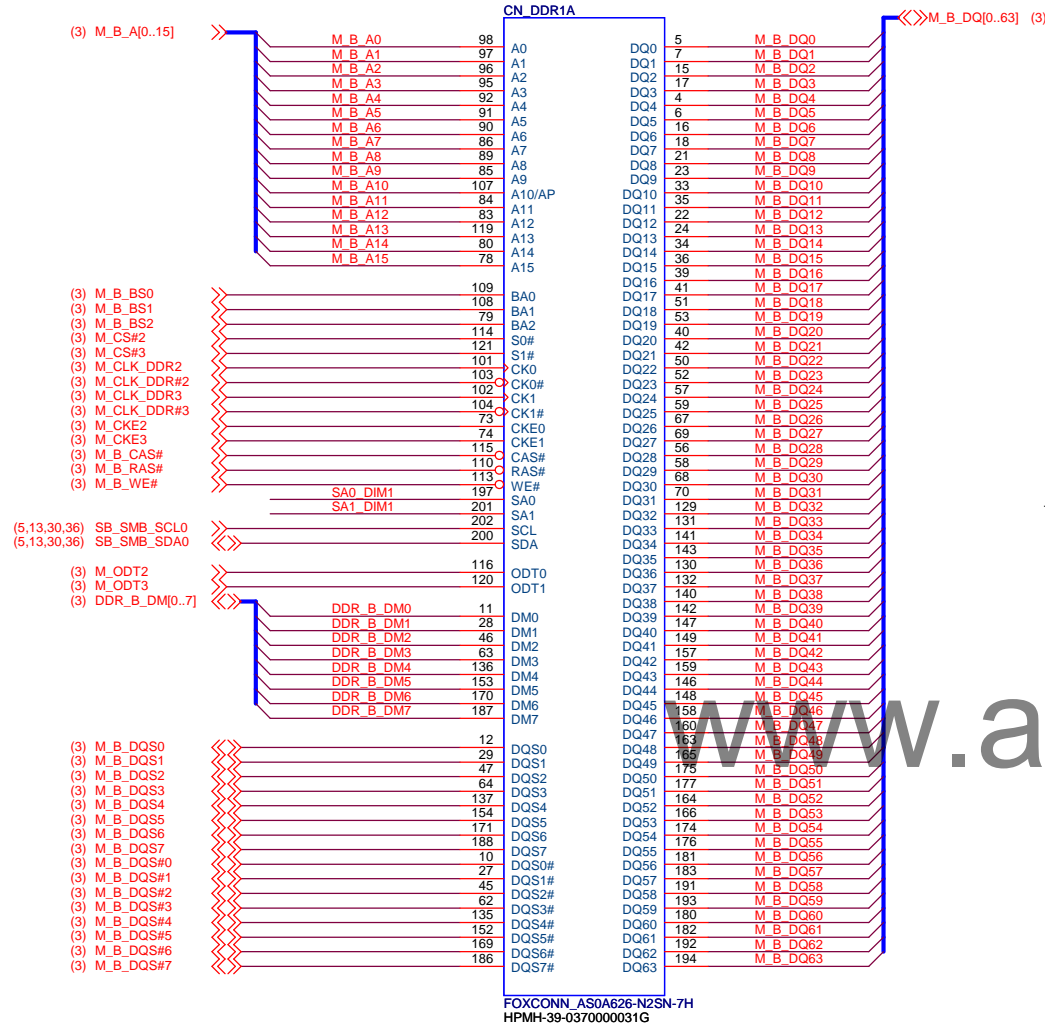
Place these caps close
to Pin203 and 204.



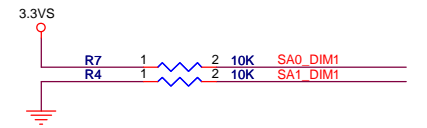
FLEX Computing

Project Name :	H510UA1	Title :	SO-DIMM Channel - A
Size :	Document Number :	Rev :	D
	HPMH-40GAB6300-D		
Date :	Thursday, December 30, 2010	Sheet :	5 of 51

MEM CH-B

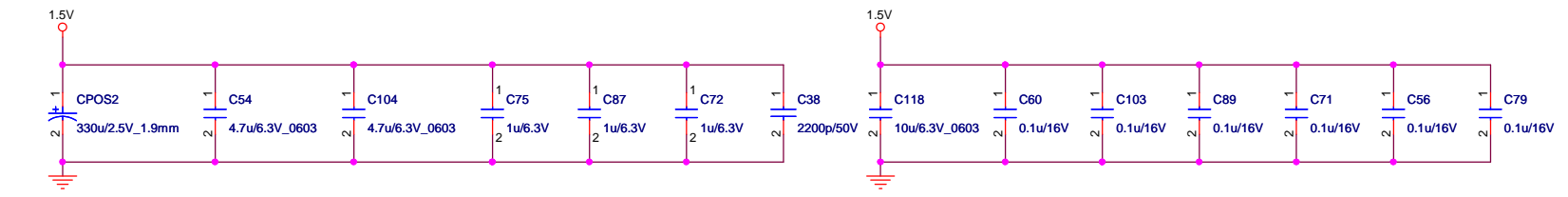


Layout
0.1uF Caps for CMD,CLK,CTRL return path
Place Caps on the same side as SO-DIMM and close to VDD Pin .

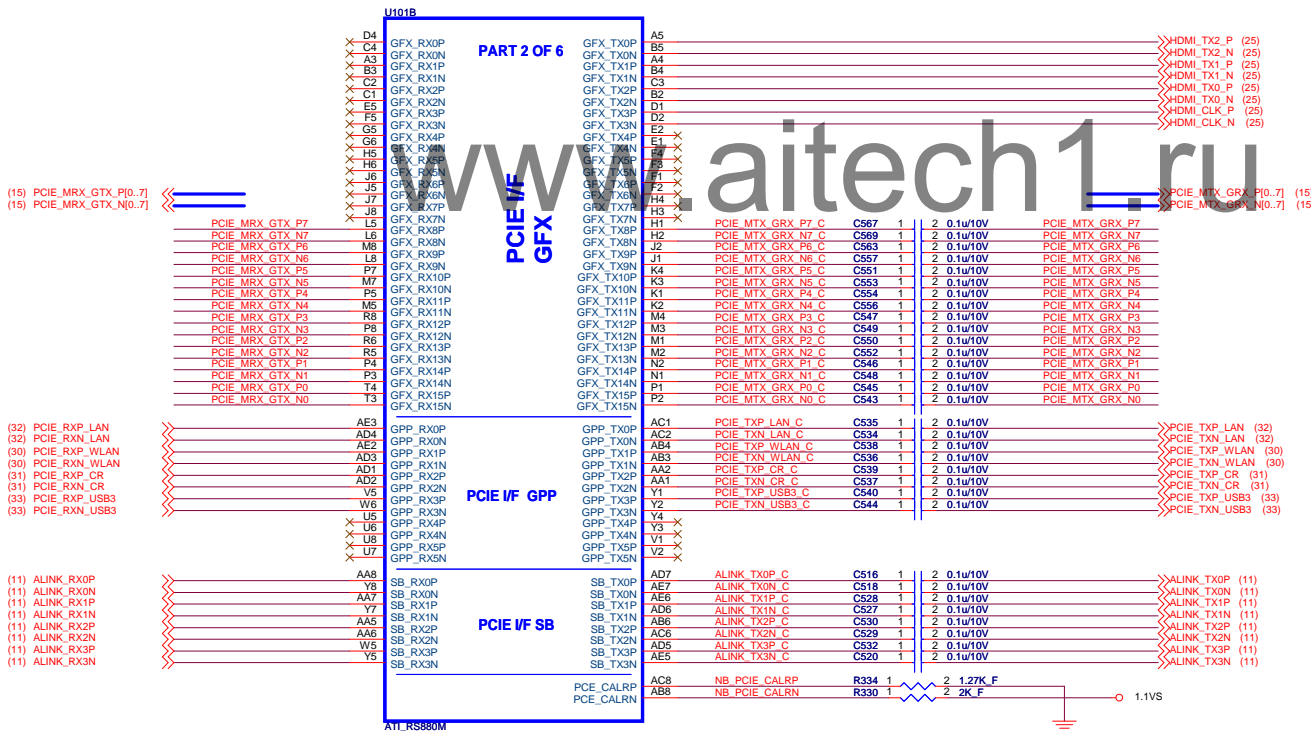
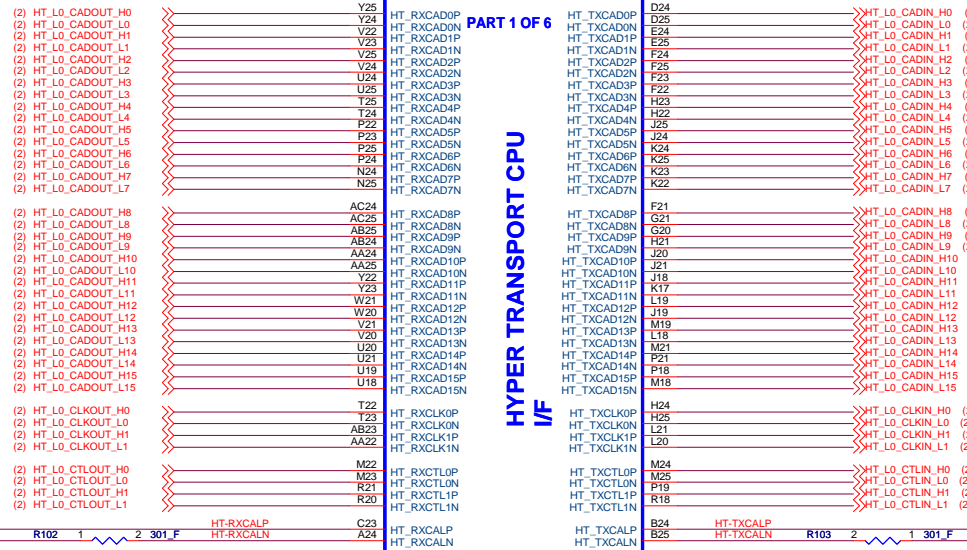


FLEXComputing

Project Name : H510UA1	Title : SO-DIMM Channel - B
Size : Document Number : HPMH-40GAB6300-D	Rev : D
Date : Thursday, December 30, 2010	Sheet : 6 of 51



NB HT/ PCIE



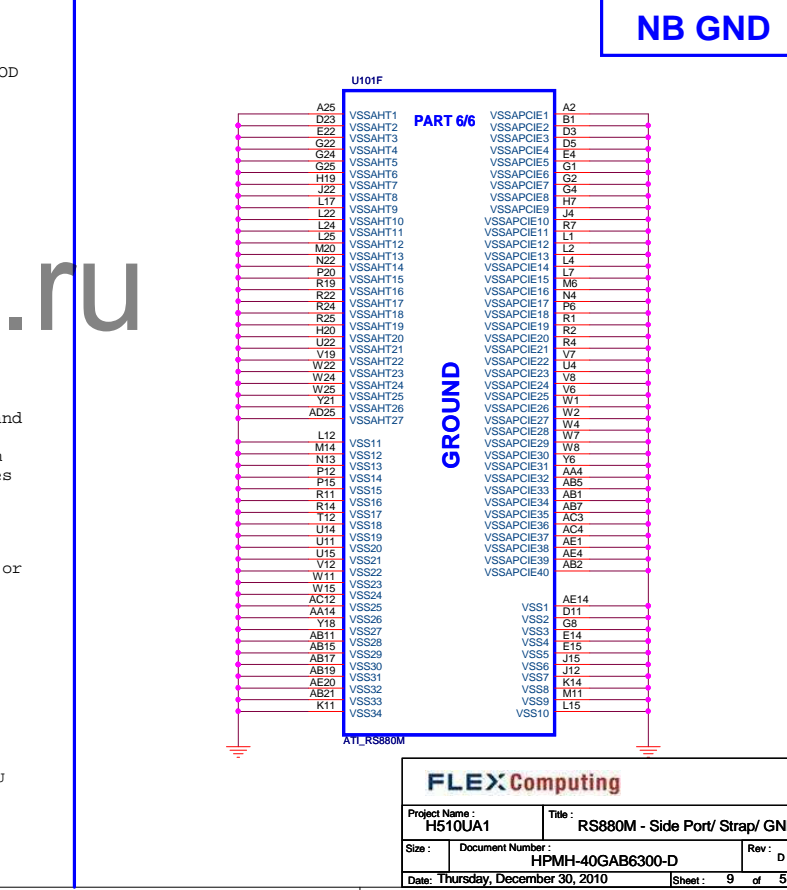
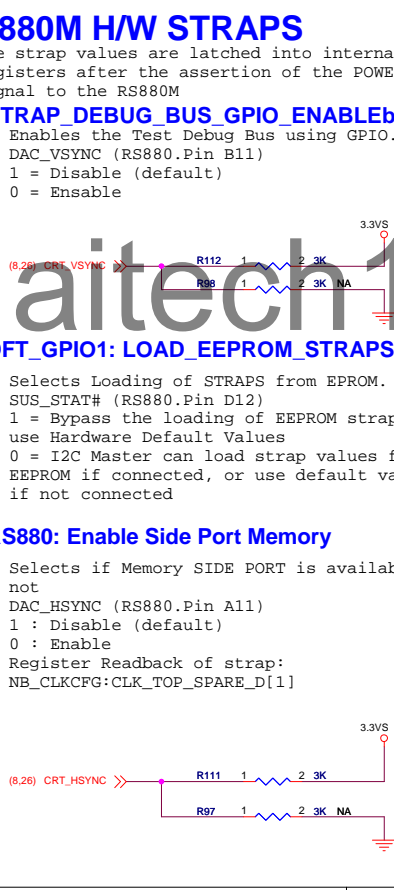
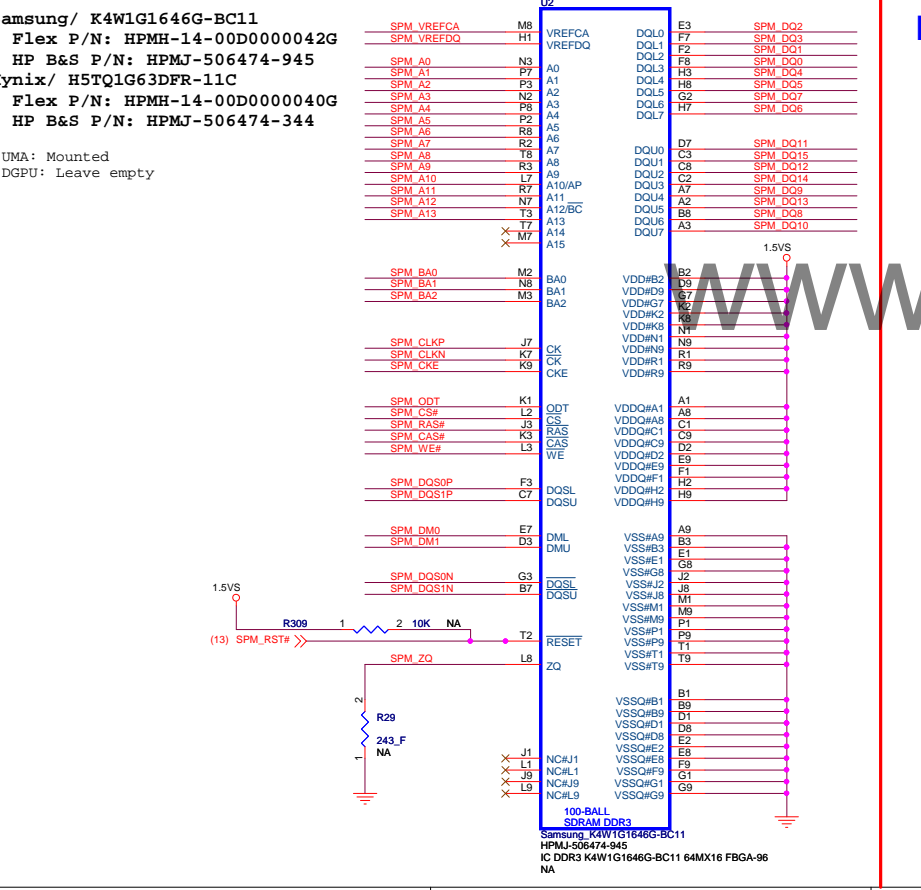
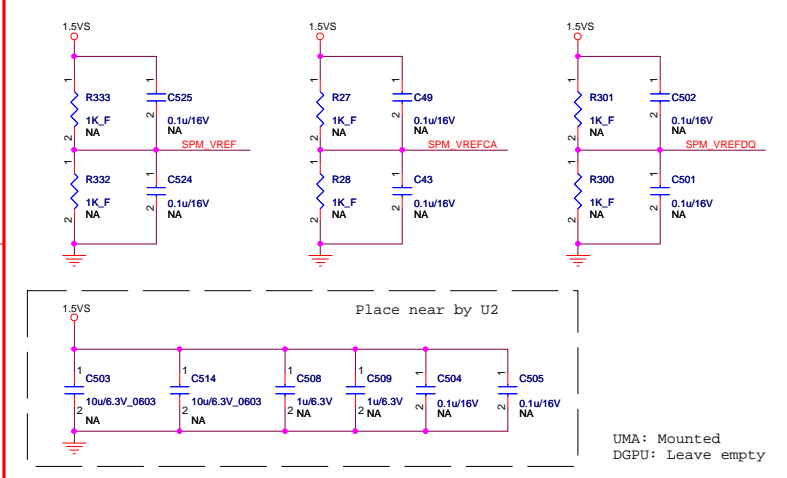
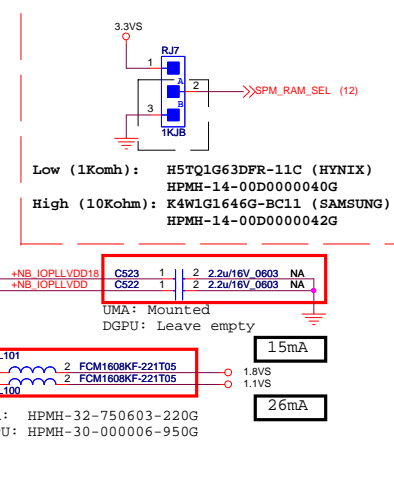
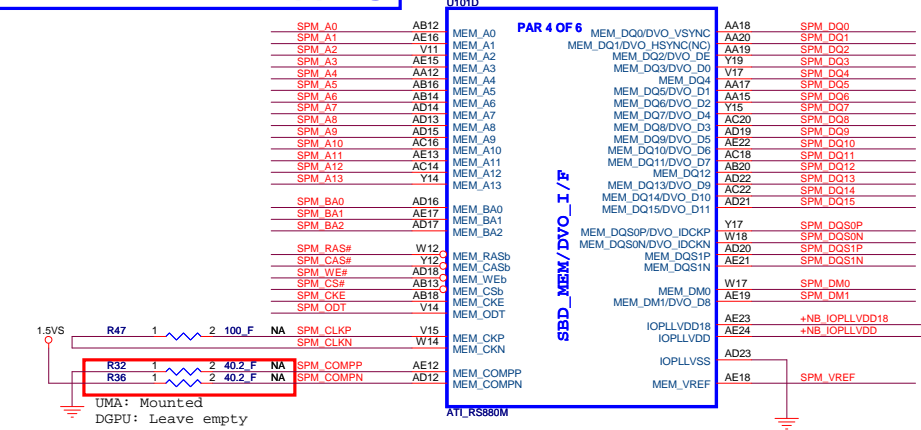
Flex P/N: HPMH-10-0010000096G
HP B&S P/N: HPMJ-534109-001 (UMA)
HPMJ-604096-001 (DGPU)

FLEX Computing

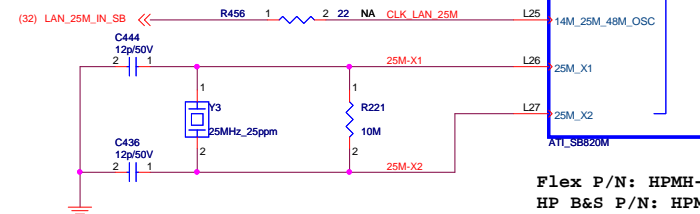
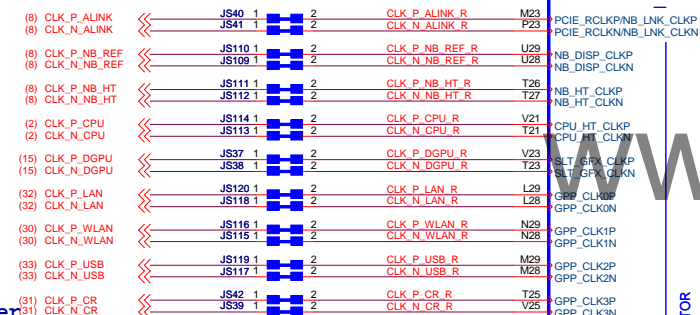
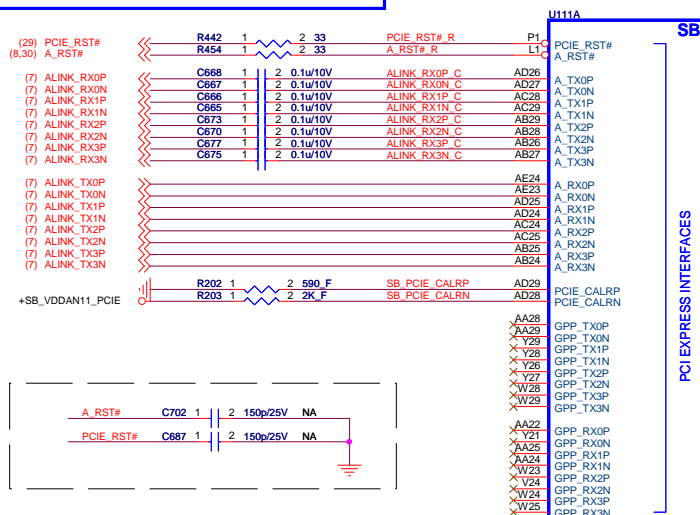
Project Name : H510UA1	Title : RS880M - HT/ PCI-E I/F
Size : Document Number : HPMH-40GAB300-D	Rev : D
Date: Thursday, December 30, 2010	Sheet: 7 of 51



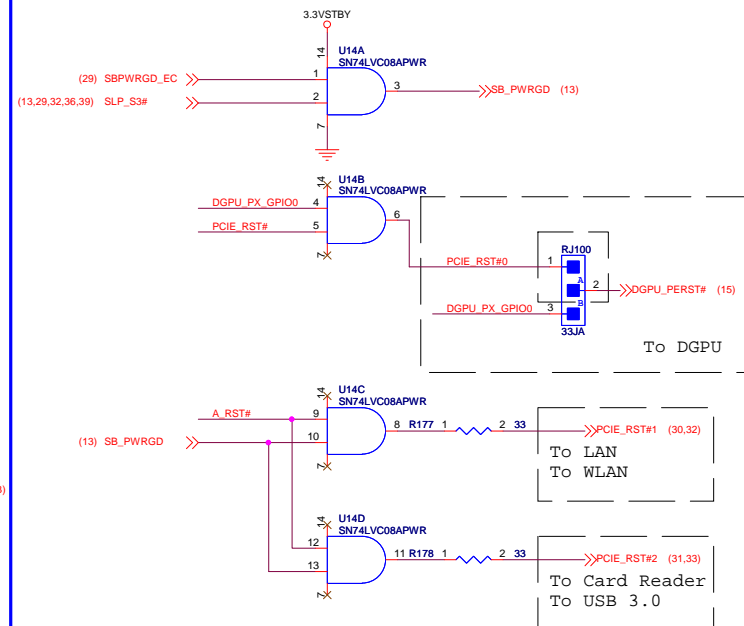
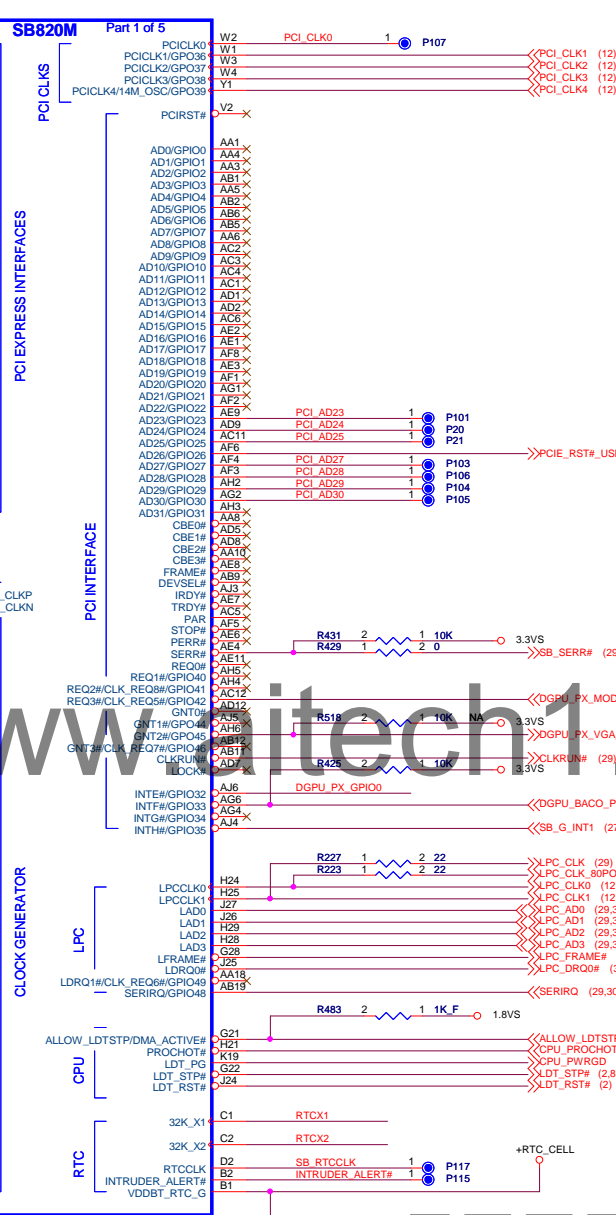
NB Side Port/ Strapping



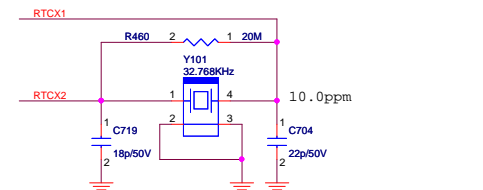
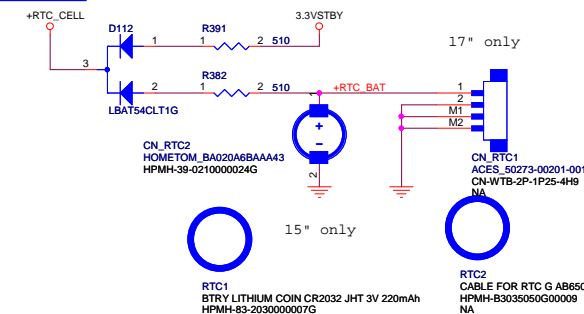
A-Link



Flex P/N: HPMH-10-0010000106G
HP B&S P/N: HPMJ-590825-002



RTC



FLEX Computing

Project Name : H510UA1		Title : SB820M - CPU/ PCIE/ A-link/ CLK	
Size :	Document Number : HPMH-40GAB6300-D		Rev : D
Date : Thursday, December 30, 2010		Sheet : 11 of 51	

SB820M Debug Straps

PciIIByp (PCI AD27)

Bypass PCI PLL
(Used in functional test at tester):

L: Bypass internal PLL clock
H: Use internal PLL generated PLL CLK (Internal Pull-Up of 15Kohm)

ILAAutorunEnB (PCI AD26)

ILA Auto run Enable

L: ILA Auto run enable
H: ILA Auto run disable (Internal Pull-Up of 15Kohm)

FCCIkByP (PCI AD25)

Bypass FC CLK

L: Bypass internal FC CLK (Used in functional test at tester)
H: Use internal FC CLK

I2CROMEn (PCI AD24)

I2C ROM Enable. Load the setting for A-Link Express/ PLL/ music control from I2C ROM

L: Getting the value from I2C EPROM
H: Disable I2C ROM
(Internal Pull-Up of 15Kohm)

PCI_ROM_BOOT (PCI AD23)

Bootting from PCI memory

L: Route ROM fetch tp PCI bus on the very first boot. Use ROMTYPE to determine the ROM type on the subsequent boots.
H: Use ROMTYPE straps to determine the ROM type
(Internal Pull-Up of 15Kohm)

PCIe EEPROM Data/ Clock (PCI_REQ3/ PCI_GNT3)

PCIe EEPROM Data/ Clock

Connected to PCIe EEPROM SDA/ SCL pin or provided test point access for lad use.

SB820M H/W STRAPS

ECEnableStrap (LPCCLK0)

Embedded Controller (EC):

L: Disable
H: Enable



Type I are captured on RSMRST#
Type II are captured on PWRGD.

CLKGEN (LPCCLK1)

Define Clock Generator:

L: External clock mode
H: Internal clock mode



ROMTYPE_1&0 (EC_PWM3& EC_PWM2)

ROMTYPE_1 EC_PWM3	ROMTYPE_0 EC_PWM2	ROM type
0	0	FWH
0	1	LPC& PMC ROM
1	0	SPI
1	1	Reserve

Default Pull-High Pull-Low --> 2.2Kohm

Reserved for Pull-Low selection.



BIF_GEN2_COMPLIANCE_Strap (PCI CLK1)

Set PCIe to Gen II mode:

SB820M: Only provision for Pull down is required, not install by default.



BootFailTmrEn (PCI CLK2)

Watchdog function:

L: Disable BootFailtmr function
H: Enable BootFailtmr function



DefaulStrapMode (PCI CLK3)

Default Debug Straps:

L: Disable Debug Straps
H: Select external Debug Straps



CPUClkSel (PCI CLK4)

CPU/ NB HT Clock Selection:

L: Reserved
H: Required setting for integrated clock mode



CoreSpeedMode (AZ_SDOUT)

Slow down core clock for low power mobile platform:

L: Performance Mode
H: Low Power Mode

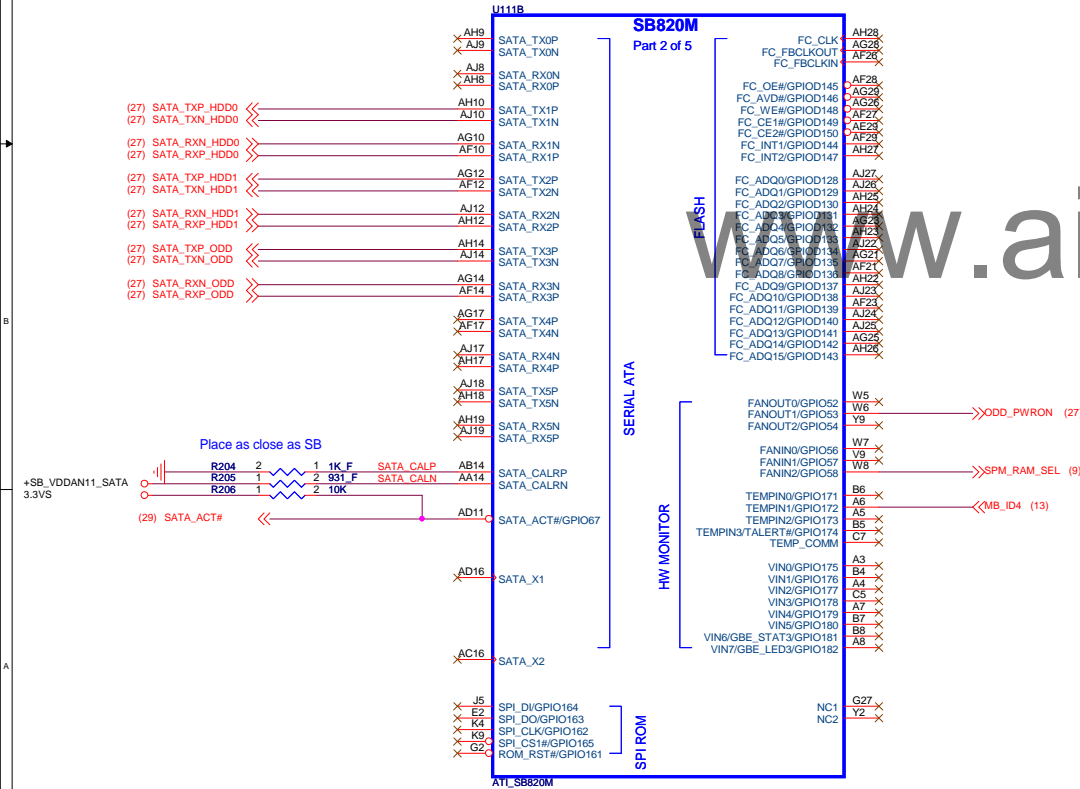


Type I : LPCCLK0, EC_PWM3& EC_PWM2
Type II : the rest of strapping

FLEXComputing

Project Name : H510UA1	Title : SB820M - SATA/ SPI/ Strap
Size : Document Number : H510UA1-40GAB6300-D	Rev : D
Date: Thursday, December 30, 2010	Sheet: 12 of 51

SB SATA/ SPI/ STRAP



(27) ODD_DA#

3.3VS

R452
1K

10K
NA

1N4148

U106
ME2N7002E-G
NA

SB_ODD_DA#

Reserve for Zero-ODD

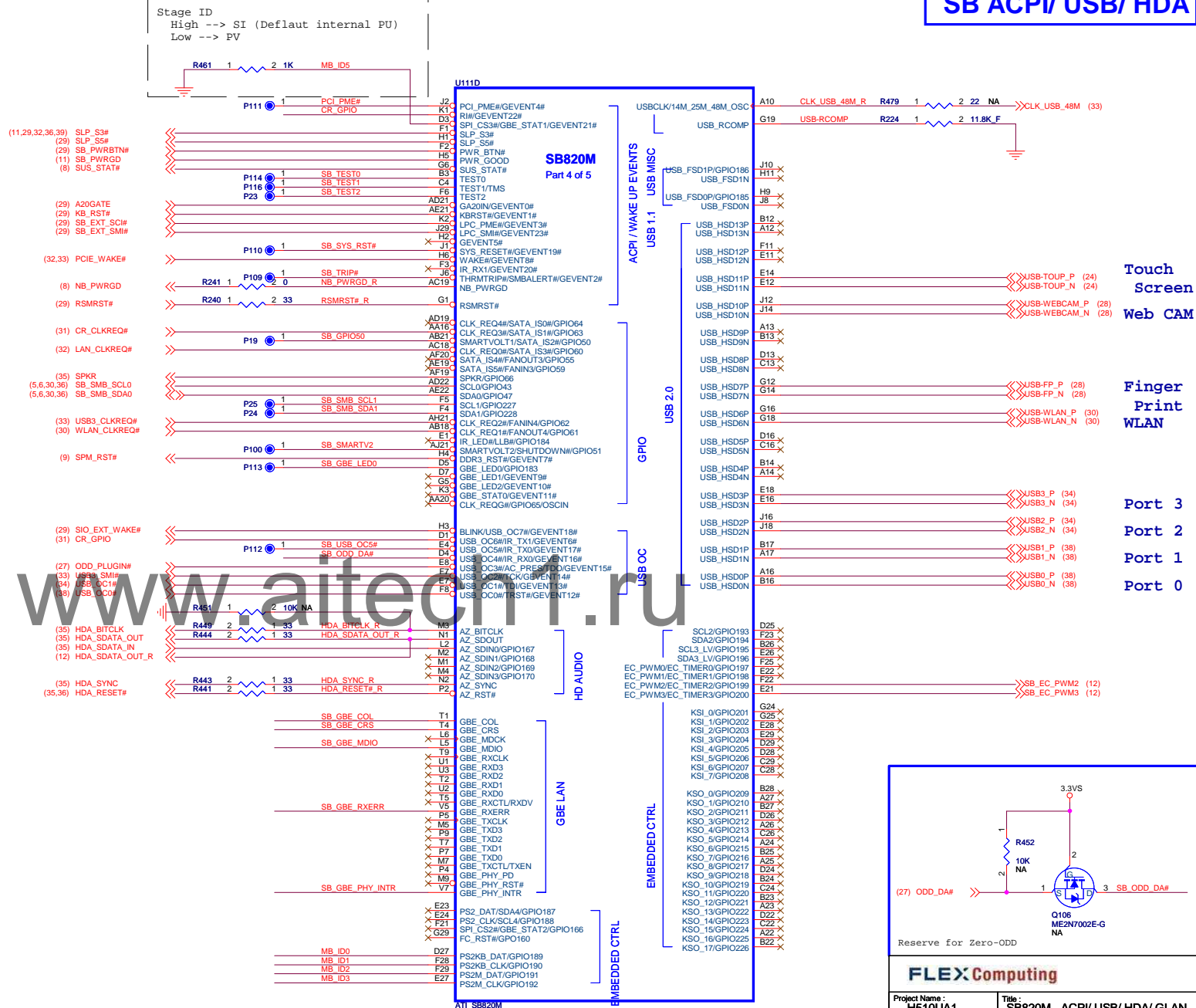
FLEXComputing	
Project Name : H510UA1	Title: SB820M - ACPI/ USB/ HDA/ GLAN
Size :	Document Number : HPMH-40GAB6300-D
Date: Thursday, December 30, 2010	Sheet : 13 of 51

The diagrams illustrate the connection of the 3.3VSTBY_SB signal to different memory modules and their associated MB_ID signals:

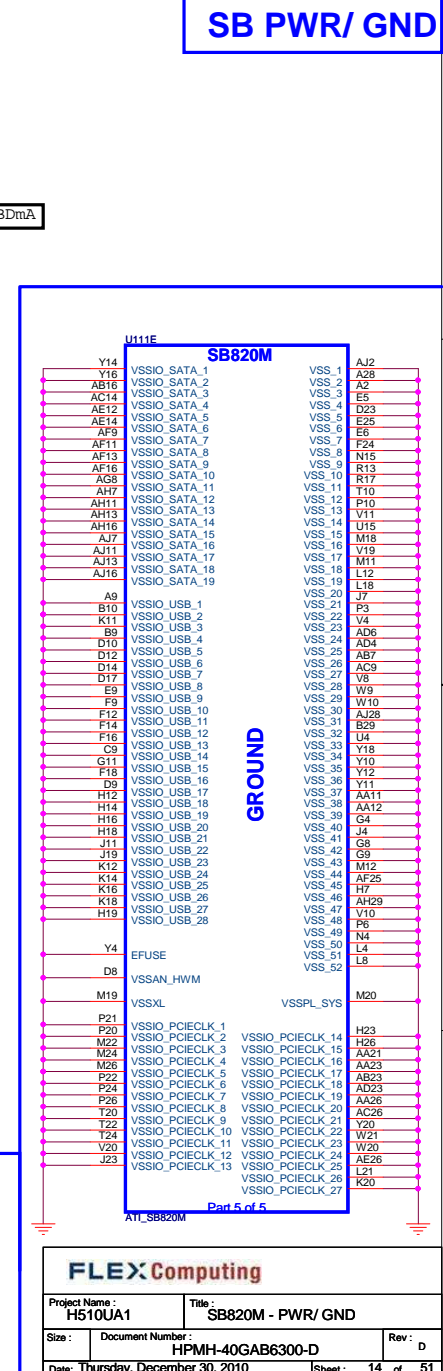
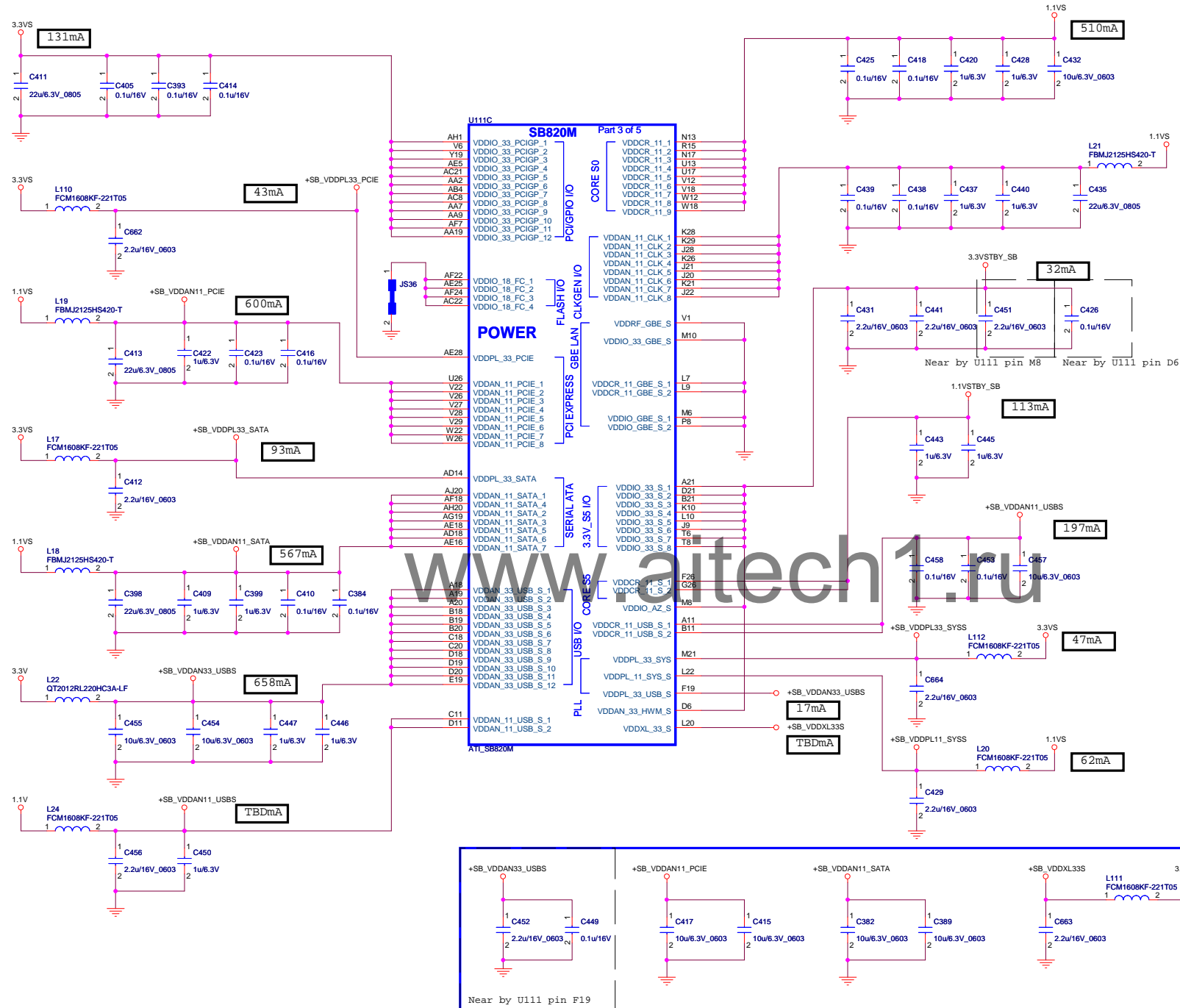
- Top Left:** 3.3VSTBY_SB is connected to pin 1 of RJ103. Pin 2 is connected to MB_ID3. Pin 3 is connected to ground. The module is labeled 1KJA.
- Top Right:** 3.3VSTBY_SB is connected to pin 1 of RJ107. Pin 2 is connected to MB_ID4 (12). Pin 3 is connected to ground. The module is labeled 1KJB.
- Bottom Left:** 3.3VSTBY_SB is connected to pin 1 of RJ101. Pin 2 is connected to MB_ID2. Pin 3 is connected to ground. The module is labeled 1KJB.
- Bottom Middle:** 3.3VSTBY_SB is connected to pin 1 of RJ102. Pin 2 is connected to MB_ID1. Pin 3 is connected to ground. The module is labeled 1KJA.
- Bottom Right:** 3.3VSTBY_SB is connected to pin 1 of RJ104. Pin 2 is connected to MB_ID0. Pin 3 is connected to ground. The module is labeled 1KJA.

The schematic diagram illustrates the EMI (Electromagnetic Interference) section, showing connections to the ground plane. It includes the following components and connections:

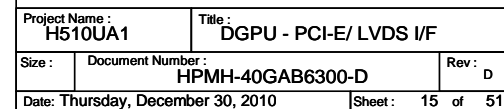
- EMI Section:**
 - HDA_BITCLK:** Connected to C691 (1) and 2 22p/50V NA.
 - CLK_USB_48M:** Connected to EC136 (1) and 2 22p/50V NA.
- 3.3VSBY_SB:**
 - Connected to R219 (1) and 2 10K.
 - Connected to R212 (1) and 2 10K.
 - SB_GBE_MDIO
 - SB_GBE_PHY_INTR
- 3.3VS:**
 - Connected to R480 (1) and 2 4.7K.
 - Connected to R196 (1) and 2 2.2K.
 - Connected to R197 (1) and 2 2.2K.
 - SUS_STAT#
 - SB_SMB_SQLO
 - SB_SMB_SDA0
 - Connected to R210 (1) and 2 10K.
 - Connected to R215 (1) and 2 10K.
 - Connected to R211 (1) and 2 10K.
 - SB_GBE_COL
 - SB_GBE_CRS
 - SB_GBE_RXERR
 - Connected to R448 (1) and 2 10K.
 - Connected to R453 (1) and 2 10K.
 - HDA_BITCLK
 - HDA_SDATA_IN



SB PWR/ GND



HP B&S P/N: HPMJ-628114-001



PWRGOOD
For Broadway, Madison and Park the PWRGOOD ball must be connected to ground

	DVPDATA_2	DVPDATA_1	DVPDATA_0
Hynix (64Mx16) x4pcs	0	0	0
Samsung (64Mx16) x4pcs	1	0	0
Hynix (128Mx16) x4pcs	0	1	0
Samsung (128Mx16) x4pcs	1	1	0
Hynix (64Mx16) x8pcs	0	0	1
Samsung (64Mx16) x8pcs	1	0	1
Hynix (128Mx16) x8pcs	0	1	1
Samsung (128Mx16) x8pcs	1	1	1

64MX16

HYNIX:

Flex P/N: HPMH-14-00D0000040G - IC DDR3 H5TQ1G63DFR-11C 64MX16 FBGA-96

HP B&S P/N: HPMJ-506474-945

SAMSUNG:

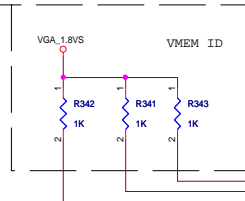
Flex P/N: HPMH-14-00D0000042G - IC DDR3 K4W1G1646G-BC11 64MX16 FBGA-96

HP B&S P/N: HPMJ-506474-344

128MX16:

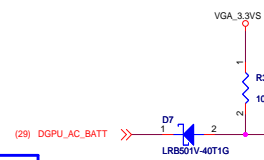
Hynix: HPMH-14-00D0000039G - IC DDR3 H5TQ2G63BFR-11C 128MX16 FBGA-96

Samsung: HPMH-14-00D0000043G - IC K4W2G1646C-HC11 128Mb*16 96 FBGA



NC on Park

NC on Park



(29) DGPU_AC_BATT

LRB501V-40T1G

(18) DGPU_GPIO0

(18) DGPU_GPIO1

(18) DGPU_GPIO2

(18) DGPU_GPIO3

(18) DGPU_GPIO4

(18) DGPU_GPIO5

(18) DGPU_GPIO6

(18) DGPU_GPIO7

(18) DGPU_GPIO8

(18) DGPU_GPIO9

(18) DGPU_GPIO10

(18) DGPU_GPIO11

(18) DGPU_GPIO12

(18) DGPU_GPIO13

(18) DGPU_GPIO14

(18) DGPU_GPIO15

(18) DGPU_GPIO16

(18) DGPU_GPIO17

(18) DGPU_GPIO18

(18) DGPU_GPIO19

(18) DGPU_GPIO20

(18) DGPU_GPIO21

(18) DGPU_GPIO22

(18) DGPU_GPIO23

(18) DGPU_GPIO24

(18) DGPU_GPIO25

(18) DGPU_GPIO26

(18) DGPU_GPIO27

(18) DGPU_GPIO28

(18) DGPU_GPIO29

(18) DGPU_GPIO30

(18) DGPU_GPIO31

(18) DGPU_GPIO32

(18) DGPU_GPIO33

(18) DGPU_GPIO34

(18) DGPU_GPIO35

(18) DGPU_GPIO36

(18) DGPU_GPIO37

(18) DGPU_GPIO38

(18) DGPU_GPIO39

(18) DGPU_GPIO40

(18) DGPU_GPIO41

(18) DGPU_GPIO42

(18) DGPU_GPIO43

(18) DGPU_GPIO44

(18) DGPU_GPIO45

(18) DGPU_GPIO46

(18) DGPU_GPIO47

(18) DGPU_GPIO48

(18) DGPU_GPIO49

(18) DGPU_GPIO50

(18) DGPU_GPIO51

(18) DGPU_GPIO52

(18) DGPU_GPIO53

(18) DGPU_GPIO54

(18) DGPU_GPIO55

(18) DGPU_GPIO56

(18) DGPU_GPIO57

(18) DGPU_GPIO58

(18) DGPU_GPIO59

(18) DGPU_GPIO60

(18) DGPU_GPIO61

(18) DGPU_GPIO62

(18) DGPU_GPIO63

(18) DGPU_GPIO64

(18) DGPU_GPIO65

(18) DGPU_GPIO66

(18) DGPU_GPIO67

(18) DGPU_GPIO68

(18) DGPU_GPIO69

(18) DGPU_GPIO70

(18) DGPU_GPIO71

(18) DGPU_GPIO72

(18) DGPU_GPIO73

(18) DGPU_GPIO74

(18) DGPU_GPIO75

(18) DGPU_GPIO76

(18) DGPU_GPIO77

(18) DGPU_GPIO78

(18) DGPU_GPIO79

(18) DGPU_GPIO80

(18) DGPU_GPIO81

(18) DGPU_GPIO82

(18) DGPU_GPIO83

(18) DGPU_GPIO84

(18) DGPU_GPIO85

(18) DGPU_GPIO86

(18) DGPU_GPIO87

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(18) DGPU_GPIO226

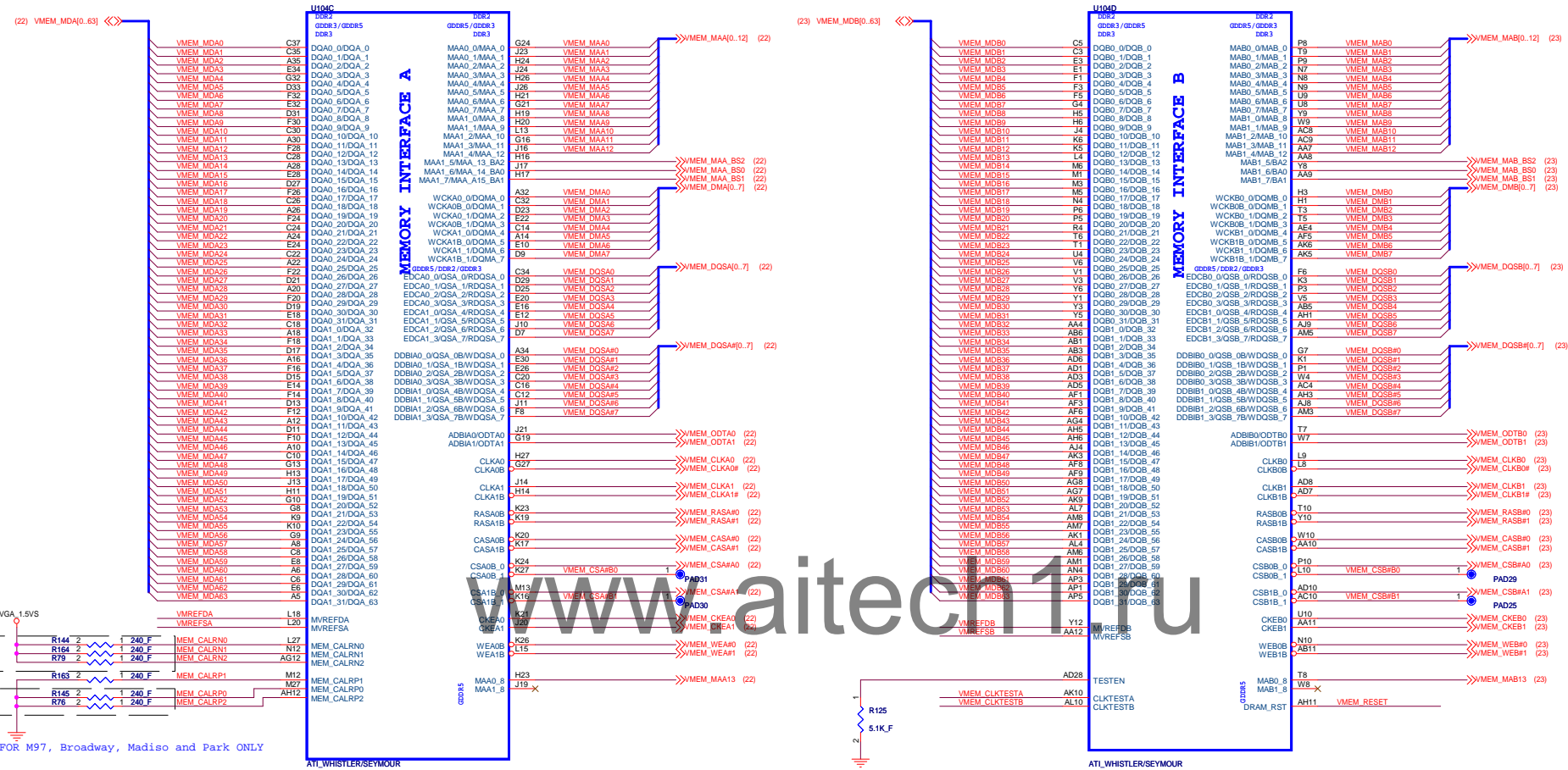
(18) DGPU_GPIO227

(18) DGPU_GPIO228

(18) DGPU_GPIO229

(18) DGPU_GPIO230

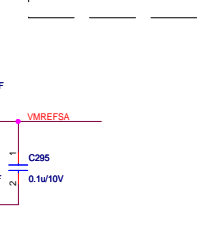
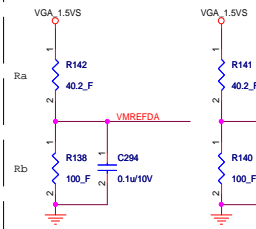
(18) DGPU_GPIO231



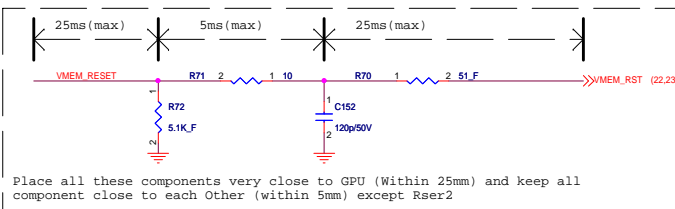
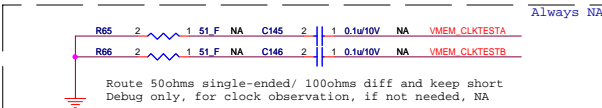
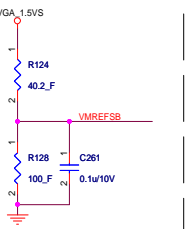
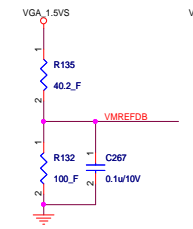
DIVIDER RESISTORS	DDR3 / GDDR3
MVREF TO 1.5V (Ra)	40.2R
MVREF TO GND (Rb)	100R

Place colse to Pin
For DDR3: 0.7 * VDDR1

Seymour: NA
Whistler: Mounte



Place colse to Pin
For DDR3: 0.7 * VDDR1

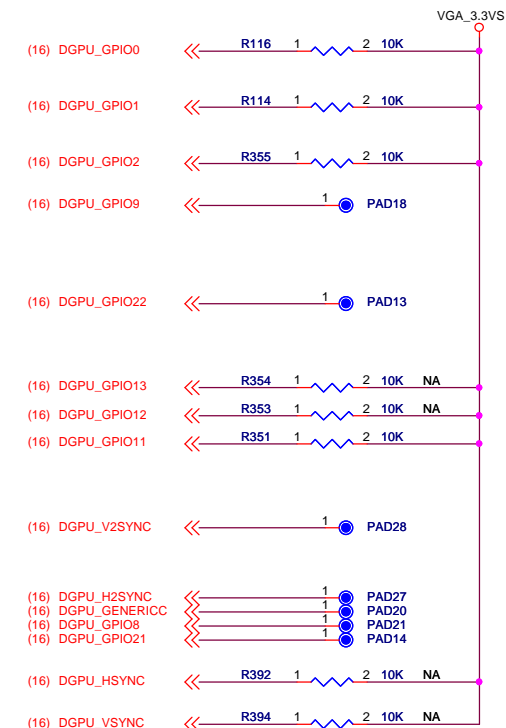


FLEX Computing

Project Name:	H510UA1	Title:	DGPU - VRAM I/F
Size:	Document Number:	HPMH-40GAB6300-D	Rev: D
Date:	Thursday, December 30, 2010	Sheet:	17 of 51


DGPU STRAP

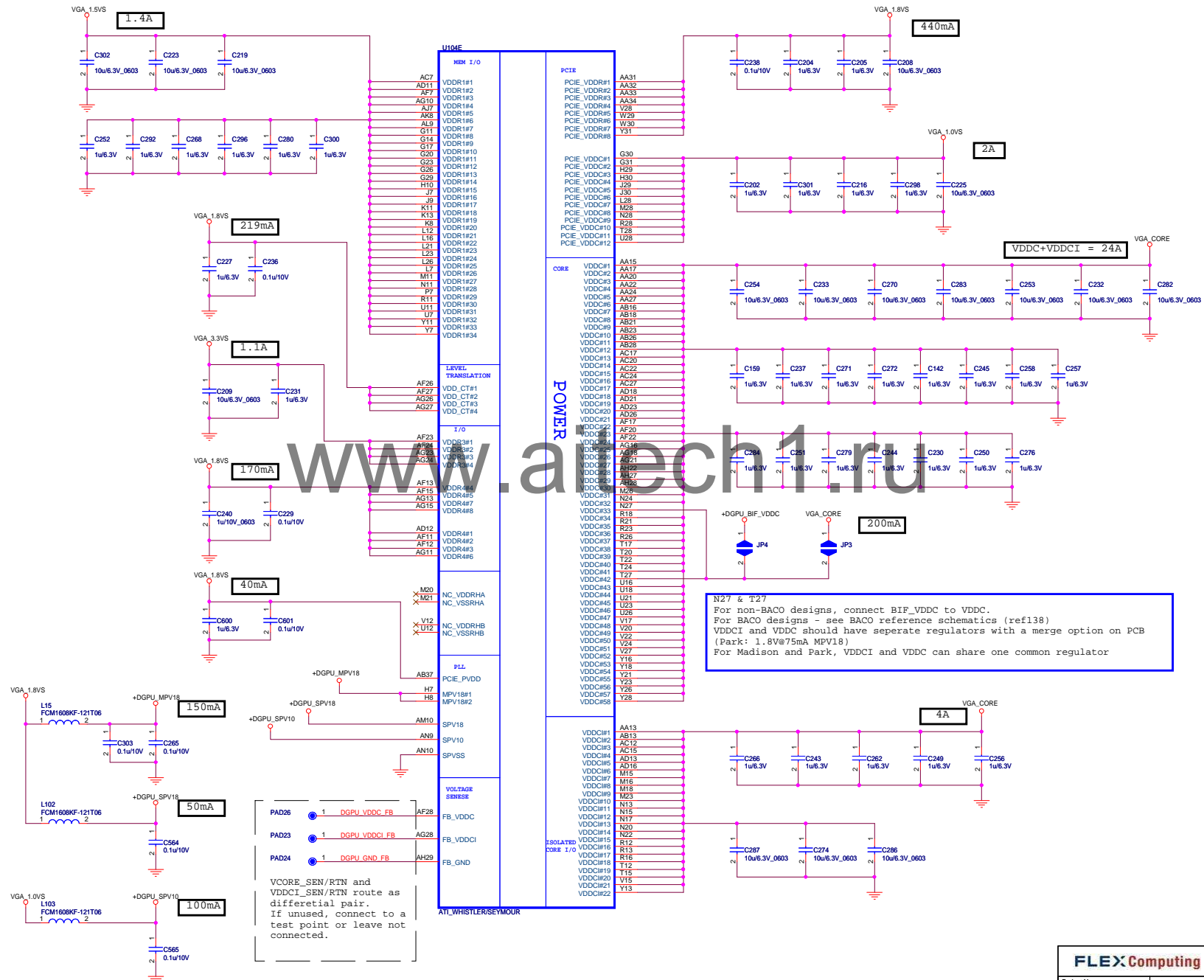
CONFIGURATION STRAPS				
STRAPS	PIN	DESCRIPTION	ASIC Default	Status
TX_PWRS_ENB	GPIO0	Transmitter (Tx) power savings enable 0: 50% Tx output swing (DEFAULT) 1: Full Tx output swing	All Internal Pull Down	Mounted
TX_DEEMPH	GPIO1	PCI Express transmitter deemphasis enable. 0: Tx de-emphasis disabled (DEFAULT) 1: Tx de-emphasis enabled		Mounted
RESERVED	GPIO2	0 : PCIe device as 2.5 GT/s capable (DEFAULT) 1 : PCIe device as 5.0 GT/s capable		Mounted
VGA_DIS	GPIO9	VGA disable determines whether or not the card will be recognized as the system's VGA controller (via the SUBCLASS field in the PCI configuration space): 0 : VGA Controller capacity enabled (DEFAULT) 1 : The device will not be recognized as the system's VGA controller		NA
BIOS_ROM_EN	GPIO_22_ROMCSB	0 - Disable external BIOS ROM device (DEFAULT) 1 - Enable external BIOS ROM device		NA
CONFIG[2] CONFIG[1] CONFIG[0]	GPIO13 GPIO12 GPIO11	BIOS_ROM_EN = 1, Config[2:0] defines the ROM type. BIOS_ROM_EN = 0, Config[2:0] defines the primary memory aperture size. Size of the primary memory apertures CONFIG[2:0] 128 MB 000 256 MB 001 64MB 010 32MB 011		NA NA Mounted
VIP_DEVICE_STRAP_ENA	V2SYNC	IGNORE VIP DEVICE STRAPS L: Ignore VIP Device Strap (DEFAULT) H: Enable VIP Device Strap		NA
RSVD RSVD RSVD RSVD	H2SYNC GENERICC GPIO8 GPIO21_BB_EN			NA NA NA NA
AUD[1] AUD[0]	HSYNC VSYNC	AUD[1] AUD[0] 0 0 No audio function 0 1 Audio for DisplayPort and HDMI if dongle is detected 1 0 Audio for DisplayPort only 1 1 Audio for both DisplayPort and HDMI		NA NA

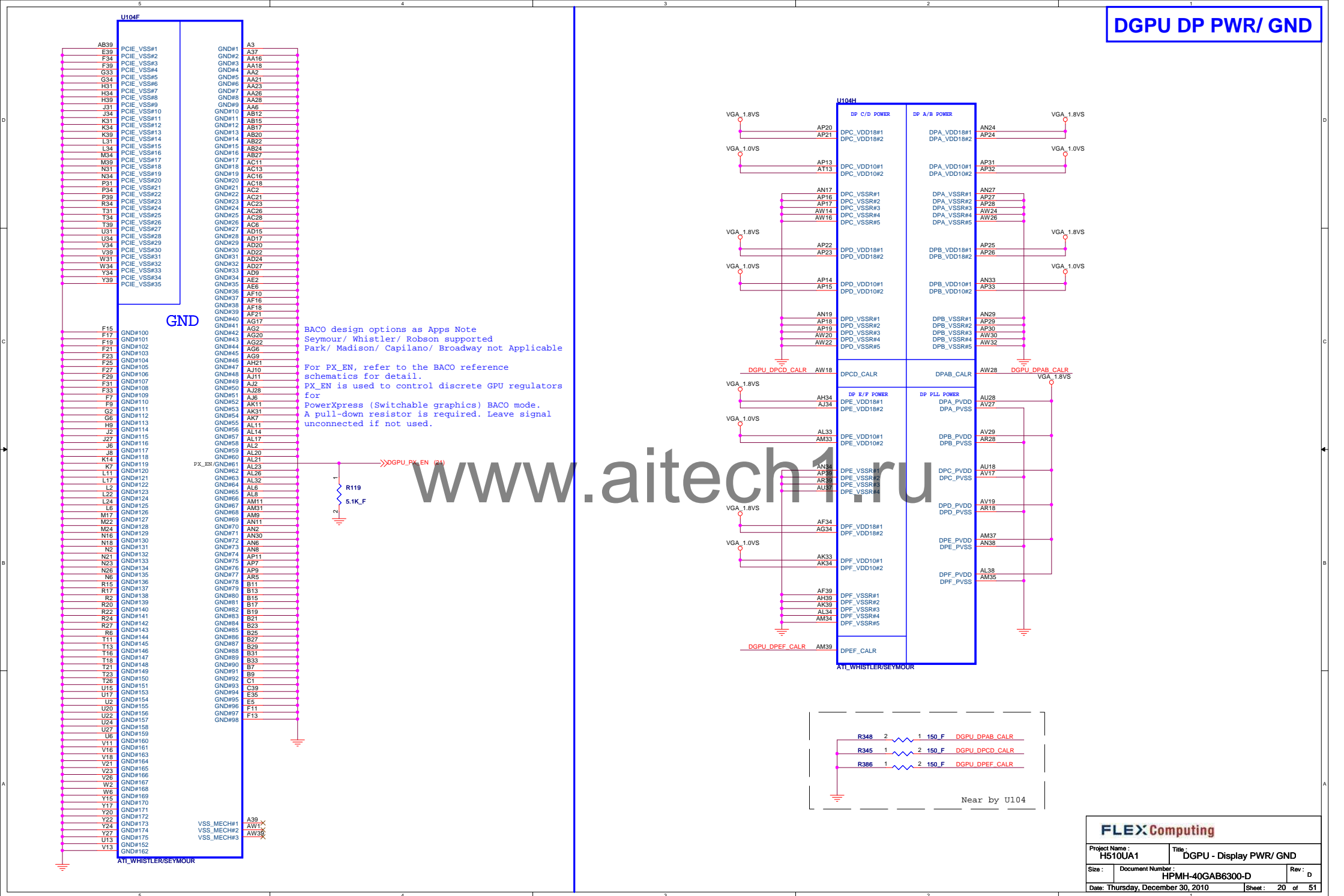


Signal	Seymour/Whistler	Robson/ Park/ Medison/ Capilano/ Broadway
Ball AJ21 on M2 Ball AG13 on S3	SWAPLOCKA SwaplockA/ B signals can be optionally used on a multi-GPU design with multiple display outputs to allow all displays in a group (group A or group B) to update at the same time and have synchronous left/ right stereo timing. Genlock of the GPUs is also needed, either via a genlock system, or by feeding all GPUs with the same reference clock. Also connecting SwaplockB is preferred, but not required. SwaplockA/ B are open drain, 3.3V signals. If this feature is not required, these signals can be used as 3.3V GPIOs or left unconnected on the PCB.	Ball AJ21 is NC on M2 packages Ball AG13 is R2SET on S3 package
Ball AK21 on M2 Ball H12 on S3	SWAPLOCKB - see above On a multi-gpu design, SwaplockB from all GPUs are connected together with an external pull-up resistor (10K Ohms). If this feature is not required, these signals can be used as 3.3V GPIOs or left unconnected on the PCB.	Ball AK21 is NC on M2 packages Ball AH12 is DAC2 Output - on S3 package

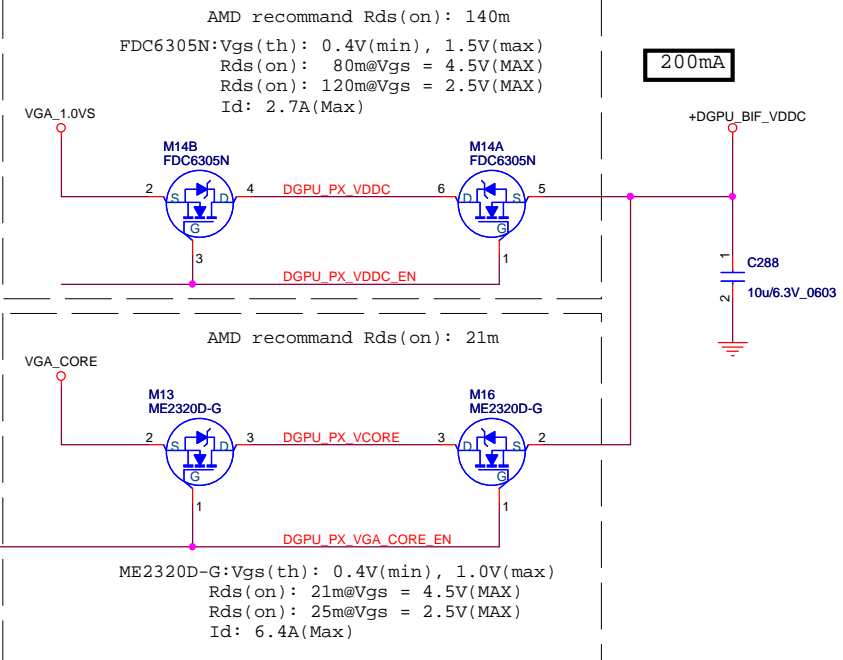
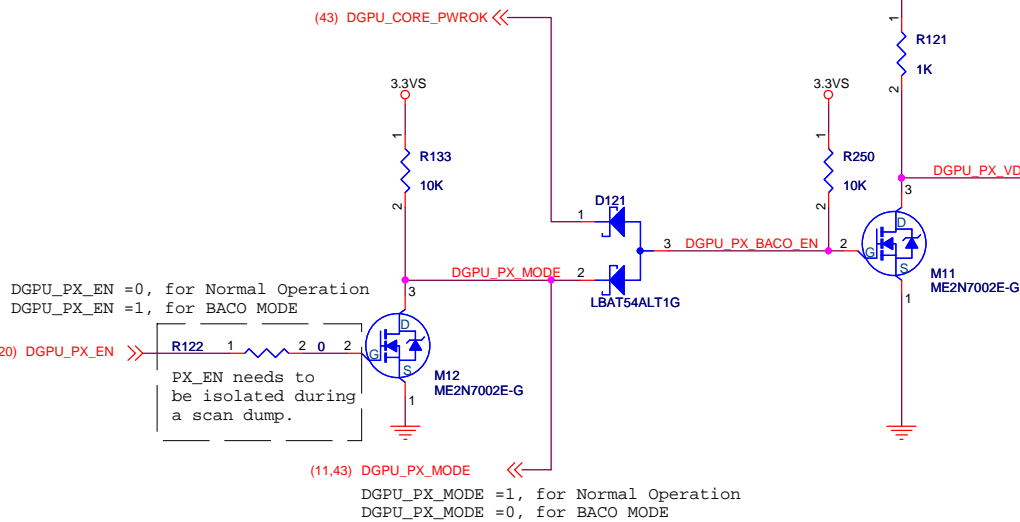
Signal	Seymour/Whistler	Robson/ Park/ Medison/ Capilano/ Broadway
Ball AC32 on M2	NC	DAC2 Output-C on M2 package
Ball AA29 on M2	NC	R2SET on M2 package
Ball AD32 on M2	NC	DAC2 Output- Y
Ball AG33 on M2	NC	A2VDD
Ball AD33 on M2	NC	A2VDDQ
Ball AF33 on M2	TSVSSQ	A2VSSQ
Ball AG33, AG32 on M2	NC	VDD2DI/VSS2DI
H2SYNC	GENLK_CLK (3.3V): Reference clock input (3.3V) for pixel PLL received from frame-lock/ gen-lock interface	H2SYNC
V2SYNC	GENLK_VSYNC (3.3V): Frame timing indicator.Output to frame-lock/genlock interface	V2SYNC

			
Project Name : H510UA1		Title : DGPU - Strap	
Size :	Document Number : HPMH-40GAB6300-D		Rev : D
Date: Thursday, December 30, 2010		Sheet :	18 of 51



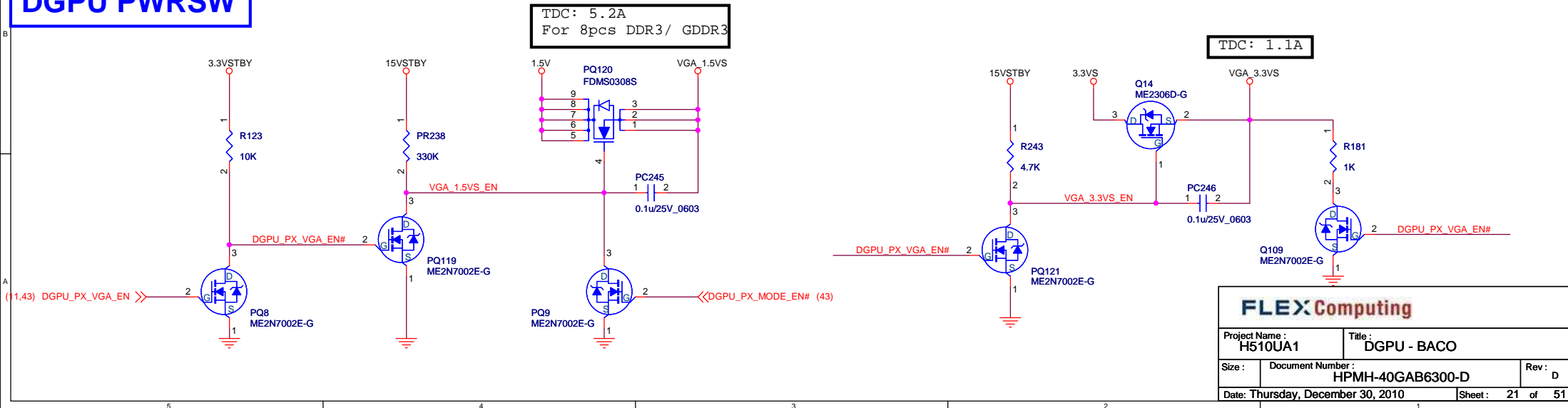


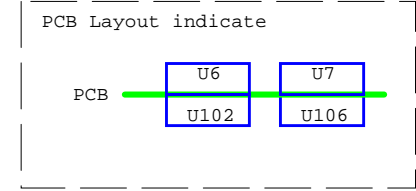
DGPU BACO



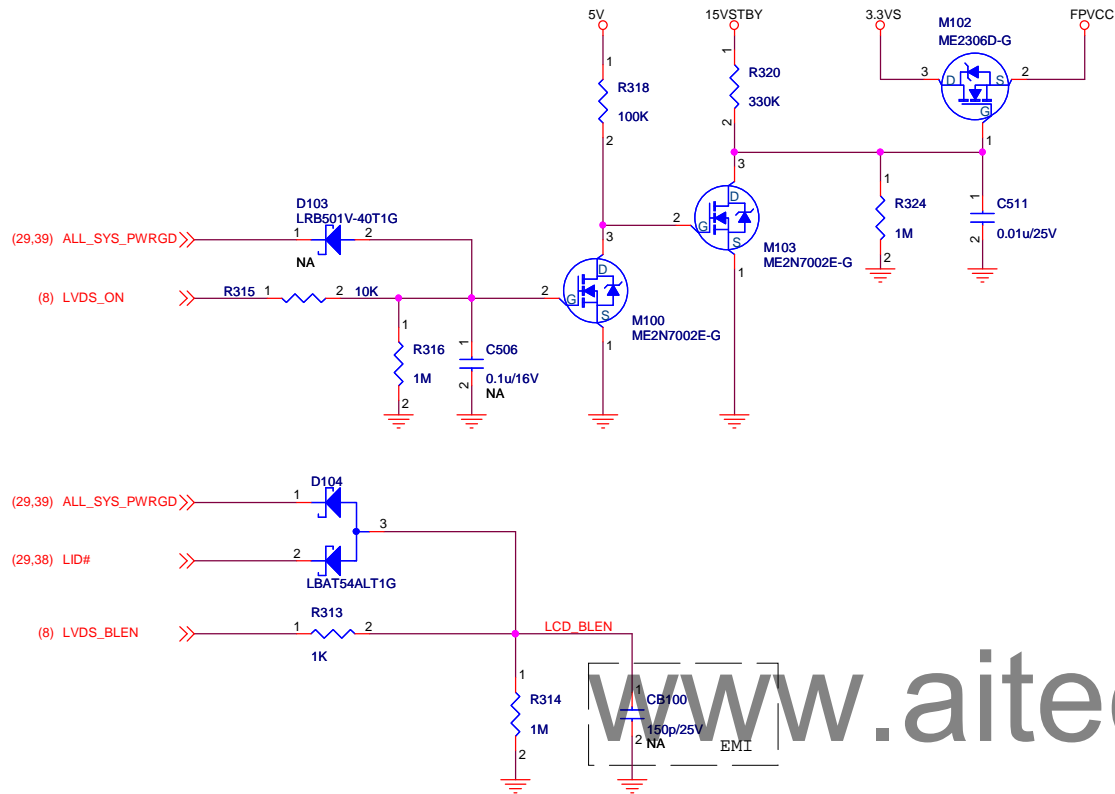
www.aitech1.ru

DGPU PWRSW

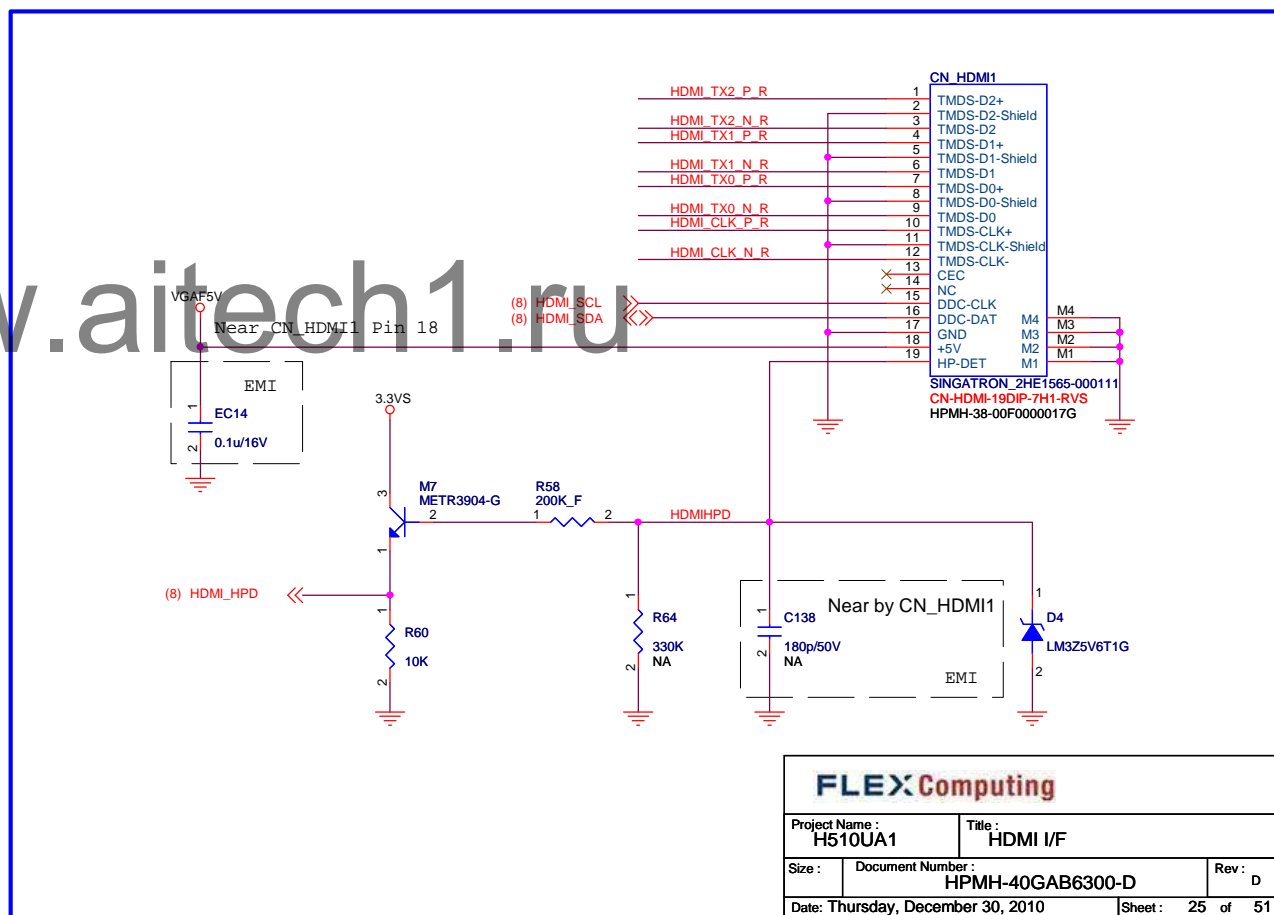
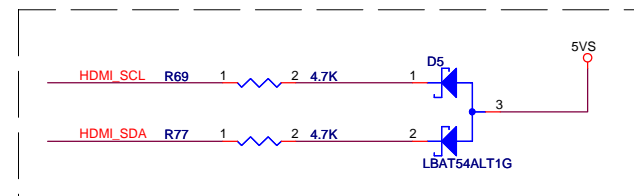
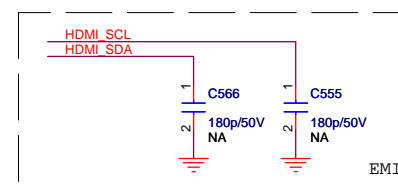
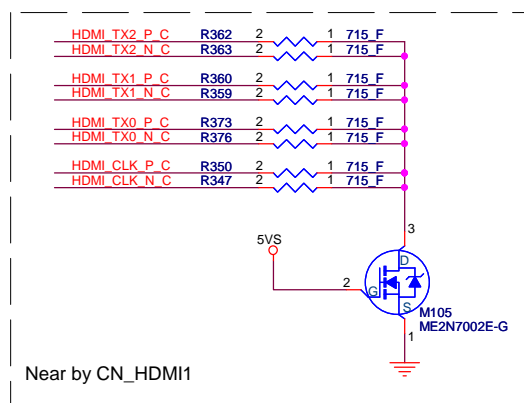
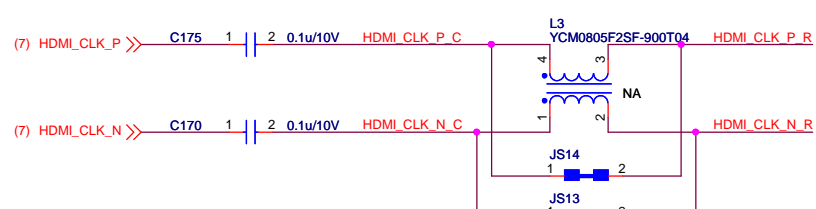
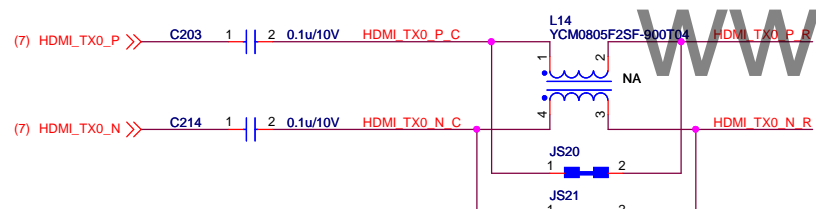
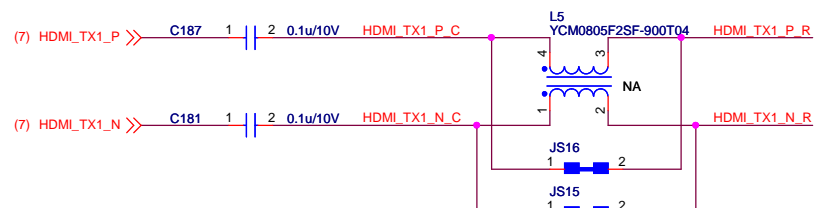
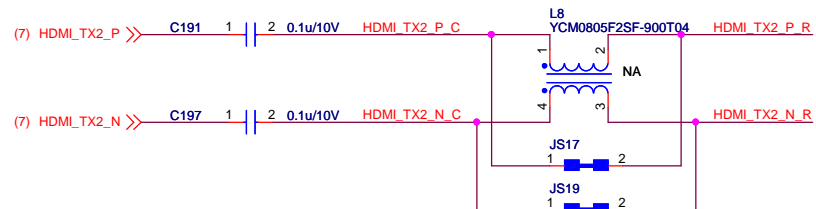


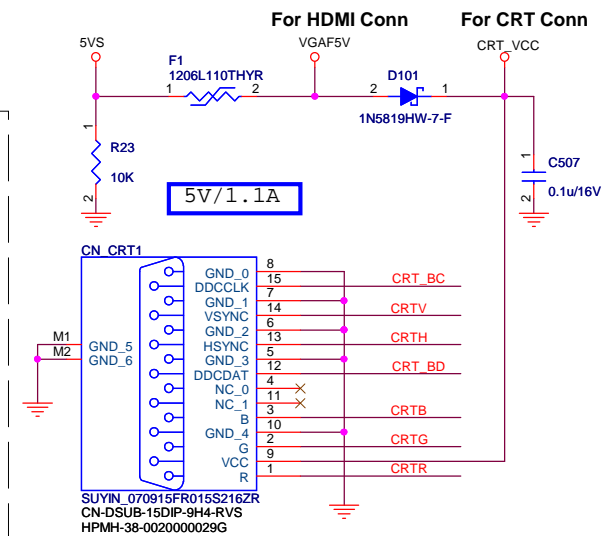
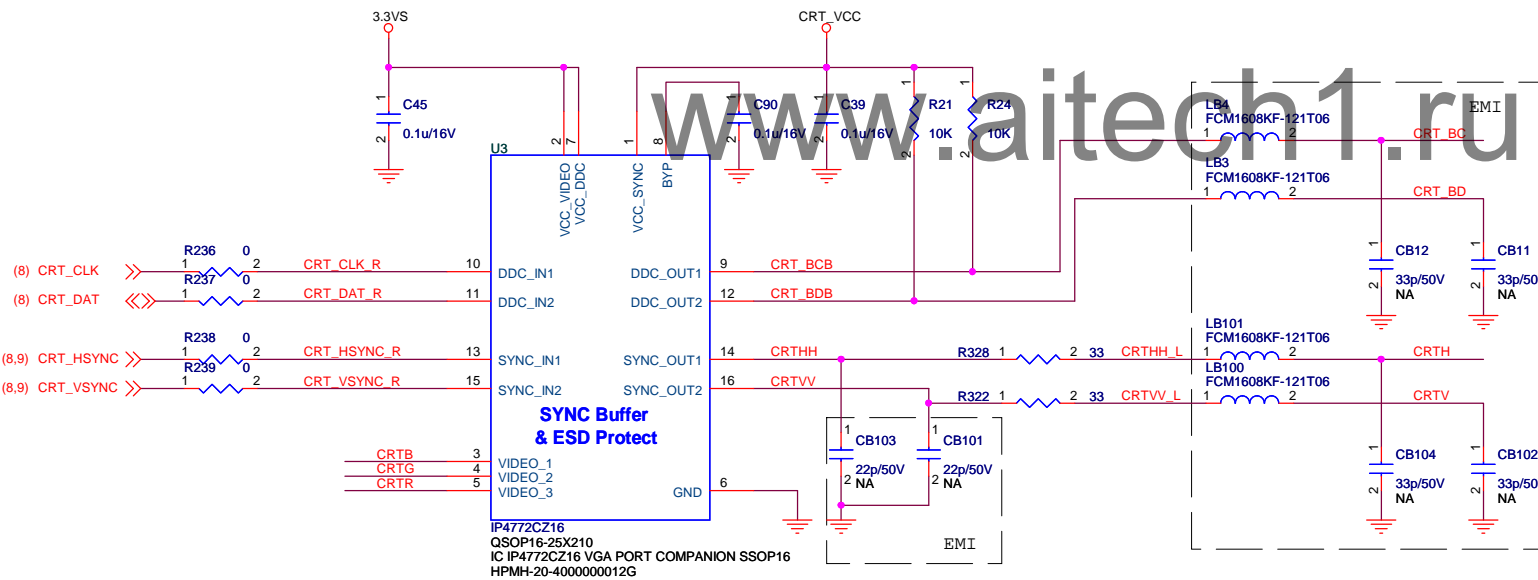
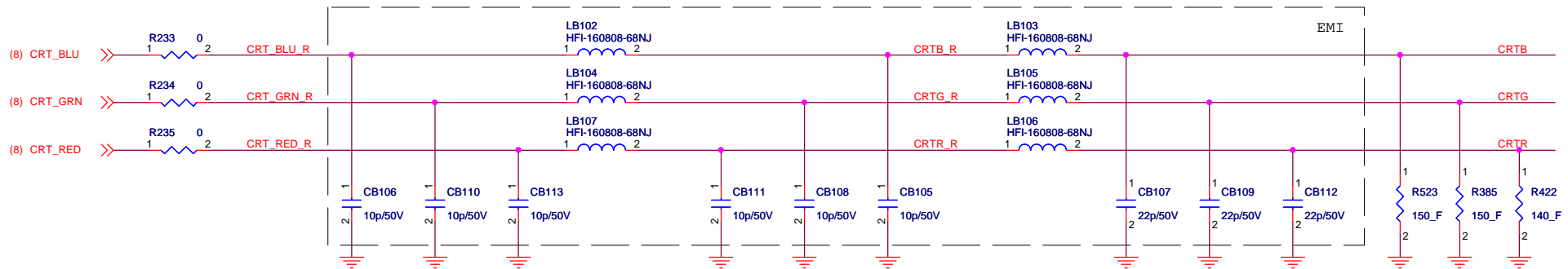


LVDS



HDMI

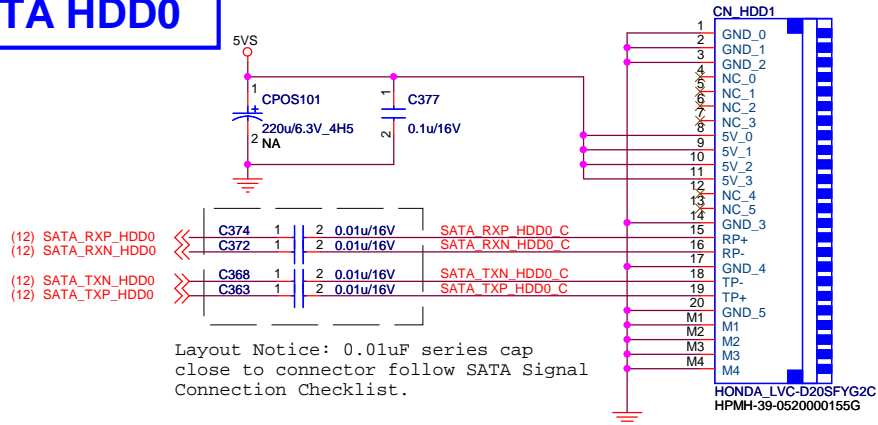




FLEX Computing

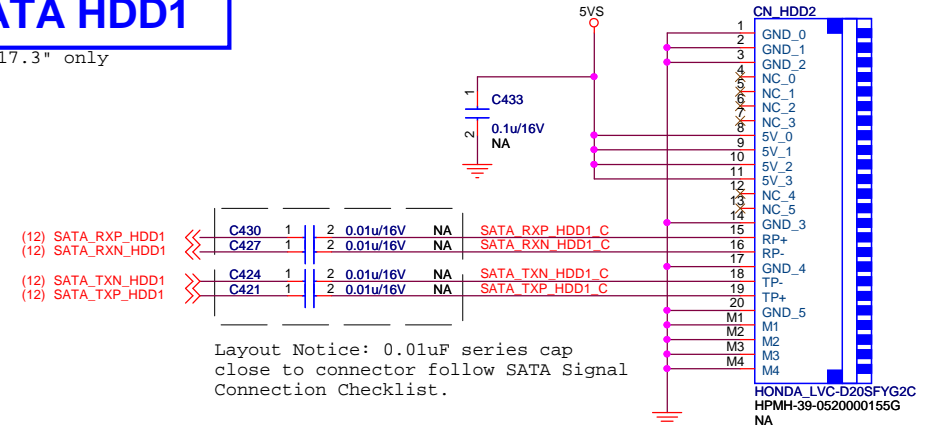
Project Name :	H510UA1	Title :	D-sub I/F
Size :	Document Number :	HPMH-40GAB6300-D	Rev : D
Date :	Thursday, December 30, 2010	Sheet :	26 of 51

SATA HDD0

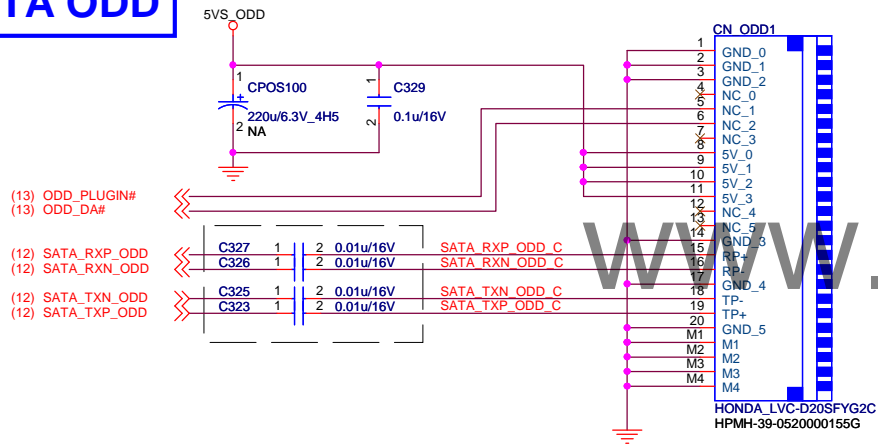


SATA HDD1

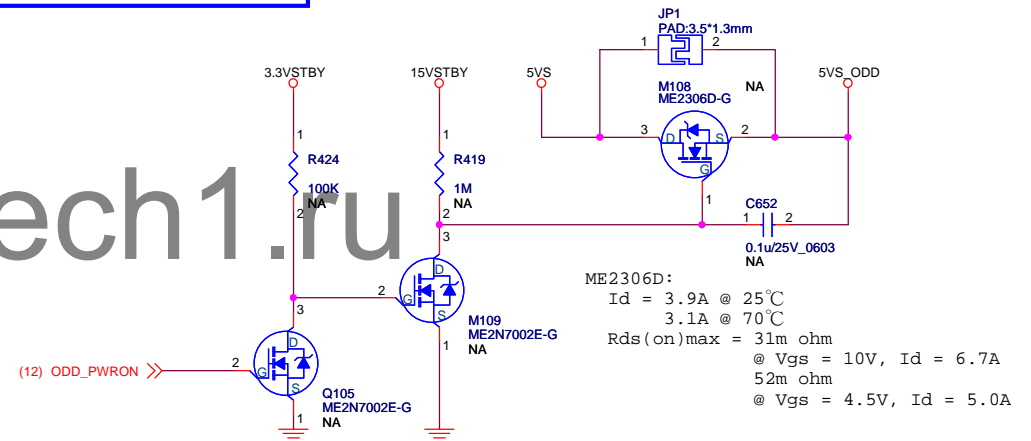
For 17.3" only



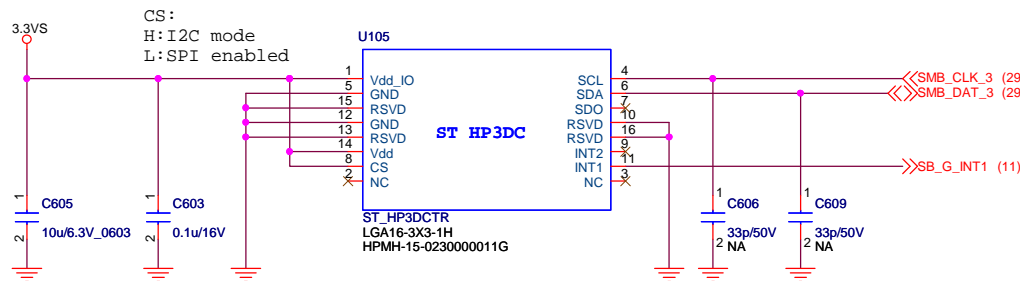
SATA ODD



ODD Zero PWR



G-Sensor



G-SENSOR - ST HP3DC

3.3VS

ADDR: 0001100x(30h) - SDO PD

ADDR: 0011101x(32h) - SDO NC

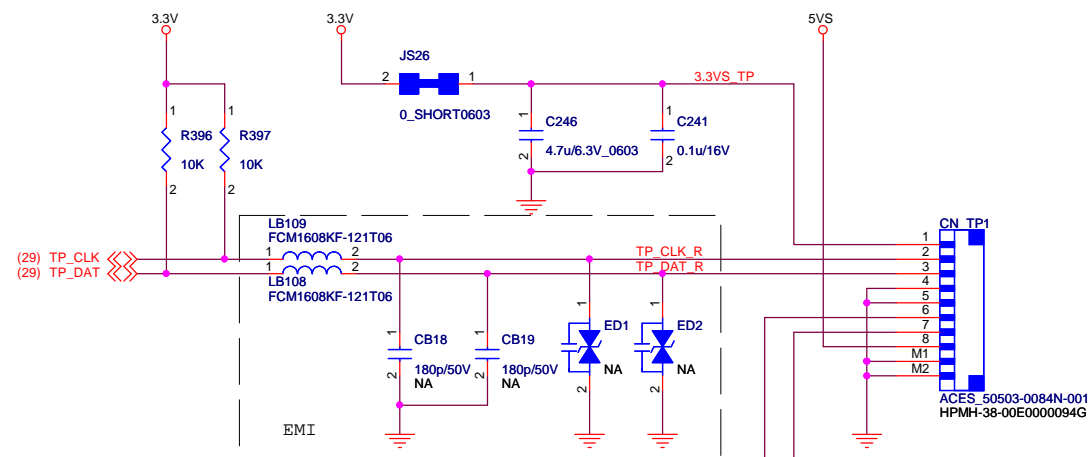
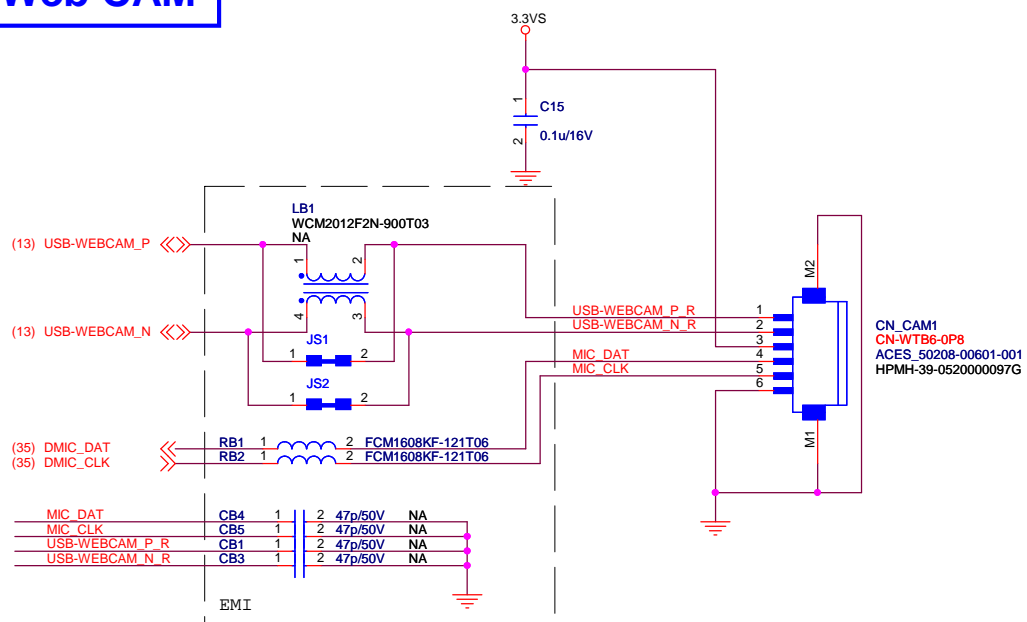
SINK: ?mA@VoL=0.33V (MAX)

FLEXComputing

Project Name :	H510UA1	Title :	HDD/ ODD/ Zero PWR/ G-sensor
Size :	Document Number :	Rev :	D
Date :	Thursday, December 30, 2010	Sheet :	27 of 51

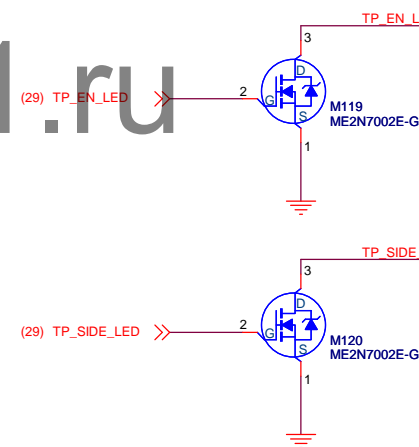
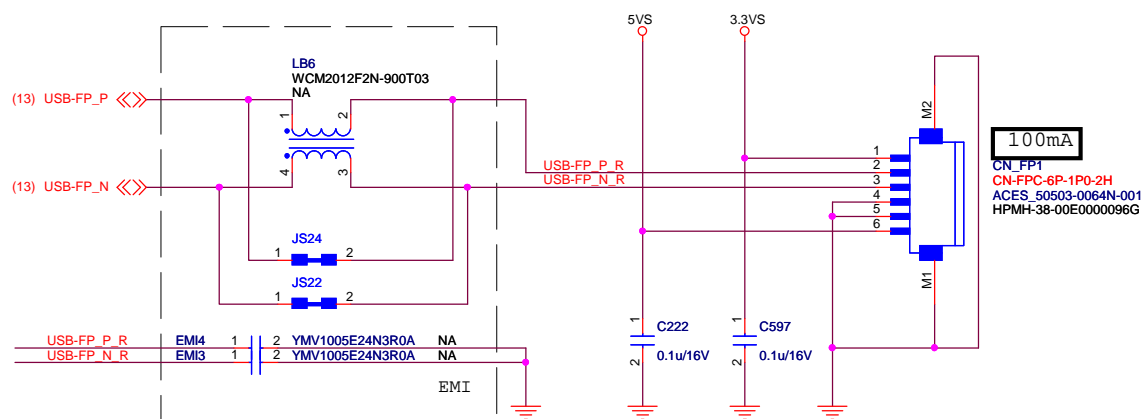
Web CAM

T/P



Finger Printer

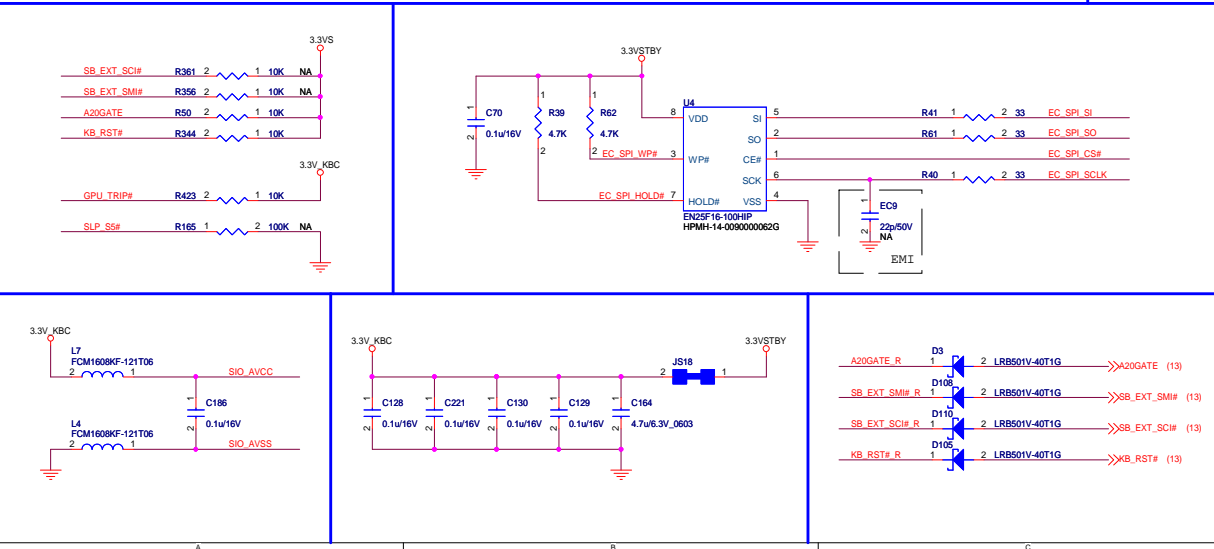
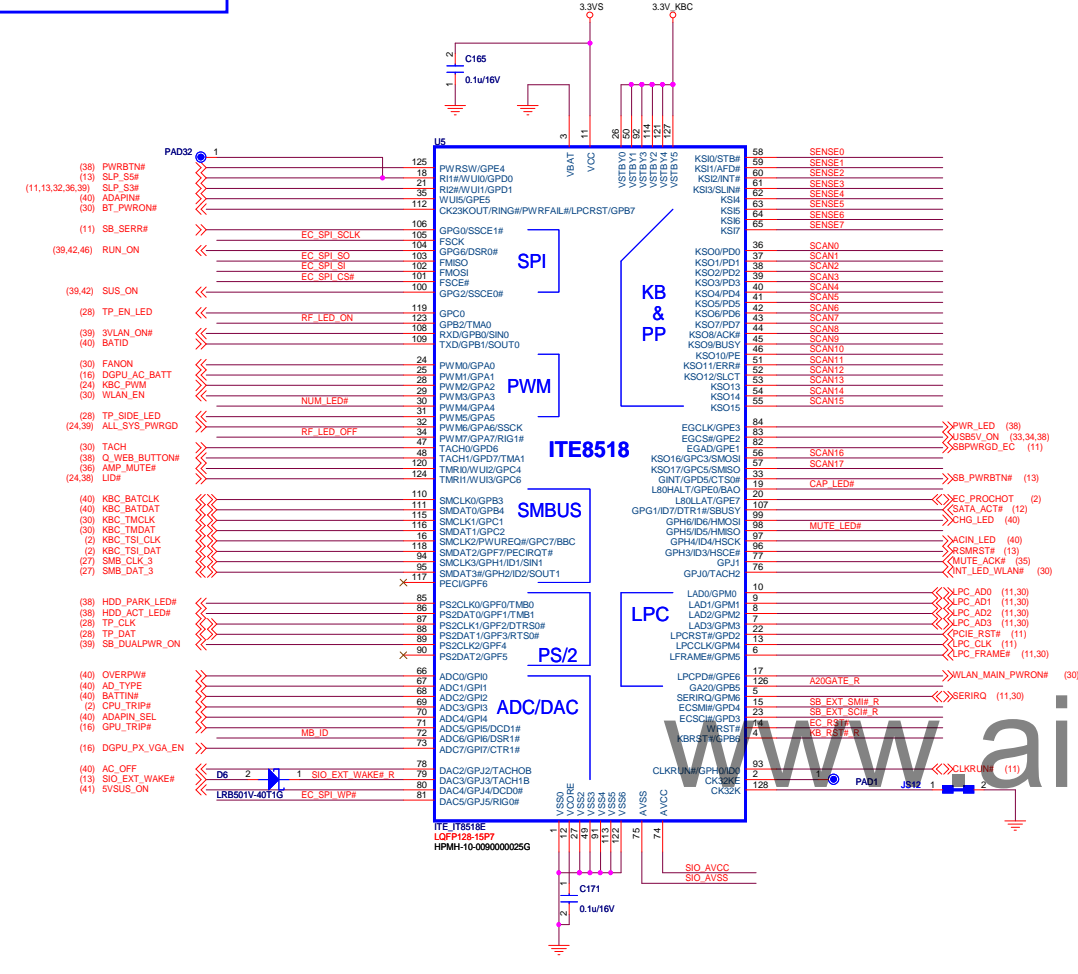
Remve Finger Printer coponents for IMR



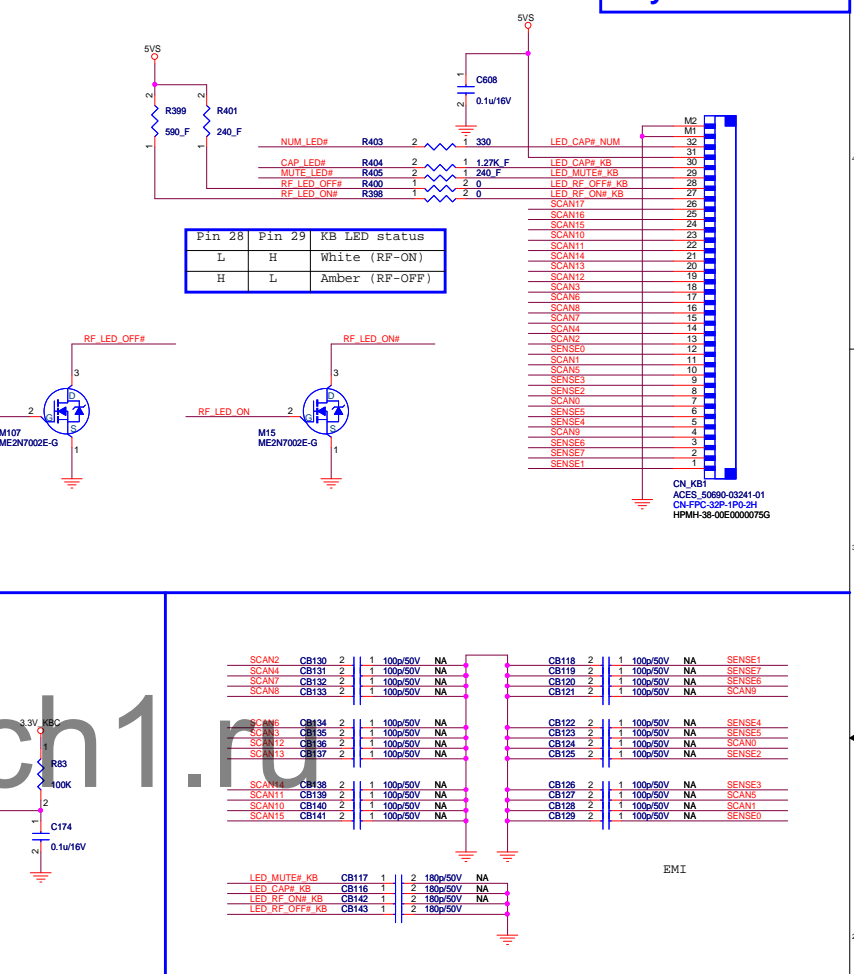
FLEXComputing

Project Name : H510UA1		Title : WebCAM/ BT/ FP/ Touch Screen	
Size :	Document Number :	HPMH-40GAB6300-D	
Date : Thursday, December 30, 2010	Sheet : 28	of 51	

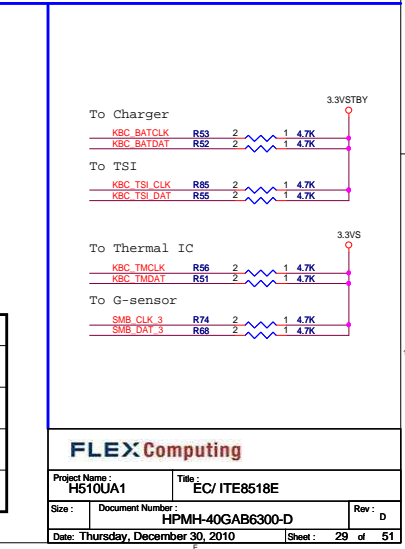
EC/ ITE8518E



Keyboard Conn



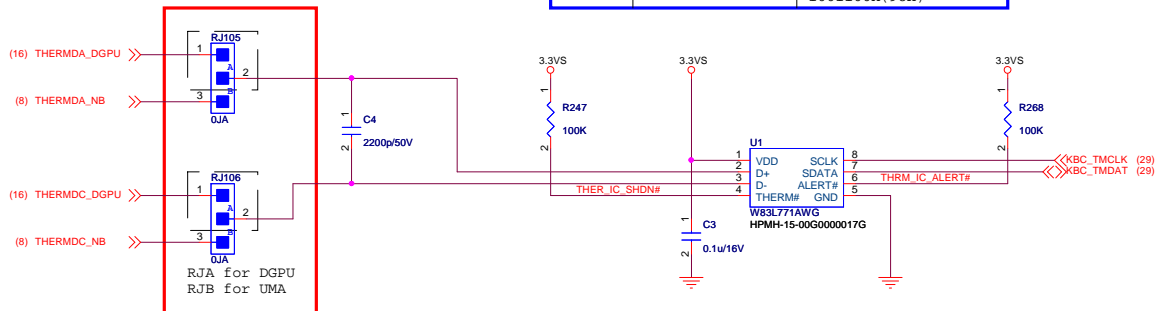
MB-ID		
3.3V	INTEL-DI	R92: 10K -- HPMH-30-301036-990G R104: NA
2.2V	INTEL-UI	R92: 10K -- HPMH-30-301036-990G R104: 20K -- HPMH-30-102036-990G
1.1V	AMD-DA	R92: 20K -- HPMH-30-102036-990G R104: 10K -- HPMH-30-301036-990G
GND	AMD-UA	R92: NA R104: 10K -- HPMH-30-301036-990G



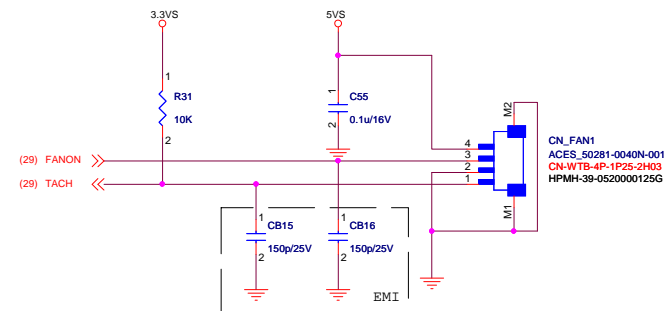
Thermal Sensor

Thermal IC FOR CPU or DGPU

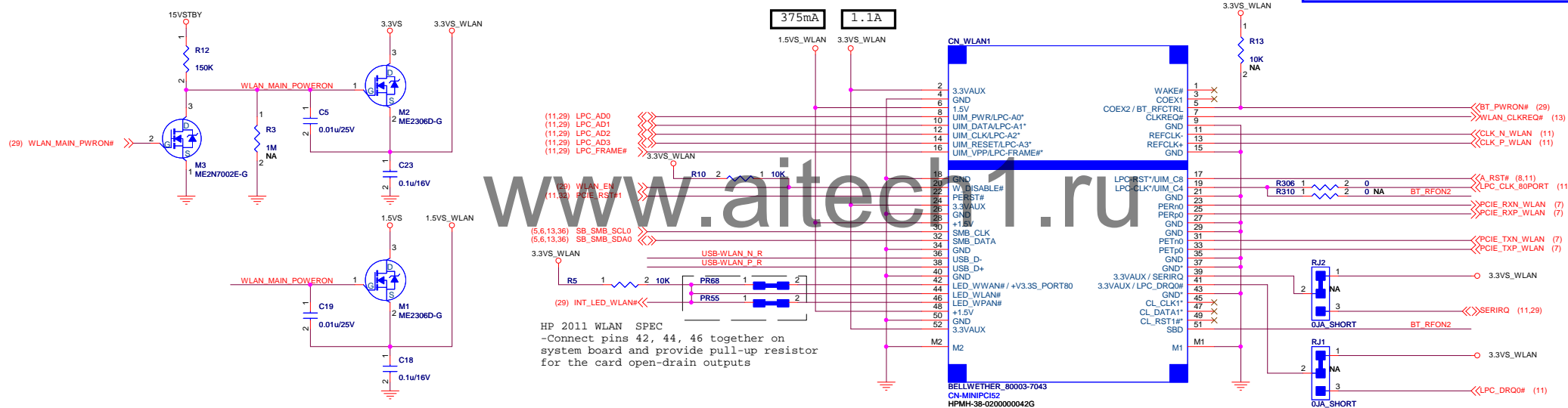
WINBOND	W83L771AWG	HPMH-15-00G0000017G 1001100x(98h)
TI	TMP431ADGKR	HPMH-15-0500000005G 1001100x(98h)



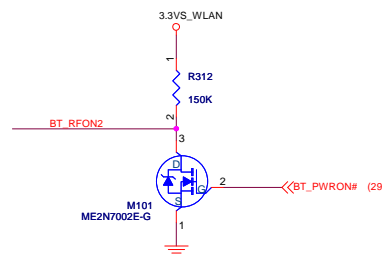
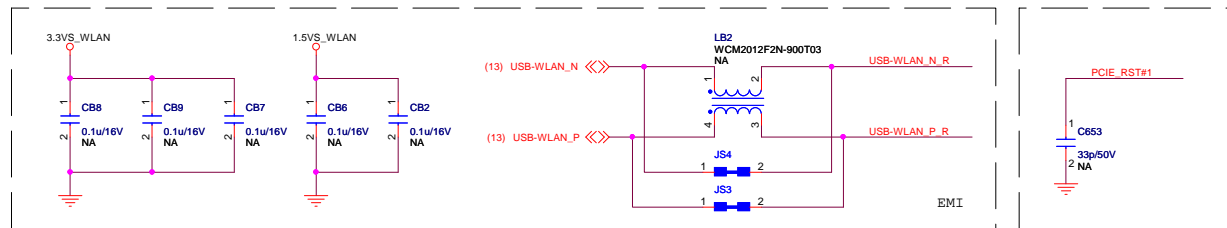
FAN



Mini PCI-E - WLAN (Half)



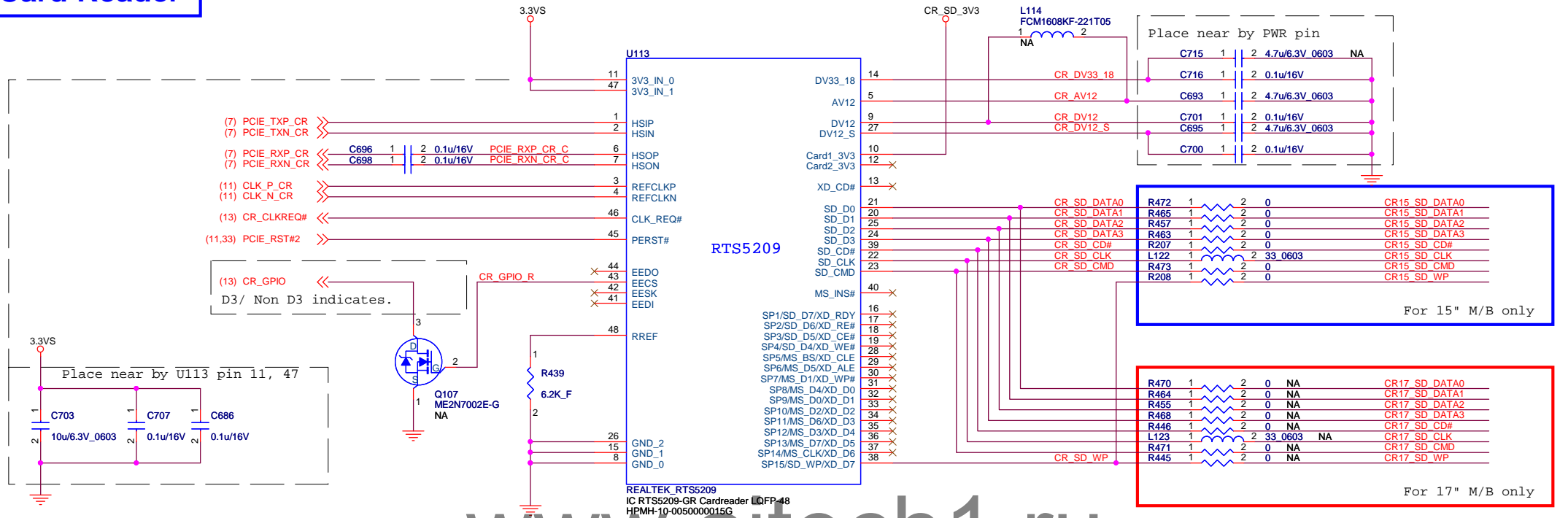
HP 2011 WLAN SPEC
-Connect pins 42, 44, 46 together on system board and provide pull-up resistor for the card open-drain outputs



FLEX Computing

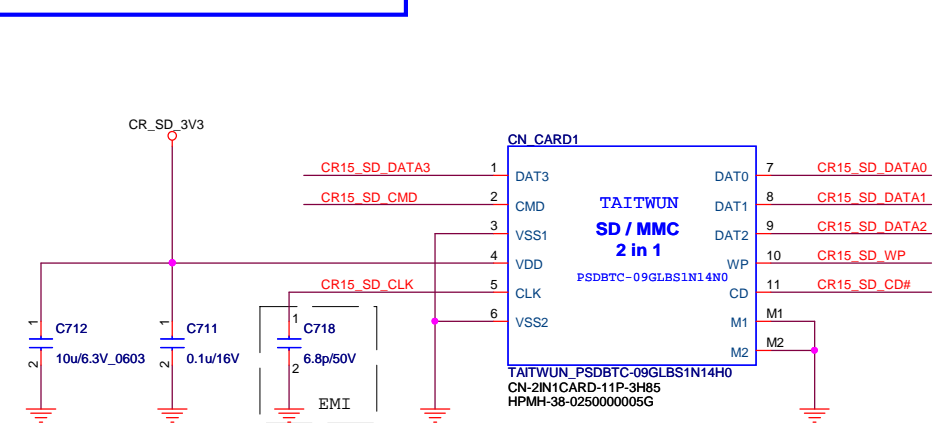
Project Name : H510UA1	Title : Thermal/ FAN/ WLAN/ HP-Logo
Size : Document Number : HPMH-40GAB6300-D	Rev : D
Date : Tuesday, January 11, 2011	Sheet : 30 of 51

Card Reader



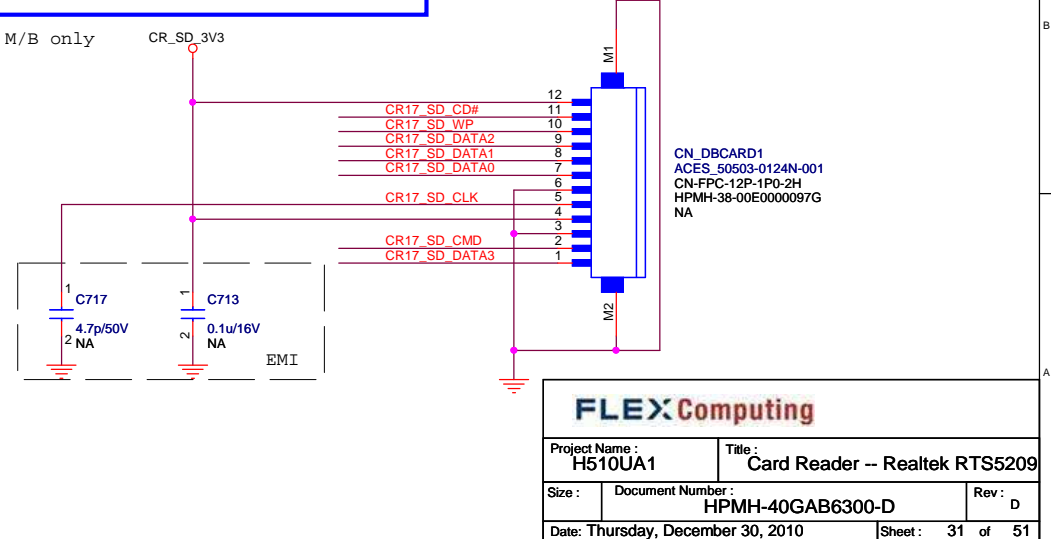
Card Reader CONN

For 15" M/B only

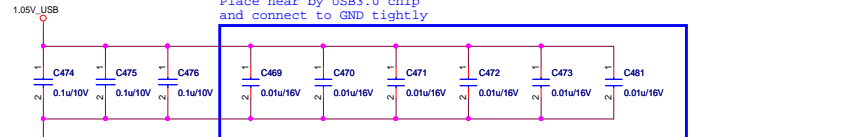
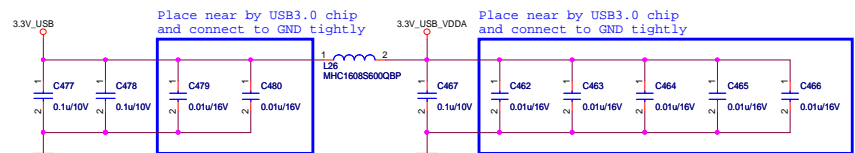
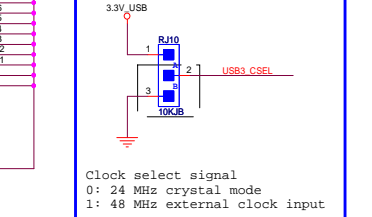
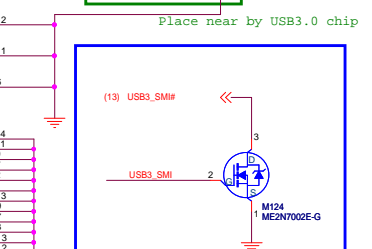
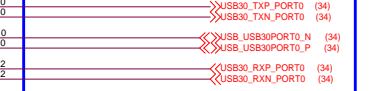
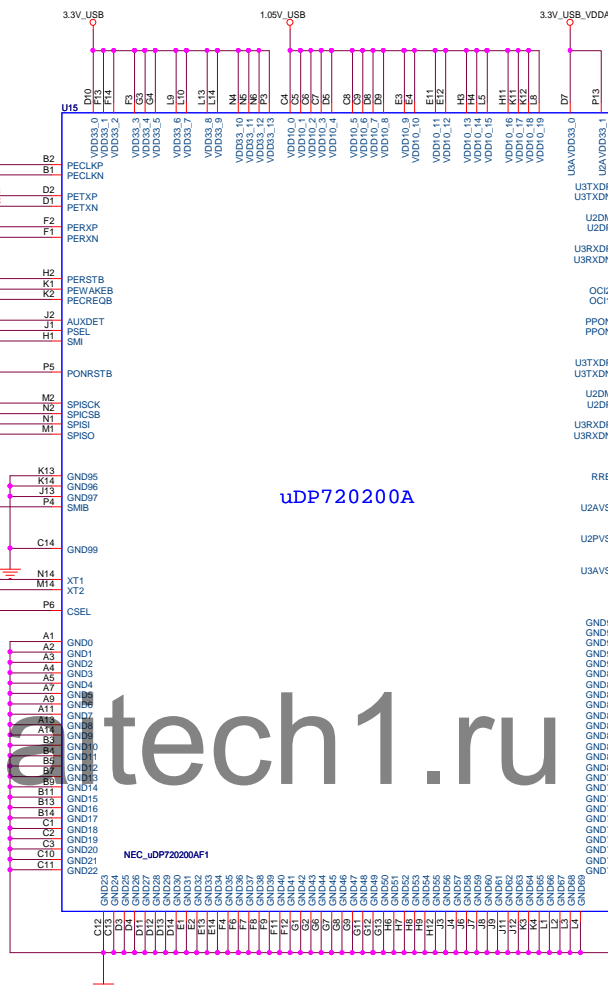
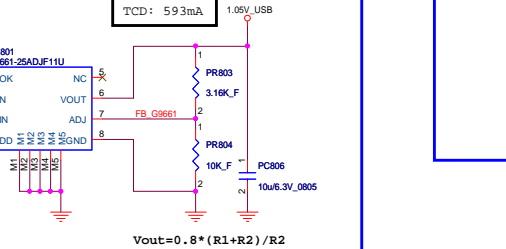
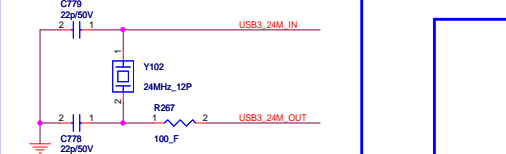
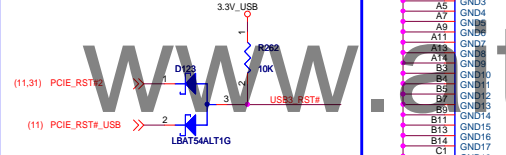
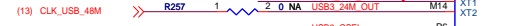
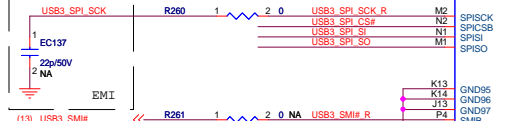
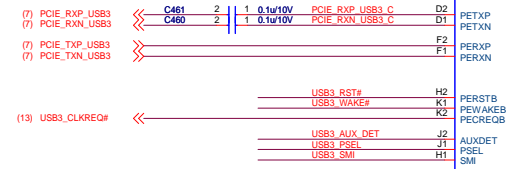
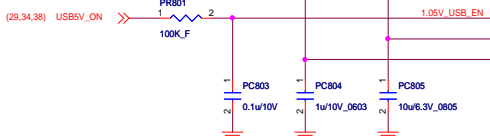
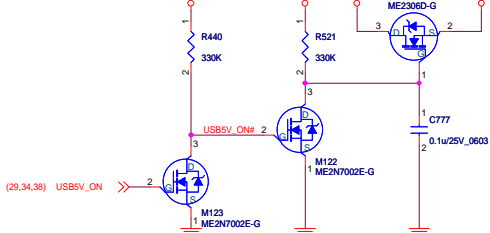
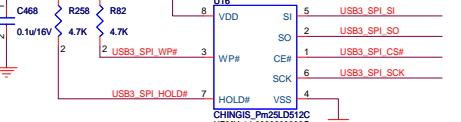
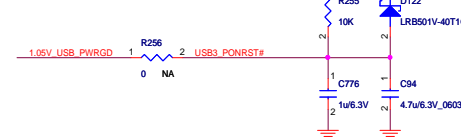
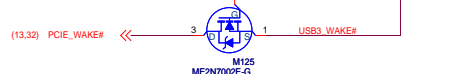


Card Reader BTB CONN

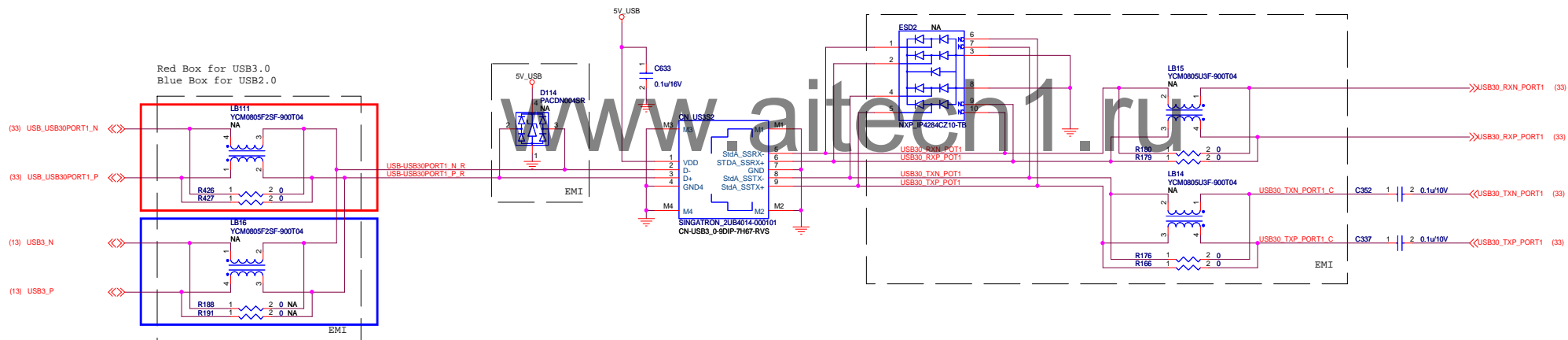
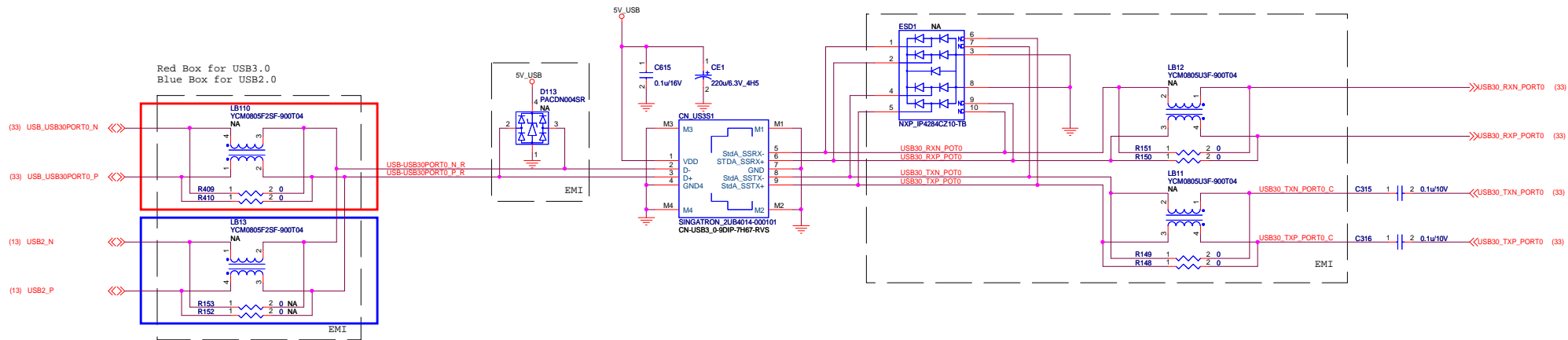
For 17" M/B only



Leave empty for IMR

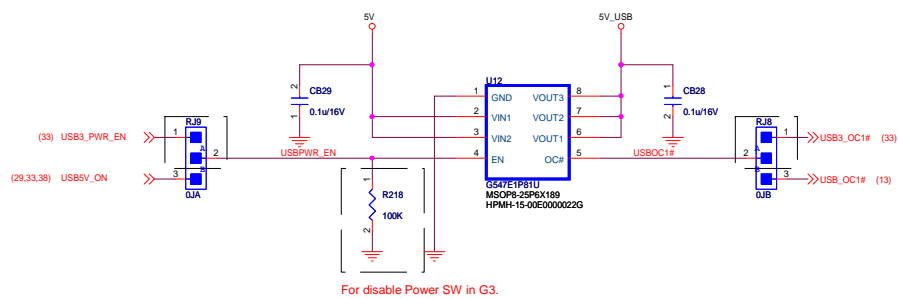


USB 3.0/ 2.0



USB PWR SW

USB 3.0: RJ8& RJ9 mounted A, B.
USB 2.0: RJ8& RJ9 mounted B, B.



USB3.0 Conn:

HPMH-38-0040000065G -- CONN USB 3.0 9P 2UB4014-000101 SINGATRON
HPMH-38-0040000067G -- CONN USB 3.0 9PIN TARA7-9Y5391 ACON
HPMH-38-0040000068G -- CONN USB 3.0 9P USBF-D9F1-ANR1-00 E-CONN
HPMH-38-0040000088G -- CONN USB3.0 1-1932354-1 9P H:7.4mm

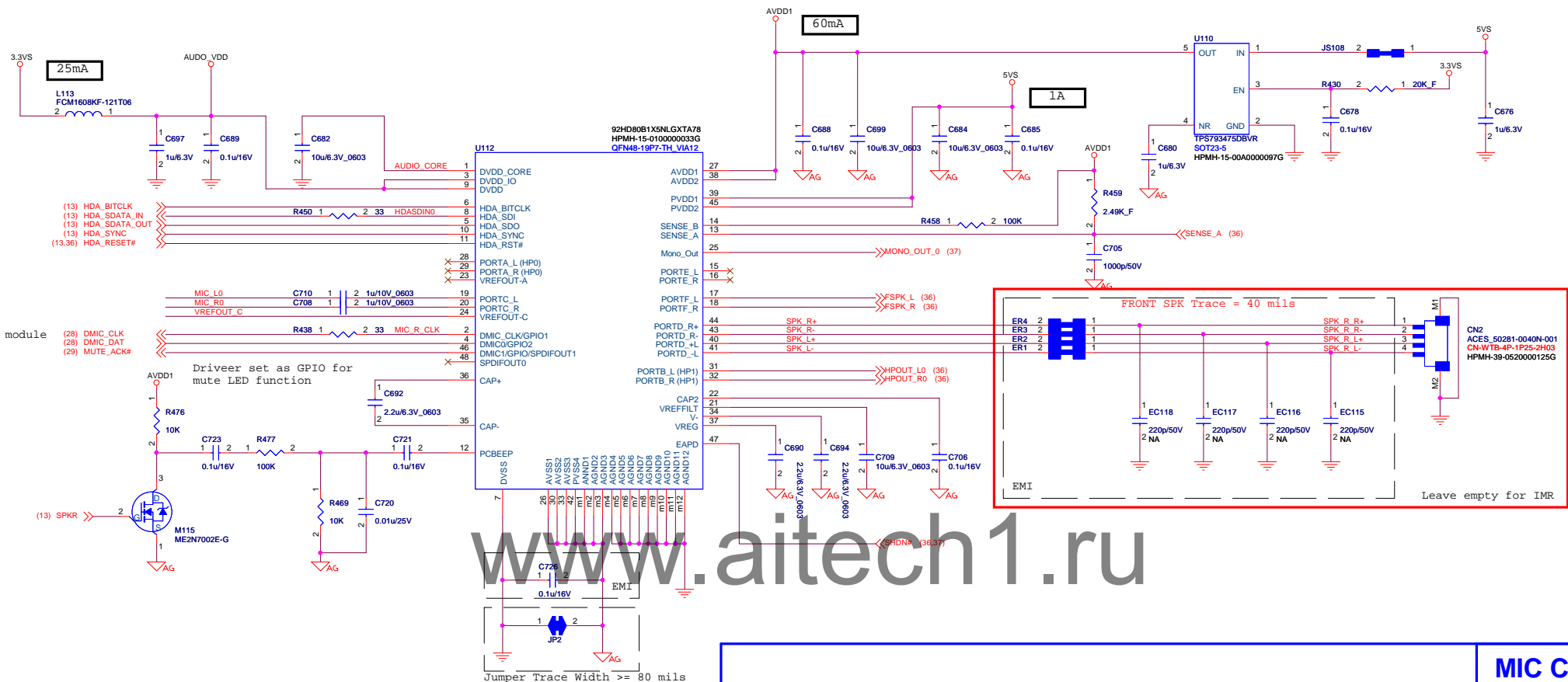
USB2.0 Conn:

HPMH-38-0040000066G -- CONN USB 2.0 4P 2UB4015-000111 SINGATRON
HPMH-38-0040000070G -- CONN USB 2.0 4PIN UARBS-4K5986 ACON
HPMH-38-0040000071G -- CONN USB 2.0 4P USBF-D4F1-ANR1-CA E-CONN

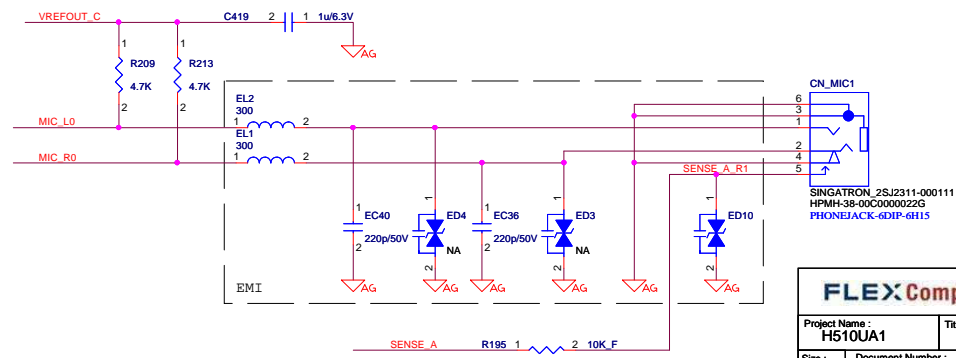
FLEX Computing

Project Name: H510UA1		Title: USB3.0 PWR/ USB I/F	
Size:	Document Number:	HPMH-40GAB6300-D	
Date: Thursday, December 30, 2010	Sheet:	34	of 51

Audio CODEC



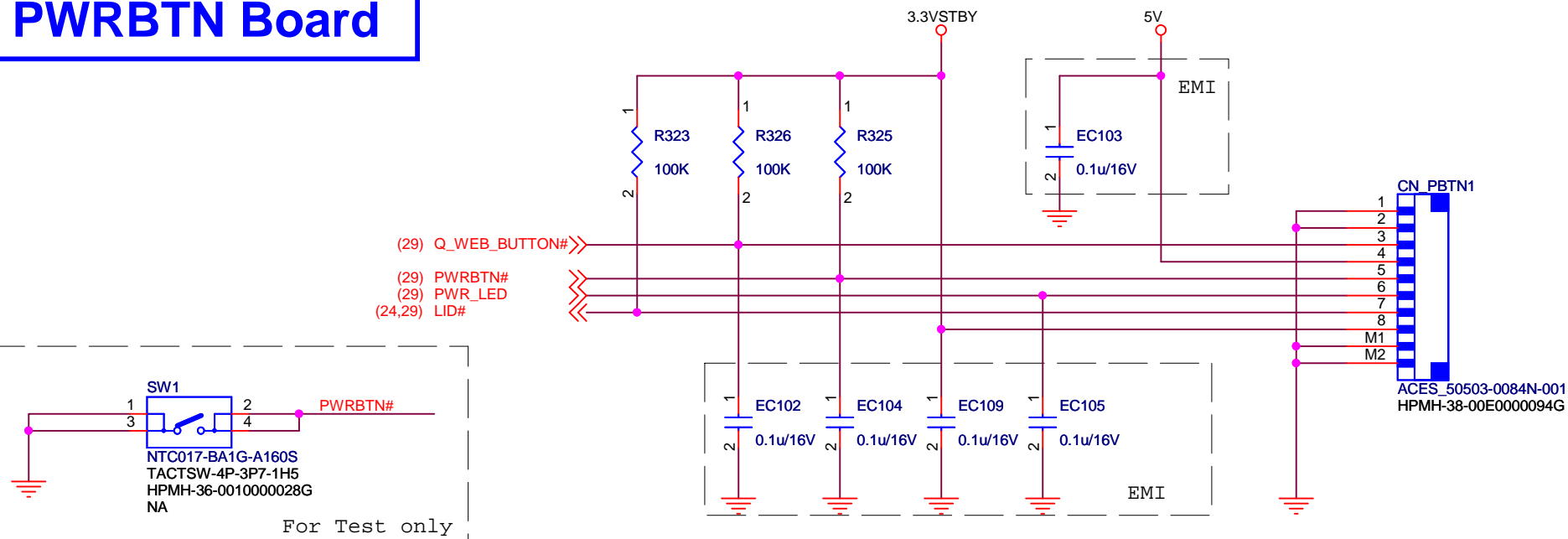
MIC CONN



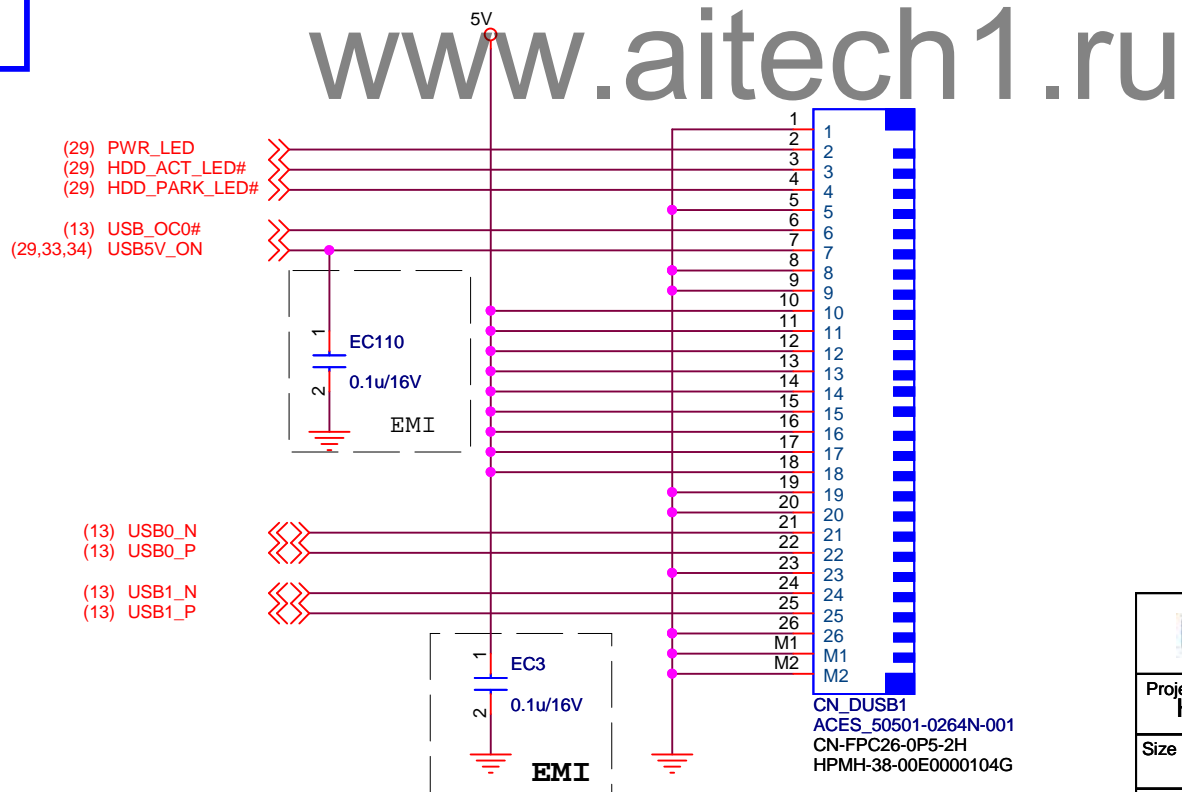
FLEX Computing

Project Name : H510UA1	Title : Audio -- IDT92HD80TA
Size : Document Number : HPMH-40GAB6300-D	Rev : D
Date : Thursday, December 30, 2010	Sheet : 35 of 51

PWRBTN Board



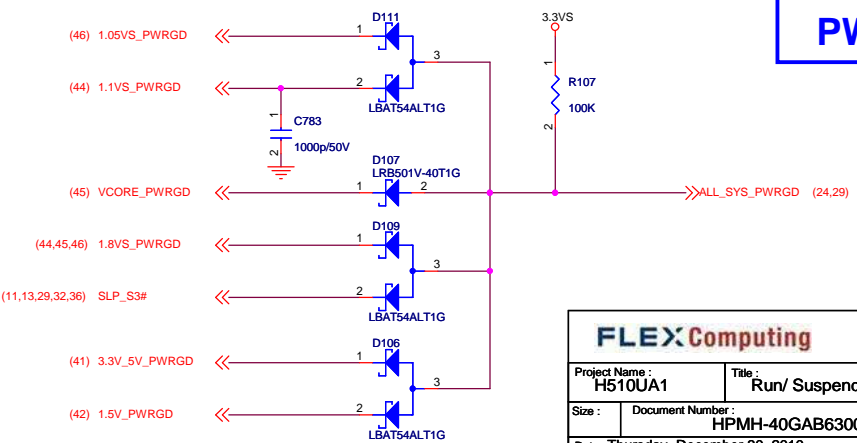
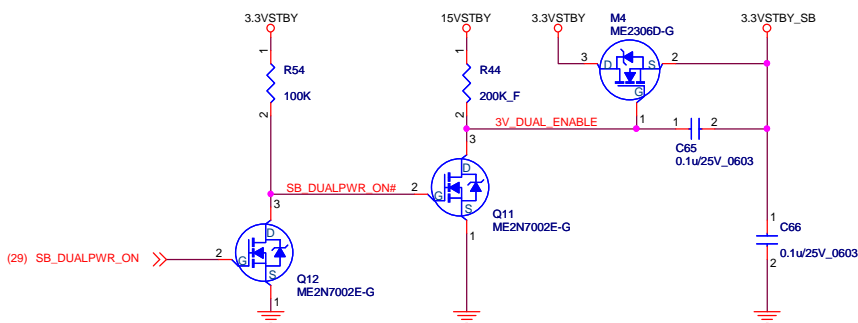
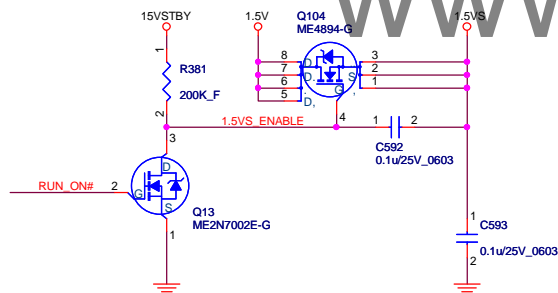
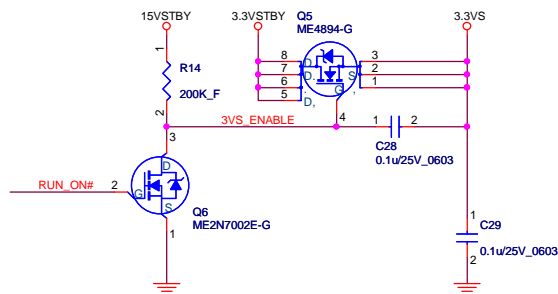
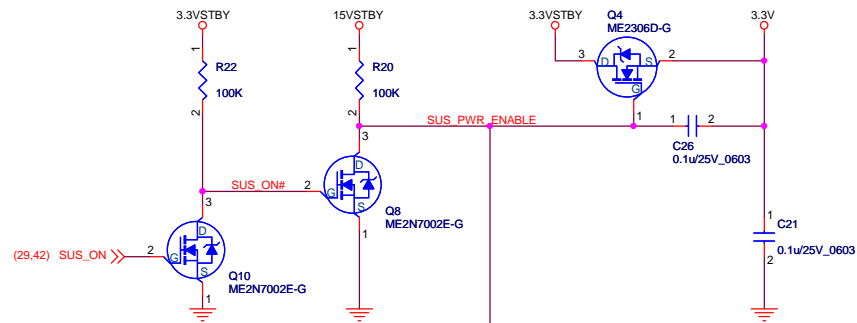
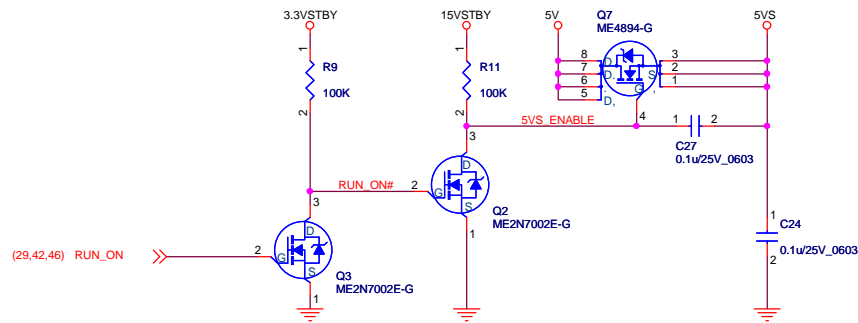
USB Board



FLEXComputing

Project Name : H510UA1		Title : Daughter Board Connector	
Size :	Document Number : HPMH-40GAB6300-D		Rev : D
Date: Thursday, December 30, 2010		Sheet :	38 of 51

RUN/ SUS PWR

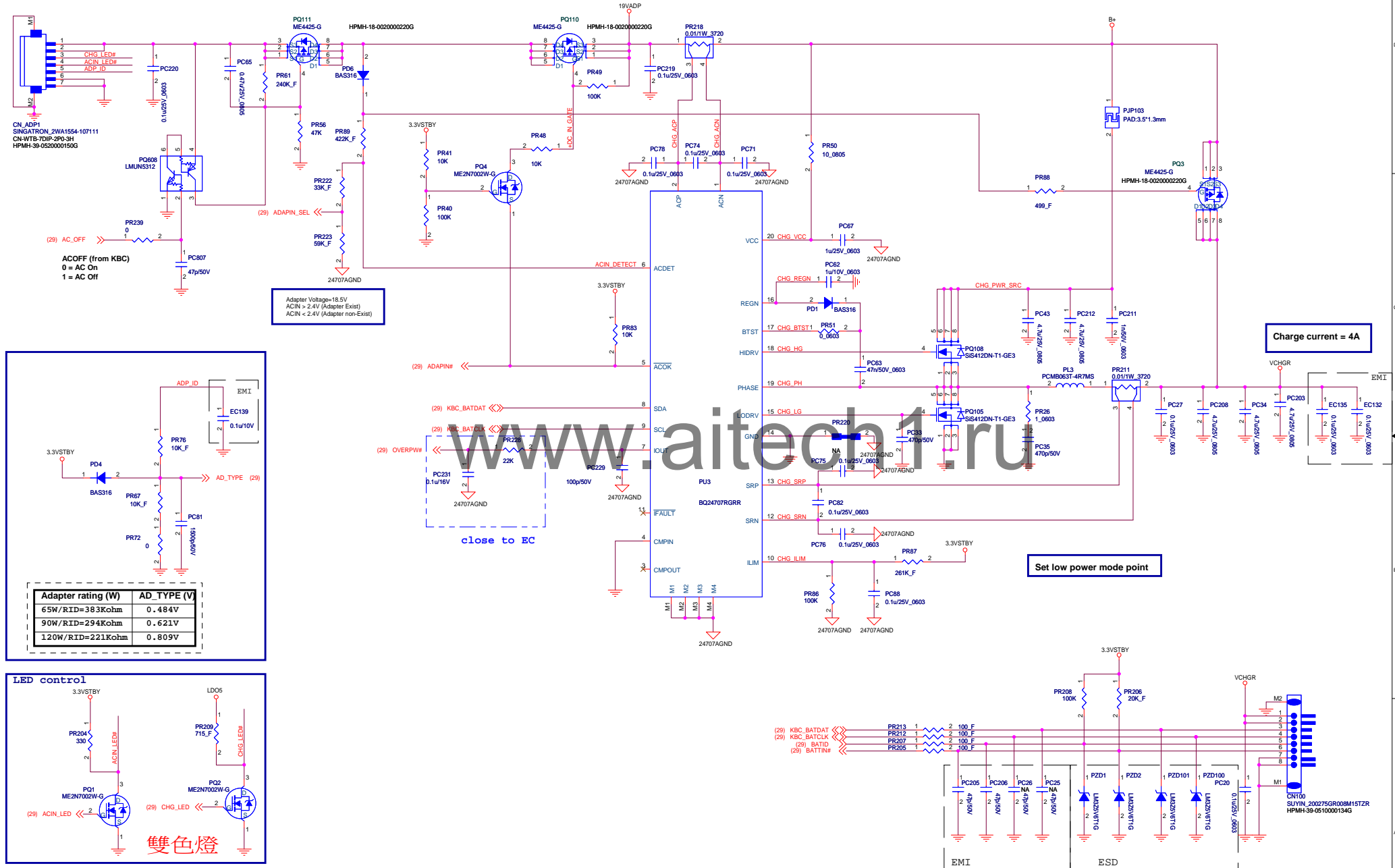
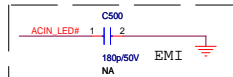


PWRGD

FLEXComputing

Project Name : H510UA1		Title : Run/ Suspend PWR switch	
Size :	Document Number :	HPMH-40GAB6300-D	
Date : Thursday, December 30, 2010	Sheet :	39	of 51

Charger

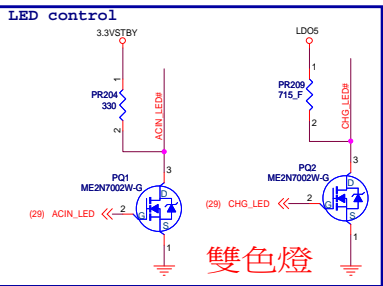


Adapter Voltage=18.5V
ACIN > 2.4V (Adapter Exist)
ACIN < 2.4V (Adapter non-Exist)

Charge current = 4A

Set low power mode point

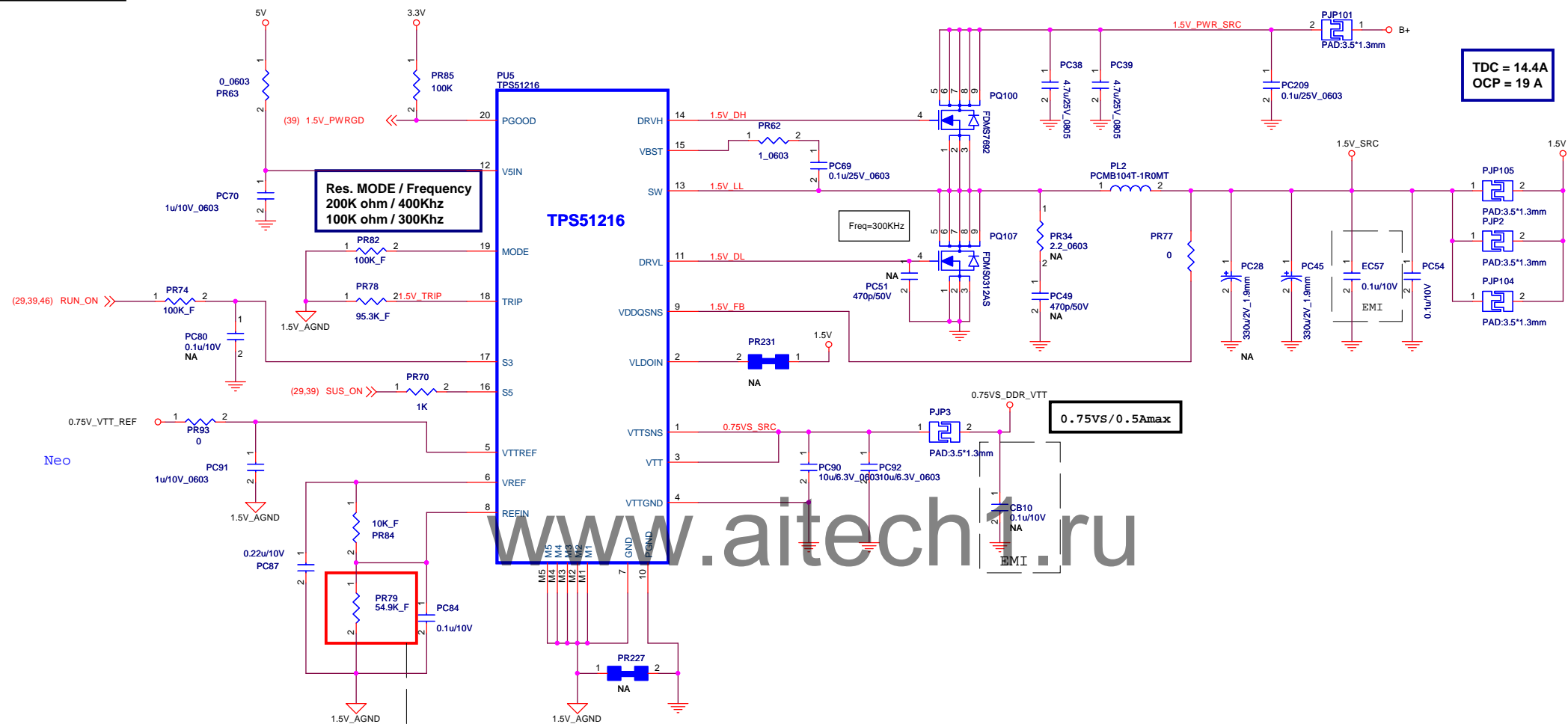
Adapter rating (W)	AD_TYPE (V)
65W/RID=383Kohm	0.484V
90W/RID=294Kohm	0.621V
120W/RID=221Kohm	0.809V



雙色燈

AirLine Combo	AC available	Charge
2.032V > ADAPIN_SEL > 1.542V	V	X
ADAPIN_SEL > 2.032V	V	V
1.542V > ADAPIN_SEL	X	X

1.5V



	UMA	Discret
PR79	49.9K ohm 1% HPMH-30-149921-990G	54.9K ohm 1% HPMH-30-154921-990G

Table 1. S3 and S5 Control Table

STATE	S3	S5	VTTREF	VTT
S0	H	H	1	1
S3	L	H	1	0 (high-Z)
S4/S5	L	L	0 (discharge)	0 (discharge)

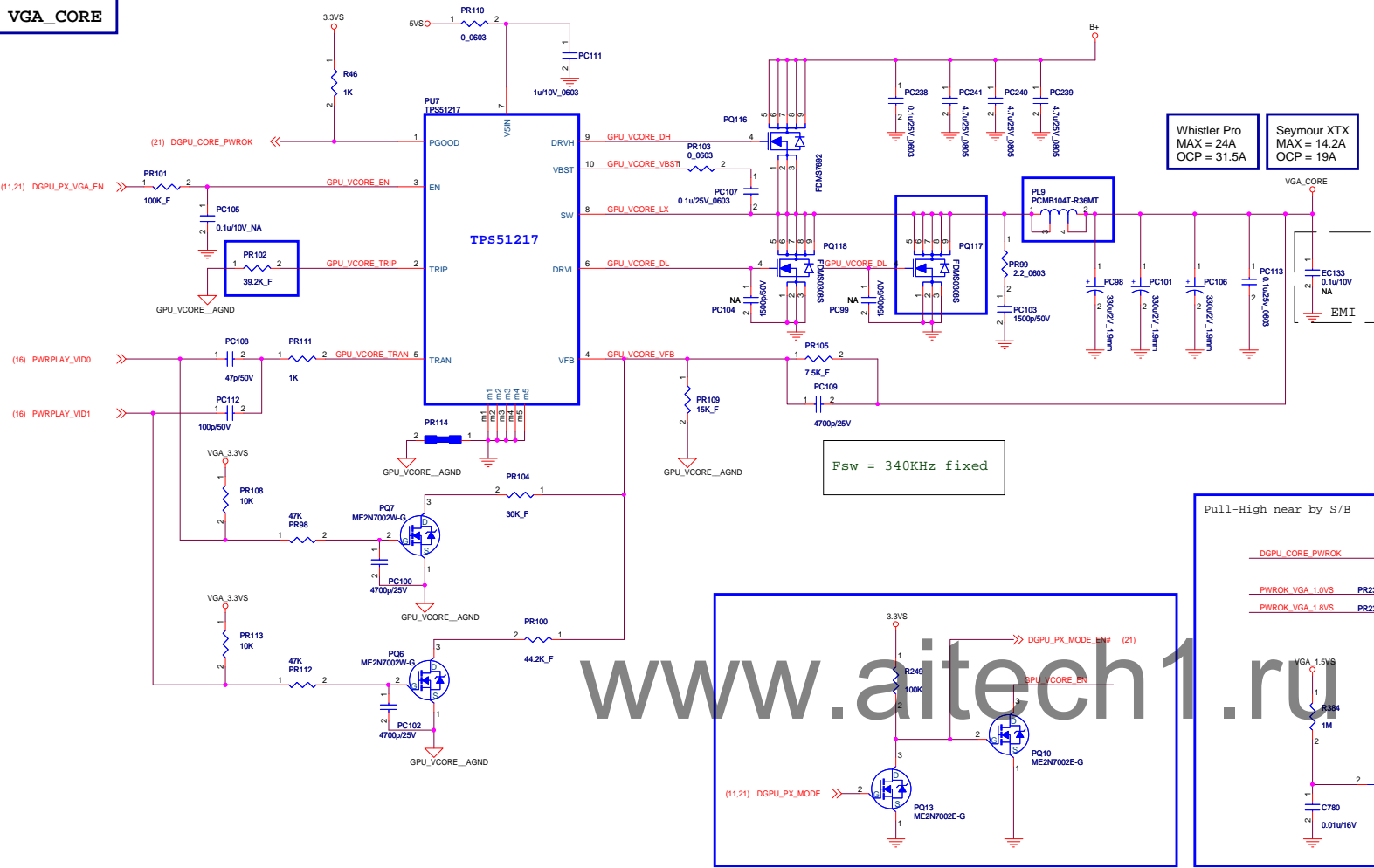
FLEXComputing

Project Name : H510UA1 Title : PWR -- DDR PWR (TPS51216)

Size : Document Number : HPMH-40GAB6300-D Rev : D

Date : Thursday, December 30, 2010 Sheet : 42 of 51

VGA_CORE



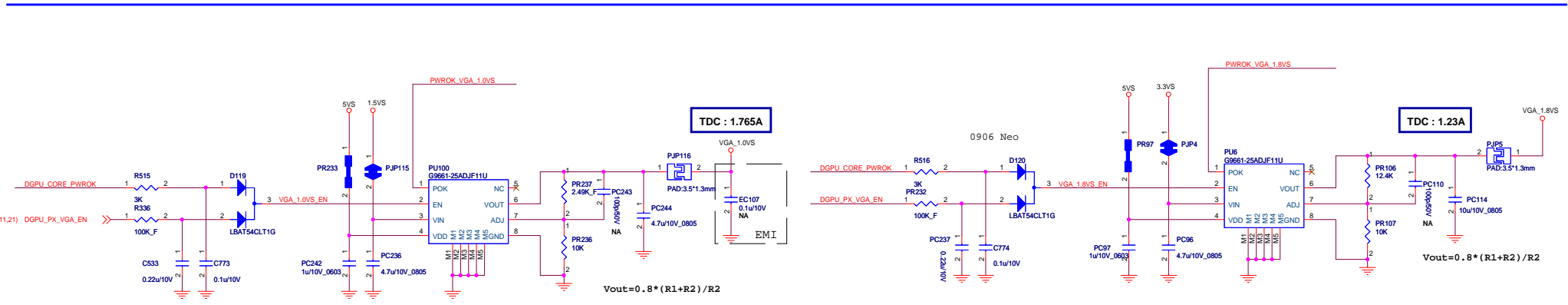
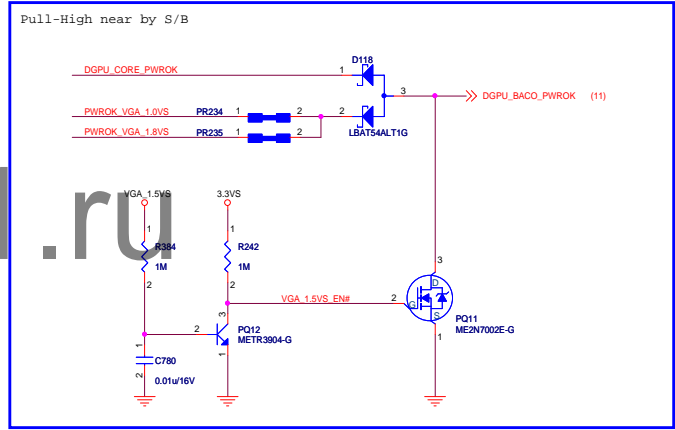
VID1	VID0	VGA_CORE (V)
0	-	0.9
1	-	1.0

VID1	VID0	VGA_CORE (V)
0	0	0.9
0	1	1.05
1	0	1.0
1	1	1.15

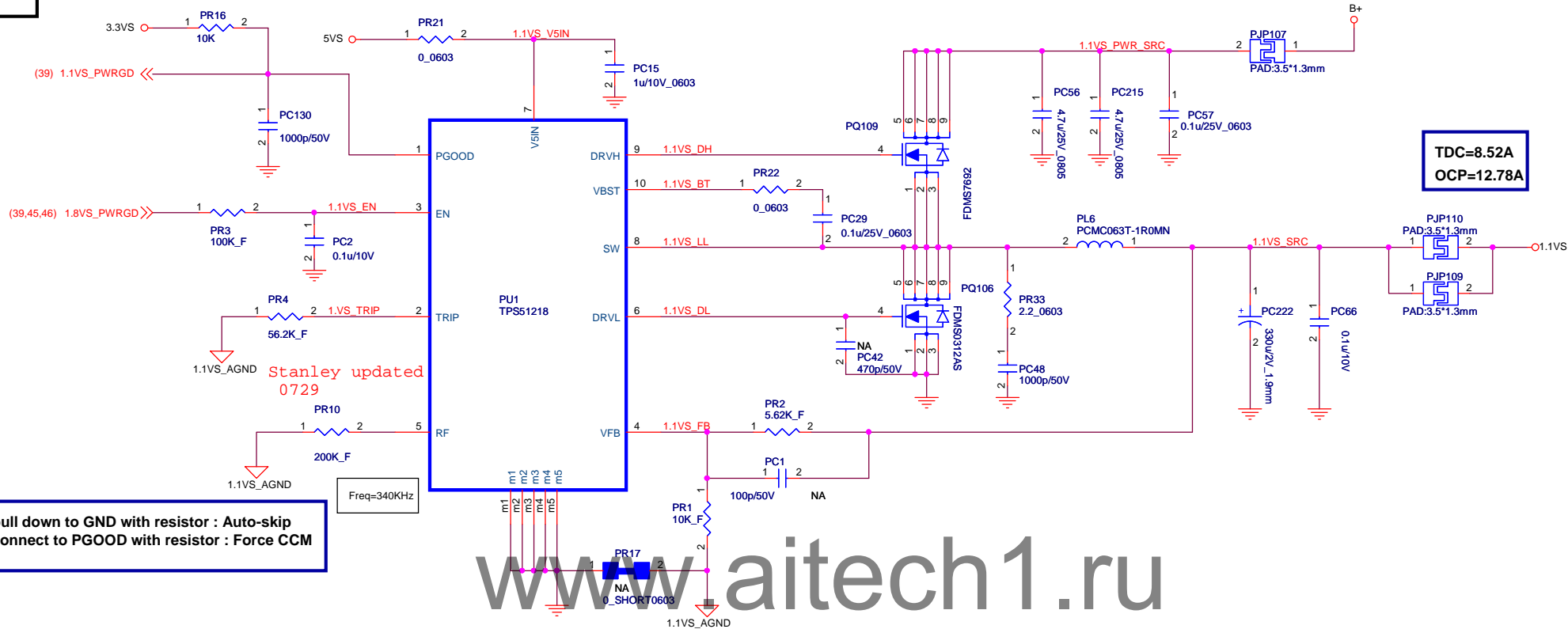
Whistler Pro
MAX = 24A
OCP = 31.5A

Seymour GTX
MAX = 14.2A
OCP = 19A

	Whistler	Seymour
PR102	39.2K ohm 1% HPMH-30-139221-990G	49.9K ohm 1% HPMH-30-149921-990G
PL9	0.36uH HPMH-32-4000000254G	1.0uH HPMH-32-4000000245G
PR104	NA	Mounted
PR98	NA	Mounted
PR108	NA	Mounted
PQ7	NA	Mounted
PC100	NA	Mounted
PQ117	Mounted	NA
PC241	Mounted	NA



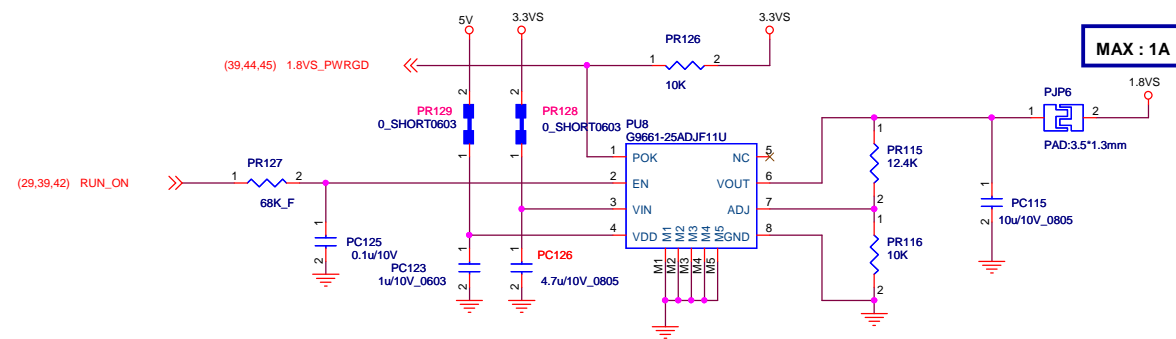
1.1VS



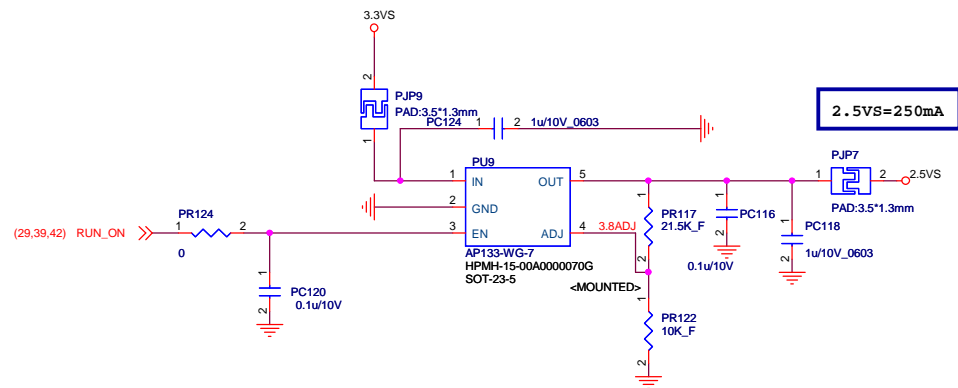
www.aitech1.ru

FLEX Computing		
Project Name :	H510UA1	
Title :	PWR -- 1.1VS (TPS51218)	
Size :	Document Number :	Rev : D
HPMH-40GAB6300-D		
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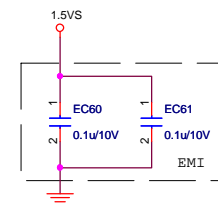
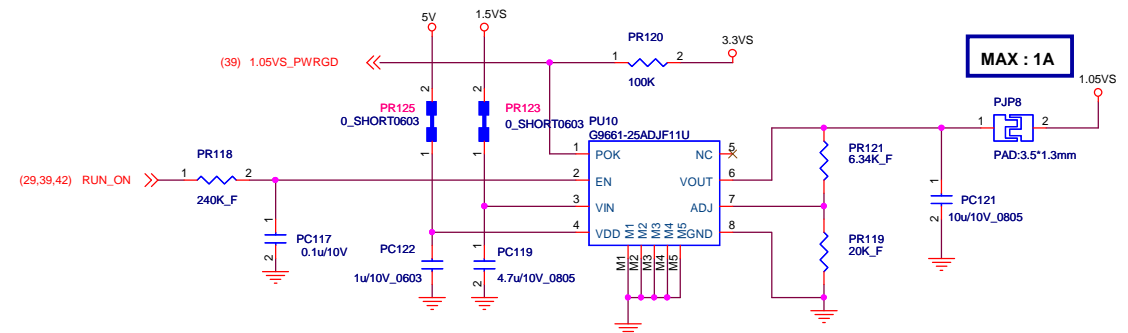
1.8VS



2.5VS



1.05VS



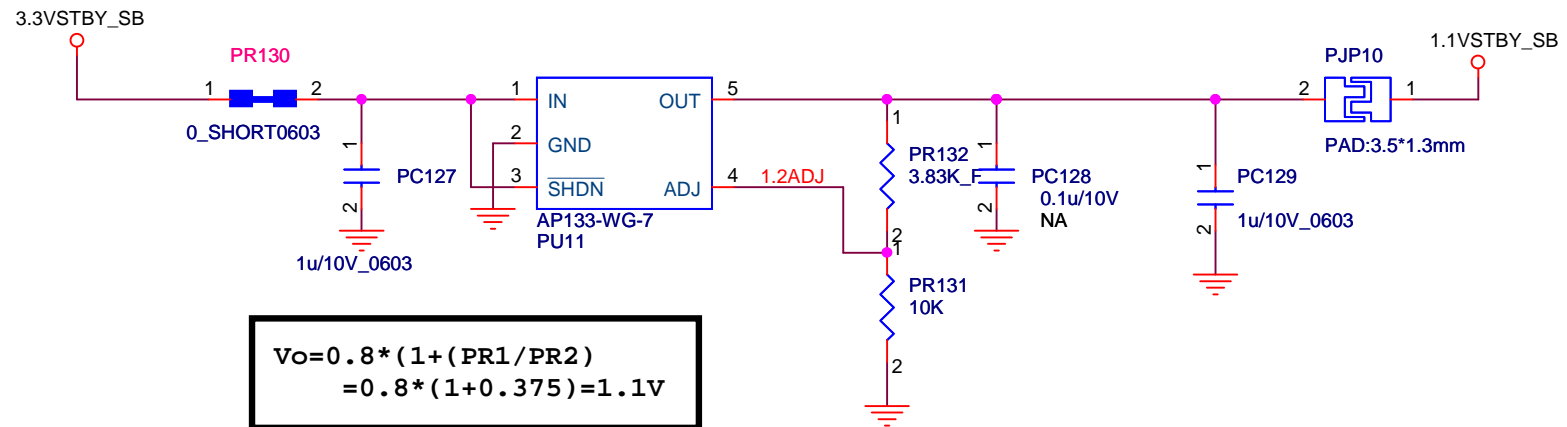
www.aitech1.ru

AP133:
 Low dropout: 350mV at
 300mA
 EN logic low: <0.4V
 EN logic high: >1.4V
 Thermal shutdown: 145°C

FLEX Computing

Project Name : H510UA1		Title : PWR -- 1.8VS/ 1.05VS/ 2.5VS	
Size :	Document Number : HPMH-40GAB6300-D	Rev : D	
Date: Thursday, December 30, 2010		Sheet : 46 of 51	

1.1VSTBY



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FLEXComputing

Project Name :
H510UA1

Title :
PWR -- 1.1VSTBY_SB (AP133)

Size :

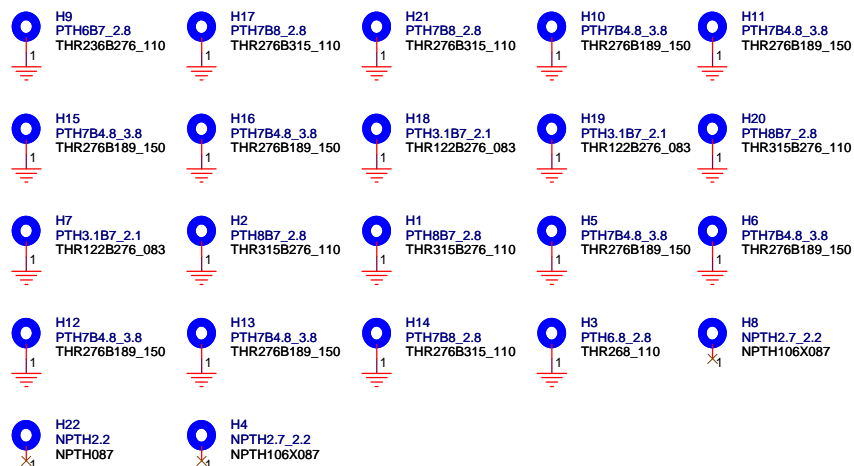
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HPMH-40GAB6300-D

Rev :
D

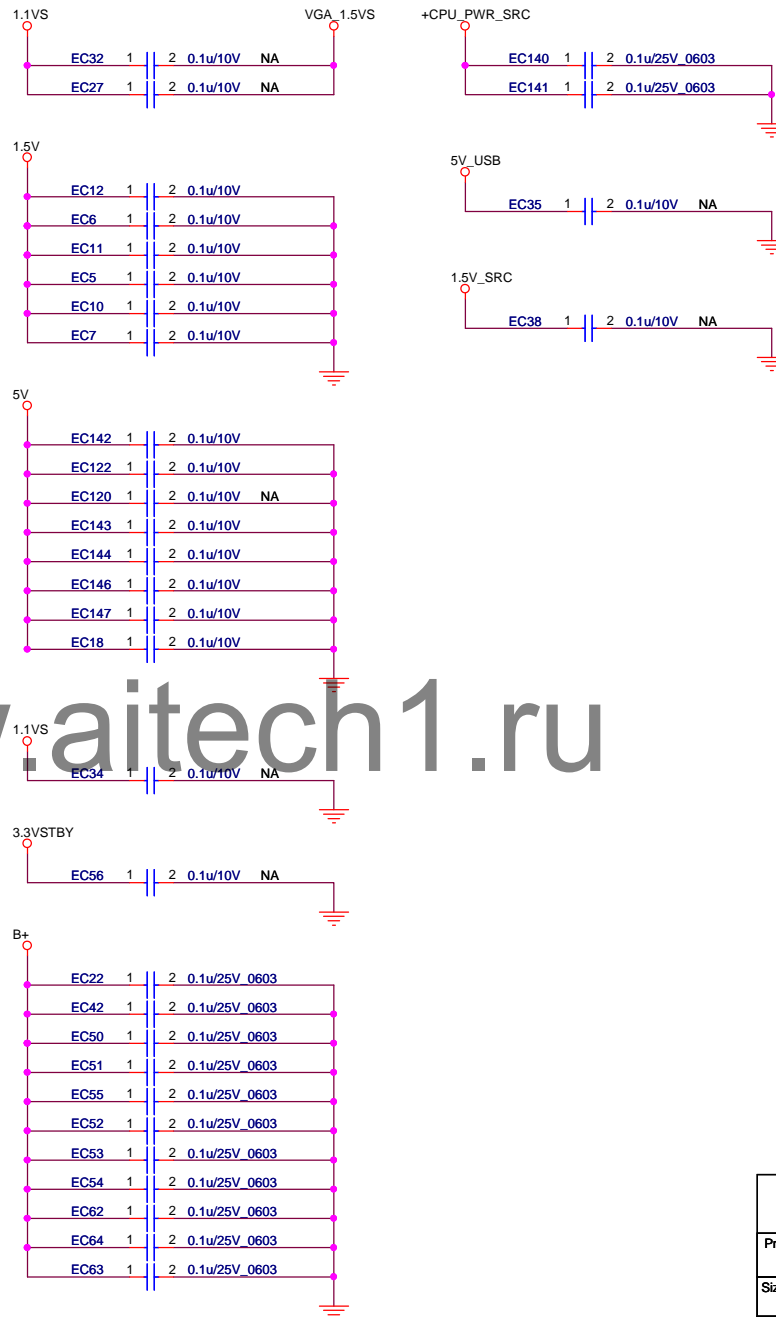
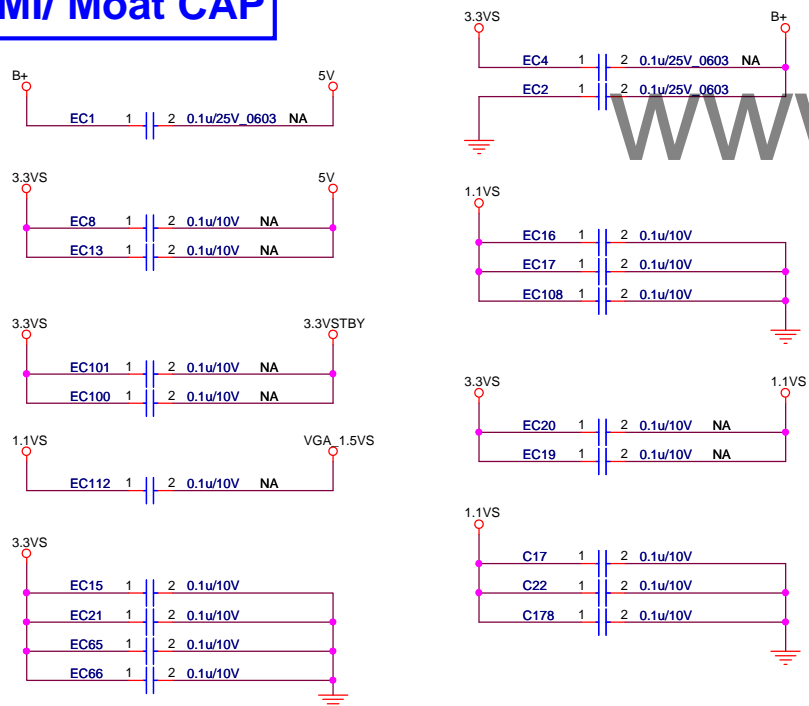
Date: Thursday, December 30, 2010

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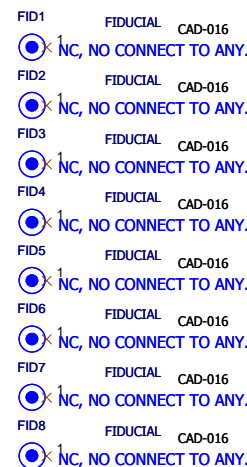
Screw Hole



EMI/ Moat CAP



FID



FLEXComputing

Project Name : H510UA1		Title : Screw Hole/ EMI/ Unused	
Size :	Document Number :	HPMH-40GAB6300-D	
Date : Thursday, December 30, 2010	Sheet : 48 of 51	Rev : D	

Version change list (P.I.R. List)

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Item	Fixed Issue	Reason for Change	Rev	PG#	Modify List	B Ver#	Phase
1	Rev. A Schematic released	Rev. A Schematic released	A			A0	DB
2	Modify F1 to smaller package	Modify F1 to smaller package	B	26	Modify F1 package to "FUSE-3L4X1W8X1H".	B0	SI
3	Add resistor for CPU test point resistor.	Add resistor for CPU test point resistor.	B	2	Add R514 for 80.6 ohm.	B0	SI
4	Add thermal sensor for NB thermal diode	Prevent N/B thermal break down	B	8, 30	Add RJ105, RJ106 and C772 to seperate DGPU& NB thermal signal.	B0	SI
5	Add DGPU CRT DDC source	Add DGPU CRT DDC channel for DDC6	B	16	Add U104 DDC channel test PAD (P27, P26) of pin AJ30, AJ31 (DDC6)	B0	SI
6	Modify CRT damping components.	Improve re-work performance	B	26	Modify JS102, JS103, JS104, JS7, JS9, JS10, JS11 to R233, R234, R235, R236, R237, R238, R239	B0	SI
7	Shift LAN transformer pin signal	Correct LAN transformer pin-out	B	32	Shift U107 pin-out to meet transformer spec	B0	SI
8	Update LAN 25M net-name	Correct LAN 25M for reserved signal.	B	32	Modify LAN 25M clock from S/B and named "LAN_25M_IN_SB"	B0	SI
9	Modify USB3.0 clock request signal	Modify USB3.0 clock request signal	B	33	Delete D7 for USB 3.0 clock request work properly	B0	SI
10	Reduce CPU/ DGPU screw hole size	To meet BGA& Screw hole keeping 3mm.	B	48	Reduce H5, H6, H12, H3 (CPU), H10, H11, H15, H16 (DGPU) to 7B4.8_3.8 mm	B0	SI
11	Prevent leakage current& fine-tune PWR seq	Prevent leakage current& fine-tune PWR seq	B	34, 39, 44, 45, 46	1. Modify R423 pin 1 to 3.3VSTBY 2. Leave C25 as empty for 1.1V seq 3. Modify R44 to 200K ohm 1% for 3.3VSTBY_SB seq. 4. Add R240, R241 for waveform improve 5. Add R519, R520 to Audio SM bus reserved. 6. Modify PR118 to 240Kohm 1% for 1.05VS seq. 7. Modify PR126 to 10Kohm for 1.8VS seq. 8. Modify PR9 to 150Kohm 1% for VCORE seq. 9. Modify PR3 to 100Kohm 1% for 1.1VS seq. 10. Del R82	B0	SI
12	Remove un-used circuit	Remove function by HP requirement	B		Remove Blue tooth& Keyboard bakclight circuit	B0	SI
13	Add KBC External Wake up event	Add KBC External Wake up event	B	13, 29	Add D6 and make link "SIO_EXT_WAKE#" from U5 pin 117 to U111 pin H3.	B0	SI
14	Modify components by ME/ height limitation	Modify components by ME/ height limitation	B	11, 28, 35, 37	1. Modify CN_RTC1 to ACES - "50273-0020N", CN2 to ACES - "50273-0020N", CN4 to ACES - "50281-00201", CN_LVDS1 to ACES "50398-04001" 2. Add M119, M120 for TP EN LED& TP Sidelight LED sinker.	B0	SI
15	Modify DGPU power sequence& BACO circuit	To meet DGPU power sequence& BACO required.	B	11, 21, 43	1. Modify U111 pin AH6 as "DGPU_PX_VGA_EN" 2. Modify PR238 to 620K ohm 1% 3. Add R243, Q14, PQ121, PC246 for VGA_3.3VS gating circuit. 4. Modify VGA_1.5VS enable signal from DGPU_PX_EN to DGPU_PX_VGA_EN. 5. Delete D6 and connect DGPU_PX_MODE to BACO circuit as enable 6. Add D118, D119, D120, PR240, R249, R515, R516, C773, C774, PC130, PQ10, PQ11, PQ12, PQ13 for VGA PWR Seq. 7. Add JP3, JP4 for BACO mode reserved. 8. Add D121, R250, PQ9, PQ11, PQ12, R242 for DGPU_BACO PWROK seq. 9. Modify DGPU_PERST# from DGPU_PX_GPIO0 and PCIE_RST# combined. Or shorted by RJ100B from DGPU_GPIO0. 10. Modify entire 3.3VS of DGPU to VGA_3.3VS. 11. Update PCIE_RST#0 reset source.	B0	SI
16	DFB update	DFB update improvement (Factory)	B	26	Modify D101 to 1N5819HW-7-F.	B0	SI
17	X'tal accuracy modify	X'tal accuracy modify	B	11	1. Modify C704, C719 to 27pF for 32.768M Hz	B0	SI
18	Seperate PCI_WAKE# from different power source	Seperate PCI_WAKE# from different power source	B	11	Add D123, R200 and pull-high to 3.3V_LAN	B0	SI
19	Add transistor for LED sinker	Add transistor for LED sinker	B	28	Add M119& M120 for LED power sinker.	B0	SI
20	Update thermal circuit	Update thermal circuit	B	30	1. Add RJ105, RJ106, R247 for DGPU& NB thermal diode switch circuit. 2. Delete R23, R25, R30, R37, R38, R42, R43, C94, D1, D2, M5, M6, Q9.	B0	SI
21	Update USB3.0 solution to NEC	Update USB3.0 solution to NEC by HP required.	B	33	Modify USB3.0 soultion to NEC uDP720200	B0	SI
22	Audio circuit modify (Kevin.Yeh)	Audio circuit modify	B	36, 37	1. Modify R484, R485, R487& R490 to 1.96K ohm 1% 2. Add R517 (10K ohm) and pull-high to "HP_AMP". 3. Add R244, R245, R246, R248, C727, C775 for B+ break down issue.	B0	SI
23	Power circuit modify (Eva.Chao)	Power circuit modify	B	40, 42, 44, 45	1. Modify PR50, PC67 from 1206 to 0805& 0603 package. 2. Modify PC45, PC207 to 220uF/ 6.3V. 3. Leave PC22, PC45& PC61 empty. 4. Add PQ608, PR239 for AC-off funtion. 5. Modify PL8 to PCMC063T-3R3MN 6. Leave PR64 empty and PR53 mouted for charge-pump states. 7. Modify PR102 to 30.1K ohm 1%. 8. Modify PR16 to 10K ohm and Add PC130 for 1.1VS_PWRGD signal quality 9. Modify PC222 for double pulse issue.	B0	SI

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Project Name:
H510UA1Title:
History - 1

Size:

Document Number:

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Rev: D

Date: Thursday, December 30, 2010

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Version change list (P.I.R. List)

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Item	Fixed Issue	Reason for Change	Rev	PG#	Modify List	B Ver#	Phase
24	Prevent GPU ACAVIN leakage current	Prevent GPU ACAVIN leakage current	C	16	Add R352& D7 to prevent GPU ACAVIN leakage current.	C0	PV
25	Update USB3.0 circuit	Update USB3.0 circuit	C	33, 34	1. Add R263, R264& M125 for USB3.0 Wake up event. 2. Add R262& D123 for USB3.0 reset timing issue. 3. Modify L26 to package 0603 for parts lead time issue. 4. Correct Analog& Digital power source 5. Add R261 for SMI BOM option 6. Delete M17 and update power switch circuit. 7. Update U16 footprint	C0	PV
26	KBC SLP_S5# signal setting	KBC SLP_S5# signal setting	C	29	Add R165 to setting SLP_S5# GND level	C0	PV
27	Logo LED broken issue	Logo LED module didn't have current limit resistor	C	24	Add R335 for Logo LED current limit	C0	PV
28	Zero power ODD function removal	Zero power ODD function removal	C	27	Leave C652, M108, M109, Q105, Q106, R419, R424& R452 empty for Zero Power ODD function removal.	C0	PV
29	EEPROM WP#	Add EEPROM WP# from EC	C	29	Add EC pin 81 as EEPROM WP# signal for EEPROM Write Protection.	C0	PV
30	NEC USB3.0 device disappear issue	Fine-tune NEC USB3.0 power up seq	C	33	1. Add C94 for NEC uPD700200A global reset timing fine-tune 2. Add R259 as empty for CLKREQ external pull-high	C0	PV
31	GPU thermal trip normal operation status	Set GPU thermal trip normal operation status	C	2, 29	1. Add R423 for GPU thermal trip normal operation status 2. Add Q108 for CPU processor hot	C0	PV
32	Hall sensor sense issue	Hall sensor can't work fine	C	28, 38	Modify SW100, C510 to D/B and modify CN_PBTN1 to 8 pin to meet M.E. modify	C0	PV
33	PX mode GPU thermal sensor fail	EC can't check GPU thermal status	C	2, 21, 29 30	1. Remove Q101, R303 remove CPU thermal alert. 2. Add R268 pull-high at alert of thermal sensor. 3. Connect DGPU_PX_VGA_EN to EC for PX mode indicates. 4.Add Q109, R181 for thermal sensor leakage issue	C0	PV
34	Stage ID indicate	Indicate SI/ PV stage for SW	C	12	Add R461 for Stage ID (Default internal PU: H-SI, L-PV)	C0	PV
35	Power seq fine-tune	Power seq fine-tune	C	33, 43	1. Modify PR801 to 100K_F for USB3.0 chip power seq 2. Modify R336, PR232 to 100K_F for VGA power seq	C0	PV
36	Power circuit modify (Staley Chiu)	Power circuit modify	C	41, 43, 44, 45, 46	1. PL8 change to 4R7 2. Leave PR66 as empty 3. PR81/ PR81 change to 22K/ 34.8K for USB port load issue 4. PR79 change to 54.9k for VRAM load issue 5. PR104 change to 30K for AMD VID Updated 6. PR100 change to 44.2k for AMD VID Updated 7. Modify MAX/OCF current text 8. Update VID table 9. PC114 change to 10u/10v0805 for Phase/Gain 10. PC222 change to 330u/2v for double purse 11. PC60 change to Panasonic source (use the same source with others) 12. Add PC247, PC248/ 68uF/25V for closing acoustic noise 13. PC115 change to 10u/10v0805 for Phase/Gain 14. PC121 change to 10u/10v0805 for Phase/Gain 15. Delete PJP114	C0	PV
37	RFI solution (Hank Tsai)	RFI solution	C	11	Modify C442, C448 to 10pF as mounted.	C0	PV
38	EMI solution (PV - Benson Ni)	Update EMI solution	C	30, 37, 38, 39, 40, 41, 42, 45, 46, 48	1. Modify CB15,CB16 as mounted. 2. Modify EC37,EC39,EC41,EC44 as mounted. 3. Modify EC102,EC104,EC105 as mounted. 4. Add EC110/ 0.1uF bypass caps. Between USB conn pin7 (USB5V_ON) and GND. 5. Add EC139/ 0.1uF bypass caps.Between CN_ADPI pin 5 and GND. Modify C500 as mounted. 6. Add EC138/ 0.1uF bypass caps. between 5VSTBY_SRC and GND. 7. Add EC57/ 0.1uF bypass caps. between 1.5V_SRC and GND. 8. Add EC45/ 0.1uF bypass caps. between CPU_VDDNB and GND. Add EC59/ 0.1uF bypass caps. between +CPU_PWR_SRC and GND. 9. Add EC60, EC61/ 0.1uF bypass caps. between 1.5VS and GND. 10. Modify EC5,EC6,EC7,EC10,EC11,EC12,EC108,EC122 as mounted. Add EC62, EC63, EC64/ 0.1uF bypass caps. between B+ and GND. Add EC65/ 0.1uF bypass caps. between 3.3VS and GND. Delete EC111,EC25,EC23,EC24,EC26,EC33,EC35,EC109,EC110,EC45,EC38.	C0	PV
39	ESD solution (PV - Stone Wang)	Update ESD solution	C	35, 36	1. EL1, EL2 from Bead 120ohm change to the Resistor 300ohm. 2. EC36, EC40 change to mounted. 3. Add a Varistor ED10 between CN_MIC1 pin5 and Net AGND. 4. ED3, ED4 change to 0603 Varistors. 5. Add a Varistor ED11 between CN_PHONE1 pin5 and Net AGND. 6. ED6, ED8, ED104, ED106 change to 0603 Varistors. 7. ED5, ED7, ED9, ED108 change to 0603 Varistors and keep them as empty	C0	PV

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Version change list (P.I.R. List)

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Item	Fixed Issue	Reason for Change	Rev	PG#	Modify List	B Ver#	Phase
40	RTC accuracy update (BOM)	RTC accuracy update	D	11	Modify C704& C719 to 22pF and 18pF.	D0	MV
41	Prevent adaptor level fail (Power)	Prevent adaptor level fail	D	40	Modify PR89 to 422Kohm 1%	D0	MV
42	Prevent leakage current from CRT	Prevent leakage current from CRT	D	26	Add R23 as 10Kohm to prevent leakage cuurent from CRT	D0	MV
43	Fine-tune LED brightness (BOM)	Fine-tune LED brightness by HP ID	D	29	1. Modify R399 to 590ohm 1% for RF on LED 2. Modify R401 to 240ohm 1% for RF off LED 3. Modify R404 to 1.27Kohm 1% for CAP lock LED 4. Modify R405 to 240ohm 1% for MUTE LED 5. Modify PR209 to 715ohm 1% for Charger LED	D0	MV
44	S5 wake-up event leakage issue (BOM)	Prevent leakage current from pull-high resistor	D	29	Leave R356, R361 as empty to prevent it.	D0	MV
45	DFX report improvement	Meet Factory DFX checking	D	45	Modify PJP100 to Normal close footprint	D0	MV
46	EMI solution improvement	EMI solution improvement	D	48	1. Modify EC15 from between 3.3VS& 5V to 3.3VS& GND 2. Modify EC18 from between 3.3VS& 5V to 5V& GND 3. Modify EC2 from between 3.3VS& B+ to B+& GND 4. Add EC35, EC38, EC66, EC140, EC141, EC142, EC143, EC144, EC146, EC147, EC148	D0	MV

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